

MCP37211-200 MCP37D11-200

200 Msps, 12-Bit Low-Power ADC with 8-Channel MUX

Features

- · Sample Rates:
 - 200 Msps for single-channel mode
 - 200 Msps/number of channels used
- SNR with f_{IN} = 15 MHz and -1 dBFS:
 - 71.3 dBFS (typical) at 200 Msps
- SFDR with f_{IN} = 15 MHz and -1 dBFS:
- 90 dBc (typical) at 200 Msps
- Power Dissipation with LVDS Digital I/O:
 - 468 mW at 200 Msps
- Power Dissipation with CMOS Digital I/O:
 - 436 mW at 200 Msps, Output Clock = 100 MHz
- Power Dissipation Excluding Digital I/O:
 - 387 mW at 200 Msps
- · Power-Saving Modes:
 - 144 mW during Standby
- 28 mW during Shutdown
- · Supply Voltage:
 - Digital Section: 1.2V, 1.8V
 - Analog Section: 1.2V, 1.8V
- Selectable Full-Scale Input Range: up to 2.975 V_{P-P}
- Input Channel Bandwidth: 500 MHz
- Channel-to-Channel Crosstalk in Multi-Channel Mode (Input = 15 MHz, -1 dBFS): >95 dB
- Output Data Format:
- Parallel CMOS, DDR LVDS
- Optional Output Data Randomizer
- Serial Peripheral Interface (SPI)

- Digital Signal Post-Processing (DSPP) Options:
 Decimation filters for improved SNR
 - Fractional Delay Recovery (FDR) for timedelay corrections in multi-channel operations (dual-/octal-channel modes)
 - Noise-Shaping Requantizer (NSR)
 - Phase, Offset and Gain adjust of individual channels
 - Digital Down-Conversion (DDC) with I/Q or f_S/8 output (MCP37D11-200)
 - Continuous wave beamforming for octalchannel mode (MCP37D11-200)
 - Built-In ADC Linearity Calibration Algorithms:
 - Harmonic Distortion Correction (HDC)
 - DAC Noise Cancellation (DNC)
 - Dynamic Element Matching (DEM)
 - Flash Error Calibration
- AutoSync Mode to Synchronize Multiple Devices to the Same Clock
- · Package Options:
 - VTLA-124 (9 mm x 9 mm x 0.9 mm)
 - TFBGA-121 (8 mm x 8 mm x 1.08 mm)
- No External Reference Decoupling Capacitor Required for TFBGA Package
- Industrial Temperature Range: -40°C to +85°C

Typical Applications

- Communication Instruments
- Microwave Digital Radio
- Cellular Base Stations
- Radar
- · Ultrasound and Sonar Imaging
- · Scanners and Low-Power Portable Instruments

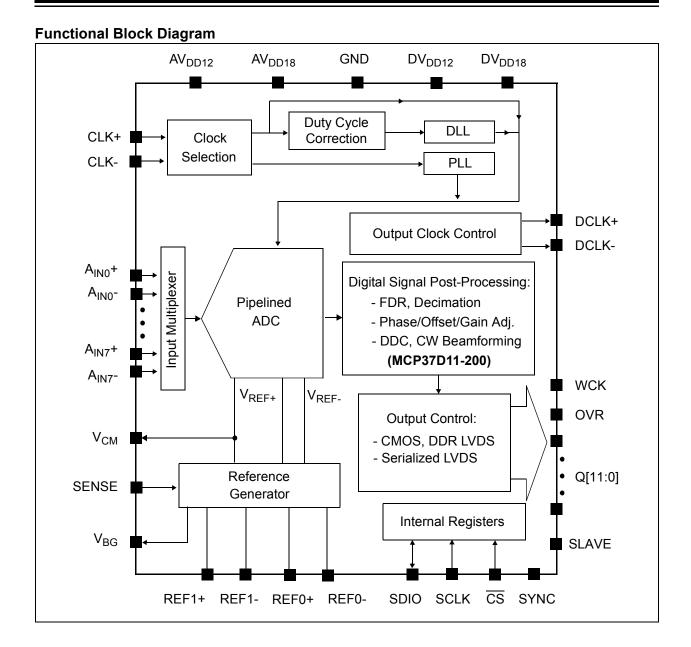
Part Number	Sample Rate	Sample Rate Resolution		Digital Down-Conversion ⁽³⁾	CW Beamforming ⁽⁴⁾	Noise-Shaping Requantizer ⁽²⁾
MCP37231-200	200 Msps	16	Yes	No	No	No
MCP37221-200	200 Msps	14	Yes	No	No	No
MCP37211-200	200 Msps	12	Yes	No	No	Yes
MCP37D31-200	200 Msps	16	Yes	Yes	Yes	No
MCP37D21-200	200 Msps	14	Yes	Yes	Yes	No
MCP37D11-200	200 Msps	12	Yes	Yes	Yes	Yes

MCP372XX/MCP37DXX Family Comparison (1):

Note 1: Devices in the same package type are pin-to-pin compatible.

2: Available in single- and dual-channel mode.

- 3: Available in single- and dual-channel mode, and octal-channel mode when CW beamforming is enabled.
- **4:** Available in octal-channel mode.



Description

The MCP37211-200 is Microchip's baseline 12-bit 200 Msps pipelined ADC, featuring built-in high-order digital decimation filters, noise-shaping requantizer, gain and offset adjustment per channel and fractional delay recovery.

The MCP37D11-200 device features digital downconversion and CW beamforming capability, in addition to the features offered by the MCP37211-200.

All devices feature harmonic distortion correction and DAC noise cancellation that enable high-performance specifications with SNR of 71.3 dBFS (typical) and SFDR of 90 dBc (typical).

These A/D converters exhibit industry-leading lowpower performance with only 468 mW operation while using the LVDS interface at 200 Msps. This superior low-power operation coupled with high dynamic performance makes these devices ideal for various high-performance, high-speed data acquisition systems, including communications equipment, radar and portable instrumentation.

In single or dual-channel mode, the Noise-Shaping Requantizer (NSR) feature can allow the ADC to improve SNR beyond a conventional 11- or 12-bit ADC. The NSR reshapes the quantization noise, such that most of the noise power is pushed outside the frequency of interest. As a result, SNR is improved significantly within a selected frequency band of interest while SFDR is not affected.

The digital down-conversion option in the MCP37D10-200 can be utilized with the decimation and quadrature output (I and Q data) option, and offers great flexibility in various digital communication system designs, including cellular base-stations and narrow-band communication systems.

The output decimation filter option improves SNR performance up to 73.7 dBFS. The digital down-conversion option, in conjunction with the decimation and quadrature output options, offers great flexibility in digital communication system design, including cellular base-stations and narrow-band communications.

These devices can have up to eight differential input channels through an input MUX. The sampling rate is up to 200 Msps when a single channel is used, or 25 Msps per channel when all eight input channels are used.

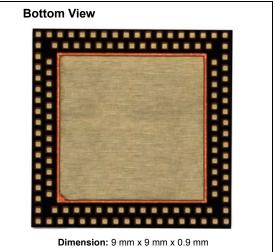
In dual or octal-channel mode, the Fractional Delay Recovery (FDR) feature digitally corrects the difference in sampling instance between different channels, so that all inputs appear to have been sampled at the same time.

AutoSync mode offers a great design flexibility when multiple devices are used in applications. It allows multiple devices to sample input synchronously at the same clock. The differential full-scale analog input range is programmable up to 2.975 V_{P-P} . The ADC output data can be coded in two's complement or offset binary representation, with or without the data randomizer option. The output data is available as full-rate CMOS or Double-Data-Rate (DDR) LVDS.

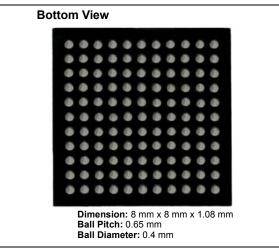
These devices also include various features designed to maximize flexibility in the user's applications and minimize system cost, such as a programmable PLL clock, output data rate control and phase alignment and programmable digital pattern generation. The device's operational modes and feature sets are configured by setting up the user-programmable registers.

The device is available in Pb-free VTLA-124 and TFBGA-121 packages. The device operates over the commercial temperature range of -40°C to +85°C.

Package Types



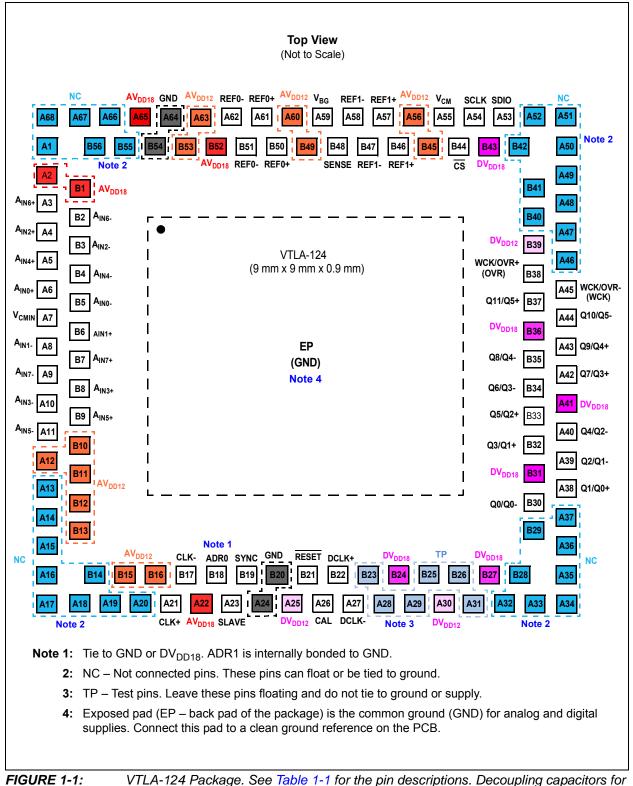
(a) VTLA-124 Package.



(b) TFBGA-121 Package.

NOTES:

1.0 PACKAGE PIN CONFIGURATIONS AND FUNCTION DESCRIPTIONS



reference pins and V_{BG} are embedded in the package. Leave TP pins floating always.

TABLE 1-1: PIN FUNCTION TABLE FOR VTLA-124

Pin No.	Name	I/O Type	Description
Power Supply Pin	s		
A2, A22, A65, B1, B52	AV _{DD18}	Supply	Supply voltage input (1.8V) for analog section
A12, A56, A60, A63, B10, B11, B12, B13, B15, B16, B45, B49, B53	AV _{DD12}		Supply voltage input (1.2V) for analog section
A25, A30, B39	DV _{DD12}		Supply voltage input (1.2V) for digital section
A41, B24, B27, B31, B36, B43	DV _{DD18}		Supply voltage input (1.8V) for digital section and all digital I/O
EP	GND		Exposed pad: Common ground pin for digital and analog sections
ADC Analog Input	Pins		
A3	A _{IN6+}	Analog	Channel 6 differential analog input (+)
B2	A _{IN6-}	Input	Channel 6 differential analog input (-)
A4	A _{IN2+}		Channel 2 differential analog input (+)
B3	A _{IN2-}		Channel 2 differential analog input (-)
A5	A _{IN4+}		Channel 4 differential analog input (+)
B4	A _{IN4-}		Channel 4 differential analog input (-)
A6	A _{IN0+}		Channel 0 differential analog input (+)
B5	A _{IN0-}		Channel 0 differential analog input (-)
B6	A _{IN1+}		Channel 1 differential analog input (+)
A8	A _{IN1-}		Channel 1 differential analog input (-)
B7	A _{IN7+}		Channel 7 differential analog input (+)
A9	A _{IN7-}		Channel 7 differential analog input (-)
B8	A _{IN3+}		Channel 3 differential analog input (+)
A10	A _{IN3-}		Channel 3 differential analog input (-)
B9	A _{IN5+}		Channel 5 differential analog input (+)
A11	A _{IN5-}		Channel 5 differential analog input (-)
A21	CLK+		Differential clock input (+)
B17	CLK-		Differential clock input (-)
Reference Pins ⁽¹⁾			
A57, B46	REF1+	Analog	Differential reference 1 (+) voltage
A58, B47	REF1-	Output	Differential reference 1 (-) voltage
A61, B50	REF0+	1	Differential reference 0 (+) voltage
A62, B51	REF0-	1	Differential reference 0 (-) voltage
SENSE, Bandgap	and Commo	n-Mode Volta	ge Pins
B48	SENSE	Analog Input	Analog input full-scale range selection. See Table 4-2 for SENSE voltage settings.
A59	V_{BG}	Analog Output	Internal bandgap output voltage Connect a decoupling capacitor (2.2 μF)
A7	V _{CMIN}	Analog Input	Common-mode voltage input for auto-calibration Connect V_{CM} voltage ⁽²⁾
A55	V _{CM}		Common-mode output voltage (900 mV) for analog input signal Connect a decoupling capacitor (0.1 μ F) ⁽³⁾

Pin No.	Name	I/O Type	Description
Digital I/O Pins			
B18	ADR0	Digital Input	SPI address selection pin (A0 bit). Tie to GND or DV _{DD18} . ⁽⁴⁾
A23	SLAVE		Slave or Master selection pin in AutoSync ⁽¹¹⁾ If not used, tie to GND.
B19	SYNC	Digital Input/ Output	Digital synchronization pin for AutoSync ⁽¹¹⁾ If not used, leave it floating.
B21	RESET	Digital Input	Reset control input: High: Normal operating mode Low: Reset mode ⁽⁵⁾
A26	CAL	Digital Output	Calibration status flag digital output: High: Calibration is complete Low: Calibration is not complete ⁽⁵⁾
B22	DCLK+		LVDS: Differential digital clock output (+) CMOS: Digital clock output ⁽⁷⁾
A27	DCLK-		LVDS: Differential digital clock output (-) CMOS: Unused (leave floating)
ADC Output Pins	8)		
B30	Q0/Q0-	Digital	Digital data output: CMOS = Q0, DDR LVDS = Q0-
A38	Q1/Q0+	Output	Digital data output: CMOS = Q1, DDR LVDS = Q0+
A39	Q2/Q1-		Digital data output: CMOS = Q2, DDR LVDS = Q1-
B32	Q3/Q1+		Digital data output: CMOS = Q3, DDR LVDS = Q1+
A40	Q4/Q2-		Digital data output: CMOS = Q4, DDR LVDS = Q2-
B33	Q5/Q2+		Digital data output: CMOS = Q5, DDR LVDS = Q2+
B34	Q6/Q3-		Digital data output: CMOS = Q6, DDR LVDS = Q3-
A42	Q7/Q3+		Digital data output: CMOS = Q7, DDR LVDS = Q3+
B35	Q8/Q4-		Digital data output: CMOS = Q8, DDR LVDS = Q4-
A43	Q9/Q4+		Digital data output: CMOS = Q9, DDR LVDS = Q4+
A44	Q10/Q5-		Digital data output: CMOS = Q10, DDR LVDS = Q5-
B37	Q11/Q5+		Digital data output: CMOS = Q11, DDR LVDS = Q5+
B38	WCK/OVR+ (OVR)		WCK: Word clock sync digital output OVR: Input over-range indication digital output ⁽¹⁰⁾
A45	WCK/OVR- (WCK)		
SPI Interface Pins	5		
A53	SDIO	Digital Input/ Output	SPI data input/output
A54	SCLK	Digital	SPI serial clock input
B44	CS	Input	SPI Chip Select input
Not Connected Pi	ns		
A1, A13 - A20, A32 - A37, A46 - A52, A66 - A68, B14, B28, B29, B40, B41, B42, B55, B56	NC		These pins can be tied to ground or left floating.
Pins that need to	be grounded		
A24, A64, B20, B54	GND		These pins are not supply pins, but need to be tied to ground.
Output Test Pins	•		
A28, A29, A31, B23, B25, B26	TP	Digital Output	Output test pins. Do not use. Always Leave these pins floating. ⁽⁹⁾

TABLE 1-1: PIN FUNCTION TABLE FOR VTLA-124 (CONTINUED)

Notes:

- These pins are for the internal reference voltage outputs. They should not be driven. External decoupling circuits are required. See Section 4.5.3, "Decoupling Circuits for Internal Voltage Reference and Bandgap Output" for details.
- 2. V_{CMIN} is used for Auto-Calibration only. V_{CMIN} + and V_{CMIN} should be tied together always. There should be no voltage difference between the two pins. Typically both V_{CMIN} + and V_{CMIN} are tied to the V_{CM} output pin together, but they can be tied to another common-mode voltage if external V_{CM} is used. This pin has High Z input in Shutdown, Standby and Reset modes.
- 3. When the V_{CM} output is used for the common-mode voltage of analog inputs (i.e. by connecting to the centertap of a balun), the V_{CM} pin should be decoupled with a 0.1 μ F capacitor, and should be directly tied to the V_{CMIN}+ and V_{CMIN}- pins.
- 4. ADR1 (for A1 bit) is internally bonded to GND ('0'). If ADR0 is dynamically controlled, ADR0 must be held constant while CS is "Low".
- 5. The device is in Reset mode while this pin stays "Low". On the rising edge of RESET, the device exits Reset mode, initializes all internal user registers to default values, and begins power-up calibration.
- 6. CAL pin stays "Low" at power-up until the first power-up calibration is completed. When the first calibration has completed, this pin has "High" output. It stays "High" until the internal calibration is restarted by hardware or a soft reset command. In Reset mode, this pin is "Low". In Standby and Shutdown modes, this pin will maintain the prior condition.
- The phase of DCLK relative to the data output bits may be adjusted depending on the operating mode. This is controlled differently depending on the configuration of the digital signal post-processing, PLL and/or DLL. Also see Addresses 0x52, 0x64 and 0x6D (Registers 5-7, 5-22 and 5-28) for more details.
- 8. DDR LVDS: Two data bits are multiplexed onto each differential output pair. The output pins shown here are for the "Even bit first", which is the default setting of OUTPUT_MODE<1:0> in Address 0x62 (Register 5-20). The even data bits (Q0, Q2, Q4, Q6, Q8, Q10) appear when DCLK+ is "High". The odd data bits (Q1, Q3, Q5, Q7, Q9, Q11) appear when DCLK+ is "Low". See Addresses 0x65 (Register 5-23) and 0x68 (Register 5-26) for output polarity control. See Figure 2-2 for LVDS output timing diagram.
- 9. Do not tie to ground or supply.
- CMOS output mode: WCK/OVR- is WCK and WCK/OVR+ is OVR.
 DDR LVDS output mode: The rising edge of DCLK+ is WCK and the falling edge is OVR.
 OVR: OVR will be held "High" when analog input overrange is detected. Digital signal post-processing will cause OVR to assert early relative to the output data. See Figure 2-2 for LVDS timing of these bits.
 WCK: WCK is normally "Low". WCK is "High" while data from the first channel is sent out. In single-channel mode, WCK stays "High" except when in I/Q output mode. See Section 4.12.4 "Word Clock (WCK)" for further WCK description.
- (a) SLAVE = "High": The device is selected as slave and the SYNC pin becomes input pin.
 (b) SLAVE = "Low": The device is selected as master and the SYNC pin becomes output pin. In SLAVE/SYNC operation, master and slave devices are synchronized to the same clock.

						Fop Vie lot to Sca					
	1	2	3	4	5	6	7	8	9	10	11
A	SDIO	V _{CM}	REF1+	REF1-	V _{BG}	REF0+	REF0-	GND	GND	A _{IN4-}	A _{IN2+}
в	SCLK	cs	GND	GND	SENSE	AV _{DD12}	AV _{DD12}	AV _{DD18}	AV _{DD18}	A _{IN4+}	A _{IN2-}
С	WCK/ OVR- (WCK)	WCK/ OVR+ (OVR)	GND	GND	AV _{DD12}	AV _{DD12}	AV _{DD12}	GND	GND	A _{IN6-}	A _{IN0+}
D	Q10/Q5-	Q11/Q5+	GND	GND	AV _{DD12}	AV _{DD12}	AV _{DD12}	GND	GND	A _{IN6+}	A _{IN0-}
Е	<mark>Q8/Q4-</mark>	Q9/Q4+	GND	GND	AV _{DD12}	AV _{DD12}	AV _{DD12}	GND	GND	A _{IN5+}	A _{IN1+}
F	Q6/Q3-	Q7/Q3+	DV _{DD18}	DV _{DD18}	AV _{DD12}	AV _{DD12}	AV _{DD12}	GND	GND	A _{IN5-}	A _{IN1-}
G	Q4/Q2-	Q5/Q2+	DV _{DD18}	DV _{DD18}	GND	GND	AV _{DD12}	AV _{DD12}	GND	A _{IN7-}	A _{IN3+}
Н	Q2/Q1-	Q3/Q1+	DV _{DD12}	DV _{DD12}	GND	GND	GND	GND	GND	A _{IN7+}	A _{IN3-}
J	Q0/Q0-	Q1/Q0+	DV _{DD12}	DV _{DD12}	GND	GND	GND	GND	GND	V _{CMIN} +	V _{CMIN} -
κ	тр	тр	тр	DCLK-	CAL	GND	SLAVE	ADR0	ADR1	GND	GND
L	тр	ТР	ТР	DCLK+	RESET	SYNC	GND	CLK+	CLK-	GND	AV _{DD18}
Analog Digital All others: Supply Voltage Notes: • Die dimension: 8 mm x 8 mm x 1.08 mm. • Ball dimension: (a) Ball Pitch = 0.65 mm, (b) Ball Diameter = 0.4 mm. • Flip-chip solder ball composition: Sn with Ag 1.8%. • Solder sphere composition: SAC-405 (Sn/Au 4%/Cu 0.5%).											

for reference pins and V_{BG} are embedded in the package. Leave TP pins floating always.

TABLE 1-2: PIN FUNCTION TABLE FOR TFBGA-121

Ball No.	Name	I/O Type	Description			
A1	SDIO	Digital Input/	SPI data input/output			
		Output				
A2	V _{CM}	Analog Output	Common-mode output voltage (900 mV) for analog input signal Connect a decoupling capacitor (0.1 µF) ⁽¹⁾			
A3	REF1+	Output	Differential reference voltage 1 (+/-). Decoupling capacitors are embedded in			
A4	REF1-		the TFBGA package. Leave these pins floating.			
A5	V _{BG}		Internal bandgap output voltage			
			A decoupling capacitor (2.2 $\mu F)$ is embedded in the TFBGA package. Leave this pin floating.			
A6	REF0+		Differential reference 0 (+/-) voltage. Decoupling capacitors are embedded in			
A7	REF0-		the TFBGA package. Leave these pins floating.			
A8	GND	Supply	Common ground for analog and digital sections			
A9						
A10	A _{IN4-}	Analog Input				
A11	A _{IN2+}		Channel 2 differential analog input (+)			
B1	SCLK	Digital Input	SPI serial clock input			
B2	CS		SPI Chip Select input			
B3	GND	Supply	Common ground for analog and digital sections			
B4						
B5	SENSE	Analog Input	Analog input range selection. See Table 4-2 for SENSE voltage settings.			
B6	AV _{DD12}	Supply	Supply voltage input (1.2V) for analog section			
B7						
B8	AV _{DD18}		Supply voltage input (1.8V) for analog section			
B9						
B10	A _{IN4+}	Analog Input	Channel 4 differential analog input (+)			
B11	A _{IN2-}		Channel 2 differential analog input (-)			
C1	WCK/OVR- (WCK)	Digital Output	WCK: Word clock sync digital output OVR: Input overrange indication digital output ⁽²⁾			
C2	WCK/OVR+ (OVR)					
C3	GND	Supply	Common ground for analog and digital sections			
C4						
C5	AV _{DD12}		Supply voltage input (1.2V) for analog section			
C6						
C7						
C8	GND		Common ground pin for analog and digital sections			
C9			Channel 6 differential analog input (-)			
C10	A _{IN6-}	Analog Input				
C11	A _{IN0+}	6	Channel 0 differential analog input (+)			
D1	Q10/Q5-	Digital Output	Digital data output ⁽³⁾ CMOS = Q10 DDR LVDS = Q5-			
D2	Q11/Q5+		DDR LVDS = Q5- Digital data output ⁽³⁾			
	Q 11/Q0 ⁺		CMOS = Q11 $DDR LVDS = Q5+$			
D3	GND	Supply	Common ground for analog and digital sections			
D4		1° F - J				

TABLE 1-	TABLE 1-2: PIN FUNCTION TABLE FOR TFBGA-121 (CONTINUED)									
Ball No.	Name	I/O Type	Description							
D5	AV _{DD12}	Supply	Supply voltage input (1.2V) for analog section							
D6										
D7										
D8	GND		Common ground for analog and digital sections							
D9										
D10	A _{IN6+}	Analog Input	Channel 6 differential analog input (+)							
D11	A _{IN0-}		Channel 0 differential analog input (-)							
E1	Q8/Q4-	Digital Output	Digital data output ⁽³⁾ CMOS = Q8 DDR LVDS = Q4-							
E2	Q9/Q4+		Digital data output ⁽³⁾ CMOS = Q9 DDR LVDS = Q4+							
E3	GND	Supply	Common ground for analog and digital sections							
E4 E5	AV _{DD12}	-	Supply voltage input (1.2V) for analog section							
E6	AV DD12		Suppry voltage input (1.2v) for analog section							
E7										
E8	GND	_	Common ground for analog and digital sections							
E9			5 5 5							
E10	A _{IN5+}		Channel 5 differential analog input (+)							
E11	A _{IN1+}	Analog Input	Channel 1 differential analog input (+)							
F1	Q6/Q3-	Digital	Digital data output ⁽³⁾							
F2	Q7/Q3+	Output	CMOS = Q6 DDR LVDS = Q3- Digital data output ⁽³⁾							
F2			CMOS = Q7 DDR LVDS = Q3+							
F3	DV _{DD18}	Supply	Supply voltage input (1.8V) for digital section.							
F4		_	All digital input pins are driven by the same DV _{DD18} potential.							
F5	AV_{DD12}		Supply voltage input (1.2V) for analog section							
F6										
F7		-								
F8	GND		Common ground for analog and digital sections							
F9 F10	A _{IN5-}		Channel 5 differential analog input (-)							
F11	A _{IN1-}	Analog Input	Channel 1 differential analog input (-)							
G1	Q4/Q2-	Digital	Digital data output ⁽³⁾							
	<u></u>	Output	Digital data output ⁽⁴⁾ CMOS = $Q4$ DDR LVDS = $Q2$ -							
G2	Q5/Q2+		Digital data output ⁽³⁾ CMOS = Q5 DDR LVDS = Q2+							
G3	DV _{DD18}	Supply	Supply voltage input (1.8V) for digital section							
G4			All digital input pins are driven by the same DV _{DD18} potential							
G5	GND		Common ground for analog and digital sections							
G6										

TABLE 1-2: PIN FUNCTION TABLE FOR TFBGA-121 (CONTINUED)

TABLE 1-2: PIN FUNCTION TABLE FOR TFBGA-121 (CONTINUED)									
Ball No.	Name	I/O Type	Description						
G7	AV _{DD12}	Supply	Supply voltage input (1.2V) for analog section						
G8									
G9	GND		Common ground for analog and digital sections						
G10	A _{IN7-}	Analog Input	Channel 7 differential analog input (-)						
G11	A _{IN3+}		Channel 3 differential analog input (+)						
H1	Q2/Q1-	Digital Output	Digital data output ⁽³⁾ CMOS = Q2 DDR LVDS = Q1-						
H2	Q3/Q1+		Digital data output ⁽³⁾ CMOS = Q3 DDR LVDS = Q1+						
H3	DV _{DD12}	Supply	Supply voltage input (1.2V) for digital section						
H4									
H5	GND		Common ground for analog and digital sections						
H6									
H7									
H8									
H9									
H10	A _{IN7+}	Analog Input	Channel 7 differential analog input (+)						
H11	A _{IN3-}		Channel 3 differential analog input (-)						
J1	Q0/Q0-	Digital Output	Digital data output ⁽³⁾ CMOS = Q0 DDR LVDS = Q0-						
J2	Q1/Q0+	-	Digital data output ⁽³⁾ CMOS = Q1 DDR LVDS = Q0+						
J3	DV _{DD12}	Supply	DC supply voltage input pin for digital section (1.2V)						
J4	0012	,							
J5	GND	-	Common ground for analog and digital sections						
J6									
J7									
J8									
J9									
J10	V _{CMIN+}	Analog Input	Common-mode voltage input for auto-calibration ⁽⁴⁾ These two pins should be tied together and connected to V _{CM} voltage.						
J11	V _{CMIN-}								
K1	TP	Digital	Output test pints. Leave these pins floating always ⁽⁸⁾						
K2		Output							
K3		1							
K4	DCLK-		LVDS: Differential digital clock output (-) CMOS: Not used (leave floating)						
K5	CAL	Digital Output	Calibration status flag digital output ⁽⁵⁾ High: Calibration is complete Low: Calibration is not complete						
K6	GND	Supply	Common ground pin for analog and digital sections						
K7	SLAVE	Digital Input	Slave or Master selection pin in AutoSync ⁽¹⁰⁾ . If not used, tie to GND.						
K8	ADR0	1 1	SPI address selection pin (A0 bit). Tie to GND or DVDD18 ⁽⁶⁾						
K9	ADR1	4	SPI address selection pin (A1 bit). Tie to GND or DVDD18 ⁽⁶⁾						

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Ball No.	Name	I/O Type	Description
K10	GND	Supply	Common ground for analog and digital sections
K11			
L1	TP	Digital	Output test pints. Leave these pins floating always ⁽⁸⁾
L2		Output	
L3			
L4	DCLK-		LVDS: Differential digital clock output (+) CMOS: Digital clock output ⁽⁷⁾
L5	RESET	Digital Input	Reset control input: High: Normal operating mode Low: Reset mode ⁽⁹⁾
L6	SYNC	Digital Input/ Output	Digital synchronization pin for AutoSync. ⁽¹⁰⁾ If not used, leave it floating.
L7	GND	Supply	Common ground for analog and digital sections
L8	CLK+	Analog Input	Differential clock input (+)
L9	CLK-	1	Differential clock input (-)
L10	GND	Supply	Common ground for analog and digital sections
L11	AV _{DD18}	Analog Input	Supply voltage input (1.8V) for analog section

TABLE 1-2: PIN FUNCTION TABLE FOR TFBGA-121 (CONTINUED)

Notes:

- 1. When the V_{CM} output is used for the common-mode voltage of analog inputs (i.e. by connecting to the center-tap of a balun), the V_{CM} pin should be decoupled with a 0.1 μ F capacitor, and should be directly tied to the V_{CMIN}+ and V_{CMIN}- pins.
- CMOS output mode: WCK/OVR- is WCK and WCK/OVR+ is OVR.
 DDR LVDS output mode: The rising edge of DCLK+ is WCK and the falling edge is OVR.
 OVR: OVR will be held "High" when analog input overrange is detected. Digital signal post-processing will cause OVR to assert early relative to the output data. See Figure 2-2 for LVDS timing of these bits.
 WCK: WCK is normally "Low". WCK is "High" while data from the first channel is sent out. In single-channel mode, WCK stays "High" except when in I/Q output mode. See Section 4.12.4 "Word Clock (WCK)" for further WCK description.
- DDR LVDS: Two data bits are multiplexed onto each differential output pair. The output pins shown here are for the "Even bit first", which is the default setting of OUTPUT_MODE<1:0> in Address 0x62 (Register 5-20). The even data bits (Q0, Q2, Q4, Q6, Q8, Q10) appear when DCLK+ is "High". The odd data bits (Q1, Q3, Q5, Q7, Q9, Q11) appear when DCLK+ is "Low". See Addresses 0x65 (Register 5-23) and 0x68 (Register 5-26) for output polarity control. See Figure 2-2 for LVDS output timing diagram.
- 4. V_{CMIN} is used for Auto-Calibration only. V_{CMIN}+ and V_{CMIN}- should be tied together always. There should be no voltage difference between the two pins. Typically both V_{CMIN}+ and V_{CMIN}- are tied to the V_{CM} output pin together, but they can be tied to another common-mode voltage if external V_{CM} is used. This pin has High Z input in Shutdown, Standby and Reset modes.
- 5. CAL pin stays "Low" at power-up until the first power-up calibration is completed. When the first calibration has completed, this pin has "High" output. It stays "High" until the internal calibration is restarted by hardware or a soft reset command. In Reset mode, this pin is "Low". In Standby and Shutdown modes, this pin will maintain the prior condition.
- 6. If the SPI address is dynamically controlled, the Address pin must be held constant while \overline{CS} is "Low".
- 7. The phase of DCLK relative to the data output bits may be adjusted depending on the operating mode. This is controlled differently depending on the configuration of the digital signal post-processing, PLL and/or DLL. Also see Addresses 0x52, 0x64 and 0x6D (Registers 5-7, 5-22 and 5-28) for more details.
- 8. Do not tie to ground or supply.
- 9. The device is in Reset mode while this pin stays "Low". On the rising edge of RESET, the device exits Reset mode, initializes all internal user registers to default values, and begins power-up calibration.
- a) SLAVE = "High": The device is selected as slave and the SYNC pin becomes input pin.
 (b) SLAVE = "Low": The device is selected as master and the SYNC pin becomes output pin. In SLAVE/SYNC operation, master and slave devices are synchronized to the same clock.

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NOTES:

2.0 ELECTRICAL SPECIFICATIONS

2.1 Absolute Maximum Ratings†

Analog and digital supply voltage (AV _{DD12} , DV _{DD12})	-0.3V to 1.32V
Analog and digital supply voltage (AV _{DD18} , DV _{DD18})	-0.3V to 1.98V
All inputs and outputs with respect to GND	–0.3V to AV _{DD18} + 0.3V
Differential input voltage	AV _{DD18} - GND
Current at input pins	±2 mA
Current at output and supply pins	±250 mA
Storage temperature	-65°C to +150°C
Ambient temperature with power applied (T _A)	-55°C to +125°C
Maximum junction temperature (T _J)	+150°C
ESD protection on all pins	
Solder reflow profile	See Microchip Application Note AN233 (DS00233)

Notice†: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2.2 Electrical Specifications

TABLE 2-1: ELECTRICAL CHARACTERISTICS

Electrical Specifications: Unless otherwise specified, all parameters apply for $T_A = -40^{\circ}$ C to +85°C, AV_{DD18} = DV_{DD18} = 1.8V, AV_{DD12} = DV_{DD12} = 1.2V, GND = 0V, SENSE = AV_{DD12}, Single-channel mode, Differential Analog Input (A_{IN}) = Sine wave with amplitude of -1 dBFS, $f_{IN} = 70$ MHz, Clock Input = 200 MHz, $f_S = 200$ Msps (ADC Core), PLL and decimation filters are disabled, Output load: CMOS data pin = 10 pF, LVDS = 100 Ω termination, LVDS driver current setting = 3.5 mA, +25°C is applied for typical value.

Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions		
Power Supply Requireme	ents							
Analog Supply Voltage	AV _{DD18}	1.71	1.8	1.89	V			
	AV _{DD12}	1.14	1.2	1.26	V			
Digital Supply Voltage	DV _{DD18}	1.71	1.8	1.89	V	Note 1		
	DV _{DD12}	1.14	1.2	1.26	V			
Analog Supply Current								
Analog Supply Current	I _{DD_A18}	_	27	46	mA	at AV _{DD18} pin		
During Conversion	I _{DD_A12}		185	252	mA	at AV _{DD12} pin		
Digital Supply Current	Digital Supply Current							
Digital Supply Current During Conversion	I _{DD_D12}		97	226	mA	at DV _{DD12} pin		
Digital I/O Current in CMOS Output Mode	I _{DD_D18}	_	27	—	mA	at DV _{DD18} pin DCLK = 100 MHz		
Digital I/O Current in	I _{DD_D18}	Measured at DV _{DD18} Pin						
LVDS Mode	_		45	66	mA	3.5 mA mode		
			33	_	mA	1.8 mA mode		
			57			5.4 mA mode		
Supply Current during P	ower-Saving M	odes						
During Standby Mode	I _{STANDBY_AN}		84		mA	Address 0x00<4:3> = 1, 1 ⁽²⁾		
	I _{STANDBY_DIG}	_	36	_				
During Shutdown Mode	I _{DD_SHDN}		23	—	mA	Address 0x00<7,0> = 1, 1 ⁽³⁾		

TABLE 2-1: ELECTRICAL CHARACTERISTICS (CONTINUED)

Electrical Specifications: Unless otherwise specified, all parameters apply for $T_A = -40^{\circ}C$ to $+85^{\circ}C$, $AV_{DD18} = DV_{DD18} = 1.8V$, $AV_{DD12} = DV_{DD12} = 1.2V$, GND = 0V, $SENSE = AV_{DD12}$, Single-channel mode, Differential Analog Input (A_{IN}) = Sine wave with amplitude of -1 dBFS, $f_{IN} = 70$ MHz, Clock Input = 200 MHz, $f_S = 200$ Msps (ADC Core), PLL and decimation filters are disabled, Output load: CMOS data pin = 10 pF, LVDS = 100 Ω termination, LVDS driver current setting = 3.5 mA, +25°C is applied for typical value.

Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions
PLL Circuit						·
PLL Circuit Current	I _{DD_PLL}		17	_	mA	PLL enabled. Included in analog supply current specification.
Total Power Dissipation ⁽⁴)					
Power Dissipation During Conversion, Excluding Digital I/O	P _{DISS_ADC}		387		mW	
Total Power Dissipation During Conversion with CMOS Output Mode	P _{DISS_CMOS}	—	436	—	mW	f _S = 200 Msps, DCLK = 100 MHz
Total Power Dissipation	P _{DISS_LVDS}		468	_	mW	3.5 mA mode
During Conversion with		—	446	_		1.8 mA mode
LVDS Output Mode			490			5.4 mA mode
During Standby Mode	P _{DISS_STANDBY}	—	144	_	mW	Address 0x00<4:3> = 1, 1 ⁽²⁾
During Shutdown Mode	P _{DISS_SHDN}	—	27.6	—	mW	Address 0x00<7,0> = 1, 1 ⁽³⁾
Power-on Reset (POR) Ve	oltage					
Threshold Voltage	VPOR	_	800	_	mV	Applicable to AV _{DD12} only
Hysteresis	VPOR_HYST	—	40	_	mV	(POR tracks AV _{DD12})
SENSE Input ^(5,7)						
SENSE Input Voltage	V _{SENSE}	GND	_	AV _{DD12}	V	V _{SENSE} selects reference
SENSE Pin Input Resistance	R _{IN_SENSE}	—	500	_	Ω	To virtual ground at 0.55V. 400 mV < V _{SENSE} < 800 mV
Current Sink into SENSE	ISENSE	_	4.5	—	μA	SENSE = 1.2V
Pin			636			SENSE = 0.8V
			-2			SENSE = 0V
Reference and Common-	Mode Voltages					
Internal Reference Voltage	V _{REF}	—	0.74	_	V	V _{SENSE} = GND
(Selected by V _{SENSE})	-	—	1.49	—	_	V _{SENSE} = AV _{DD12}
		—	$1.86 \times V_{SENSE}$	—		400 mV < V _{SENSE} < 800 mV
Common-Mode Voltage Output	V _{CM}	—	0.9	_	V	Available at V_{CM} pin
Reference Voltage	VREF1		0.4	_	V	V _{SENSE} = GND
Output ^(7,8)			0.8			V _{SENSE} = AV _{DD12}
			0.4 - 0.8			400 mV < V _{SENSE} < 800 mV
	VREF0		0.7	_	V	V _{SENSE} = GND
			1.4	_		V _{SENSE} = AV _{DD12}
			0.7 - 1.4	_		400 mV < V _{SENSE} < 800 mV
Bandgap Voltage Output	V _{BG}	—	0.55	—	V	Available at V _{BG} pin

TABLE 2-1: ELECTRICAL CHARACTERISTICS (CONTINUED)

Electrical Specifications: Unless otherwise specified, all parameters apply for $T_A = -40^{\circ}C$ to $+85^{\circ}C$, $AV_{DD18} = DV_{DD18} = 1.8V$, $AV_{DD12} = DV_{DD12} = 1.2V$, GND = 0V, $SENSE = AV_{DD12}$, Single-channel mode, Differential Analog Input (A_{IN}) = Sine wave with amplitude of -1 dBFS, $f_{IN} = 70$ MHz, Clock Input = 200 MHz, $f_S = 200$ Msps (ADC Core), PLL and decimation filters are disabled, Output load: CMOS data pin = 10 pF, LVDS = 100 Ω termination, LVDS driver current setting = 3.5 mA, +25°C is applied for typical value.

Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions
Analog Inputs					1	
Full-Scale Differential	A _{FS}		1.4875		V _{P-P}	V _{SENSE} = GND
Analog Input Range ^(5,7)		—	2.975	—		V _{SENSE} = AVDD12
		_	3.71875 x V _{SENSE}	—		400 mV < V _{SENSE} < 800 mV
Analog Input Bandwidth	f _{IN_3dB}		500		MHz	A _{IN} = -3 dBFS
Differential Input Capacitance	C _{IN}	5	6	7	pF	Note 5, Note 9
Analog Input Channel Cross-Talk	Xtalk	_	100	—	dBc	Note 10
Analog Input Leakage Current (A _{IN} +, A _{IN} - pins)	I _{LI_AH}	_	_	+1	μA	V _{IH} = AV _{DD12}
	I _{LI_AL}	-1	—	—	μA	V _{IL} = GND
ADC Conversion Rate ⁽¹¹⁾					-1	
Conversion Rate	f _S	40	_	200	Msps	Tested at 200 Msps
Clock Inputs (CLK+, CLK	-) ⁽¹²⁾					
Clock Input Frequency	f _{CLK}		_	250	MHz	Note 5
Differential Input Voltage	V _{CLK_IN}	300	_	800	mV _{P-P}	Note 5
Clock Jitter	CLK _{JITTER}	_	175	_	f _{SRMS}	Note 5
Clock Input Duty Cycle ⁽⁵⁾		49	50	51	%	Duty cycle correction disabled
		30	50	70	%	Duty cycle correction enabled
Input Leakage Current at	I _{LI_CLKH}		_	+110	μA	V _{IH} = AV _{DD12}
CLK input pin	I _{LI_CLKL}	-20	_	—	μA	V _{IL} = GND
Converter Accuracy ⁽⁶⁾						
ADC Resolution (with no missing code)		—	_	12	bits	
Offset Error			±0.31	±3.8	LSb	
Gain Error	G _{ER}	_	±0.5	_	% of FS	
Integral Nonlinearity	INL		±0.125		LSb	
Differential Nonlinearity	DNL	_	±0.03	_	LSb	
Analog Input Common-Mode Rejection Ratio	CMRR _{DC}	_	70	_	dB	DC measurement

TABLE 2-1: ELECTRICAL CHARACTERISTICS (CONTINUED)

Electrical Specifications: Unless otherwise specified, all parameters apply for $T_A = -40^{\circ}$ C to $+85^{\circ}$ C, $AV_{DD18} = DV_{DD18} = 1.8V$, $AV_{DD12} = DV_{DD12} = 1.2V$, GND = 0V, SENSE = AV_{DD12} , Single-channel mode, Differential Analog Input (A_{IN}) = Sine wave with amplitude of -1 dBFS, $f_{IN} = 70$ MHz, Clock Input = 200 MHz, $f_S = 200$ Msps (ADC Core), PLL and decimation filters are disabled, Output load: CMOS data pin = 10 pF, LVDS = 100Ω termination, LVDS driver current setting = 3.5 mA, +25^{\circ}C is applied for typical value.

Parameters Sym.		Min.	Тур.	Max.	Units	Conditions						
Dynamic Accuracy ^(6,15)												
Spurious Free Dynamic	SFDR	78	90	_	dBc	f _{IN} = 15 MHz						
Range		77	85	_	dBc	f _{IN} = 70 MHz						
Signal-to-Noise Ratio	SNR	70.63	71.33	—	dBFS	f _{IN} = 15 MHz						
	SNR	_	71.09	_	dBFS	f _{IN} = 70 MHz						
Effective Number of Bits	ENOB	11.44	11.56	—	bits	f _{IN} = 15 MHz						
(ENOB) ⁽¹³⁾	ENOB	—	11.52	_	bits	f _{IN} = 70 MHz						
Total Harmonic Distortion	THD	78	89	_	dBc	f _{IN} = 15 MHz						
(for all resolutions, first 13 harmonics)		77	82		dBc	f _{IN} = 70 MHz						
Worst Second or	HD2 or HD3	_	90	_	dBc	f _{IN} = 15 MHz						
Third Harmonic Distortion			83	_	dBc	f _{IN} = 70 MHz						
Two-Tone Intermodulation Distortion $f_{IN_1} = 17.6 \text{ MHz},$ $f_{IN_2} = 20.6 \text{ MHz}$	IMD	_	90.5		dBc	A _{IN} = -7 dBFS, with two input frequencies						
Digital Logic Input and O	utput (Except	LVDS Outp	ut)									
Schmitt Trigger High-Level Input Voltage	V _{IH}	0.7 DV _{DD18}	—	DV _{DD18}	V							
Schmitt Trigger Low-Level Input Voltage	V _{IL}	GND	_	0.3 DV _{DD18}	V							
Hysteresis of Schmitt Trigger Inputs (All digital inputs)	V _{HYST}	_	0.05 DV _{DD18}	_	V							
Low-Level Output Voltage	V _{OL}	_	_	0.3	V	I _{OL} = -3 mA, all digital I/O pins						
High-Level Output Voltage	V _{OH}	$DV_{DD18} - 0.5$	1.8		V	I _{OL} = +3 mA, all digital I/O pins						
Digital Data Output (CMO	S Mode)											
Maximum External Load Capacitance	C _{LOAD}		10	_	pF	From output pin to GND						
Internal I/O Capacitance	C _{INT}		4	_	pF	Note 5						

TABLE 2-1: ELECTRICAL CHARACTERISTICS (CONTINUED)

Electrical Specifications: Unless otherwise specified, all parameters apply for $T_A = -40^{\circ}C$ to $+85^{\circ}C$, $AV_{DD18} = DV_{DD18} = 1.8V$, $AV_{DD12} = DV_{DD12} = 1.2V$, GND = 0V, $SENSE = AV_{DD12}$, Single-channel mode, Differential Analog Input (A_{IN}) = Sine wave with amplitude of -1 dBFS, $f_{IN} = 70$ MHz, Clock Input = 200 MHz, $f_S = 200$ Msps (ADC Core), PLL and decimation filters are disabled, Output load: CMOS data pin = 10 pF, LVDS = 100 Ω termination, LVDS driver current setting = 3.5 mA, +25°C is applied for typical value.

Parameters	Sym.	Sym. Min. Typ. Ma		Max.	Units	Conditions							
Digital Data Output (LVDS	6 Mode) ⁽⁵⁾												
LVDS High-Level Differential Output Voltage	V_{H_LVDS}	200	300	400	mV	100 Ω differential termination, LVDS bias = 3.5 mA							
LVDS Low-Level Differential Output Voltage	V_{L_LVDS}	-400	-300	-200	mV	100Ω differential termination, LVDS bias = 3.5 mA							
LVDS Common-Mode Voltage	V _{CM_LVDS}	1	1.15	1.4	V								
Output Capacitance	C _{INT_LVDS}	—	4	—	pF	Internal capacitance from output pin to GND							
Differential Load Resistance (LVDS)	R _{LVDS}		100		Ω	Across LVDS output pairs							
Input Leakage Current on	Digital I/O Pir	ıs											
Data Output Pins	I _{LI_DH}		—	+1	μA	V _{IH} = DV _{DD18}							
	I _{LI_DL}	-1	—	—	μA	V _{IL} = GND							
I/O Pins except Data	I _{LI_DH}	_	_	+6	μA	V _{IH} = DV _{DD18}							
Output Pins	I _{LI_DL}	-35		_	μA	V _{IL} = GND ⁽¹⁴⁾							

Notes:

- 1. This 1.8V digital supply voltage is used for the digital I/O circuit, including SPI, CMOS and LVDS data output drivers.
- 2. Standby Mode: Most of the internal circuits are turned off, except the internal reference, clock, bias circuits and SPI interface.
- 3. Shutdown Mode: All circuits including reference and clock are turned off except the SPI interface.
- 4. Power dissipation (typical) is calculated by using the following equation:
- (a) During operation:

 $P_{DISS} = V_{DD18} \times (I_{DD_A18} + I_{DD_D18}) + V_{DD12} \times (I_{DD_A12} + I_{DD_D12})$, where I_{DD_D18} is the digital I/O current for LVDS or CMOS output. $V_{DD18} = 1.8V$ and $V_{DD12} = 1.2V$ are used for typical value calculation. (b) During Standby mode:

P_{DISS} STANDBY = (I_{STANDBY} AN + I_{STANDBY} DIG) x 1.2V

(c) During Shutdown mode:

P_{DISS SHDN} = I_{DD SHDN} x 1.2V

- 5. This parameter is ensured by design, but not 100% tested in production.
- 6. This parameter is ensured by characterization, but not 100% tested in production.
- 7. See Table 4-2 for details.
- 8. Differential reference voltage output at REF1+/- and REF0+/- pins. $V_{REF1} = V_{REF1} + -V_{REF1}$ -. $V_{REF0} = V_{REF0} + -V_{REF0}$ -. These references should not be driven.
- 9. Input capacitance refers to the effective capacitance between one differential input pin pair.
- 10. Channel cross-talk is measured when A_{IN} = -1 dBFS at 12 MHz is applied on one channel while other channel(s) are terminated with 50 Ω . See Figure 3-45 for details.
- 11. The ADC core conversion rate. In multi-channel mode, the conversion rate of an individual channel is f_S/N, where N is the number of input channels used.
- 12. See Figure 4-8 for the details of the clock input circuit.
- 13. ENOB = (SINAD 1.76)/6.02.
- 14. This leakage current is due to the internal pull-up resistor.
- 15. Dynamic performance is characterized with CH(n)_DIG_GAIN<7:0> = 0011-1000.

TABLE 2-2: TIMING REQUIREMENTS - LVDS AND CMOS OUTPUTS

Electrical Specifications: Unless otherwise specified, all parameters apply for $T_A = -40^{\circ}$ C to +85°C, $AV_{DD18} = DV_{DD18} = 1.8V$, $AV_{DD12} = DV_{DD12} = 1.2V$, GND = 0V, $SENSE = AV_{DD12}$, Single-channel mode, Differential Analog Input (A_{IN}) = Sine wave with amplitude of -1 dBFS, $f_{IN} = 70$ MHz, Clock Input = 200 MHz, $f_S = 200$ Msps (ADC Core), PLL and decimation filters are disabled, Output load: CMOS data pin = 10 pF, LVDS = 100 Ω termination, LVDS driver current setting = 3.5 mA, +25°C is applied for typical value.

Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions
Aperture Delay	t _A	_	1	—	ns	Note 1
Out-of-Range Recovery Time	t _{OVR}	_	1		Clocks	Note 1
Output Clock Duty Cycle			50		%	Note 1
Pipeline Latency	T _{LATENCY}		28	_	Clocks	Note 2, Note 4
System Calibration ⁽¹⁾						
Power-Up Calibration Time	T _{PCAL}	_	2 ²⁷	—	Clocks	First 2 ²⁷ sample clocks after power-up
Background Calibration Update Rate	T _{BCAL}	_	2 ³⁰	—	Clocks	Per 2^{30} sample clocks after T_{PCAL}
RESET Low Time	T _{RESET}	5	_		ns	See Figure 2-6 for details ⁽¹⁾
AutoSync ^(1,6)				I.		1
Sync Output Time Delay	T _{SYNC_OUT}	_	1		Clocks	
Maximum Recommended ADC		_	200		MHz	Single-Channel mode
Clock Rate for AutoSync		_	160		-	Multi-Channel mode
LVDS Data Output Mode ^(1,5)				I.		1
Input Clock to Output Clock Propagation Delay	t _{CPD}	_	5.7	_	ns	
Output Clock to Data Propagation Delay	t _{DC}	_	0.5	—	ns	
Input Clock to Output Data Propagation Delay	t _{PD}	_	5.8	—	ns	
CMOS Data Output Mode						
Input Clock to Output Clock Propagation Delay	t _{CPD}	—	3.8	_	ns	
Output Clock to Data Propagation Delay	t _{DC}	—	0.7	_	ns	
Input Clock to Output Data Propagation Delay	t _{PD}		4.5	—	ns	

Note 1: This parameter is ensured by design, but not 100% tested in production.

2: This parameter is ensured by characterization, but not 100% tested in production.

3: t_{RISE} = approximately less than 10% of duty cycle.

4: Output latency is measured without using fractional delay recovery (FDR), decimation filter or digital down-converter options.

5: The time delay can be adjusted with the DCLK_PHDLY_DLL<2:0> setting.

6: Characterized with a single slave device. The maximum ADC sample rate for AutoSync mode may be reduced if multiple slave devices are used.

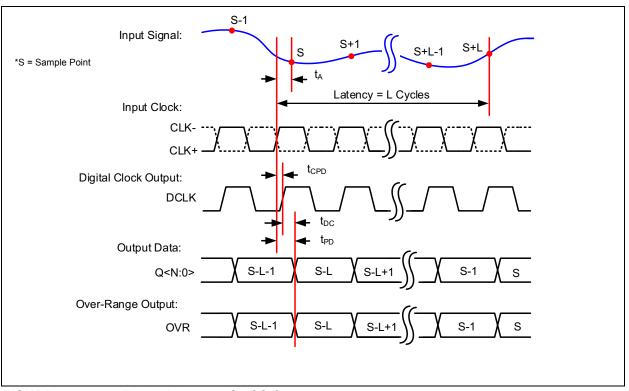


FIGURE 2-1: Timing Diagram - CMOS Output.

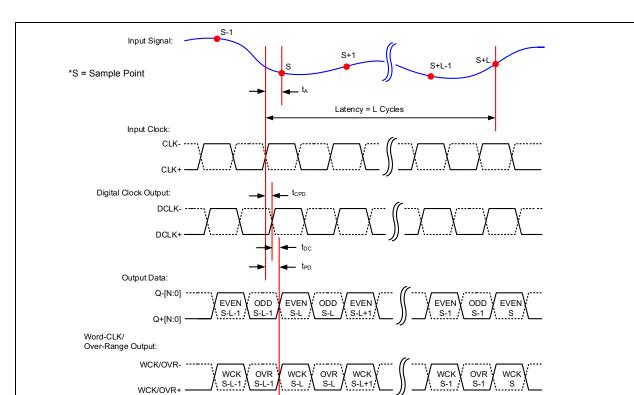


FIGURE 2-2:

Timing Diagram - LVDS Output with Even Bit First Option.

TABLE 2-3: SPI SERIAL INTERFACE TIMING SPECIFICATIONS

Electrical Specifications: Unless otherwise specified, all parameters apply for $T_A = -40^{\circ}C$ to $+85^{\circ}C$, $AV_{DD18} = DV_{DD18} = 1.8V$, $AV_{DD12} = DV_{DD12} = 1.2V$, GND = 0V, $SENSE = AV_{DD12}$, Single-channel mode, Differential Analog Input (A_{IN}) = Sine wave with amplitude of -1 dBFS, $f_{IN} = 70$ MHz, Clock Input = 200 MHz, $f_S = 200$ Msps (ADC Core), PLL and decimation filters are disabled, Output load: CMOS data pin = 10 pF, LVDS = 100Ω termination, LVDS driver current setting = 3.5 mA, +25°C is applied for typical value. All timings are measured at 50%.

Parameters	Symbol	Min.	Тур.	Max.	Units	Conditions
Serial Clock frequency, f _{SCK} =	50 MHz					
CS Setup Time	t _{CSS}	10		_	ns	
CS Hold Time	t _{CSH}	20		_	ns	
CS Disable Time	t _{CSD}	20	_		ns	
Data Setup Time	t _{su}	2	—		ns	
Data Hold Time	t _{HD}	4			ns	
Serial Clock High Time	t _{HI}	8	—		ns	
Serial Clock Low Time	t _{LO}	8	_	_	ns	Note 1
Serial Clock Delay Time	t _{CLD}	20	—		ns	
Serial Clock Enable Time	t _{CLE}	20	—		ns	
Output Valid from SCK Low	t _{DO}	_	—	20	ns	
Output Disable Time	t _{DIS}	—		10	ns	Note 1

Note 1: This parameter is ensured by design, but not 100% tested.

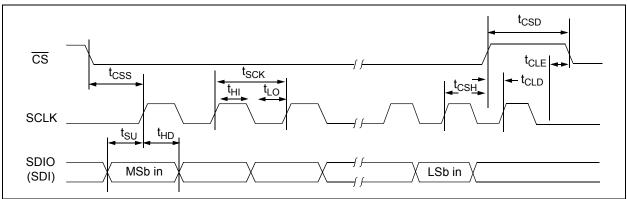


FIGURE 2-3: SPI Serial Input Timing Diagram.

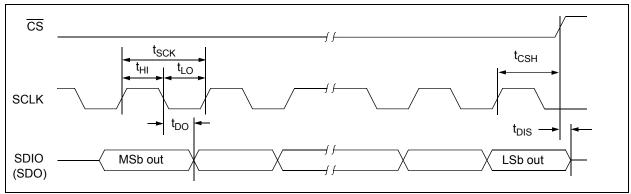
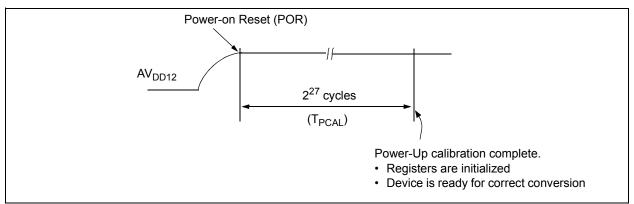
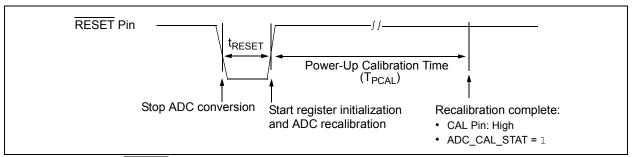


FIGURE 2-4:

SPI Serial Output Timing Diagram.









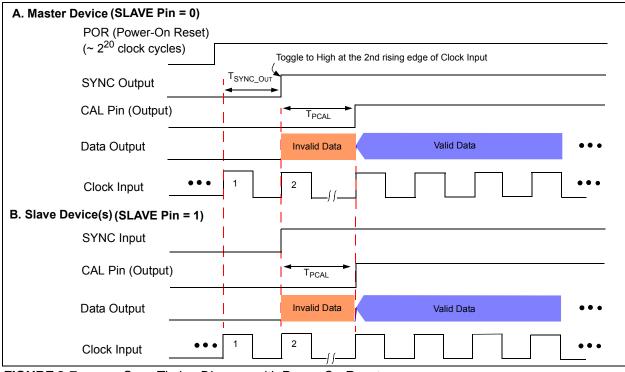
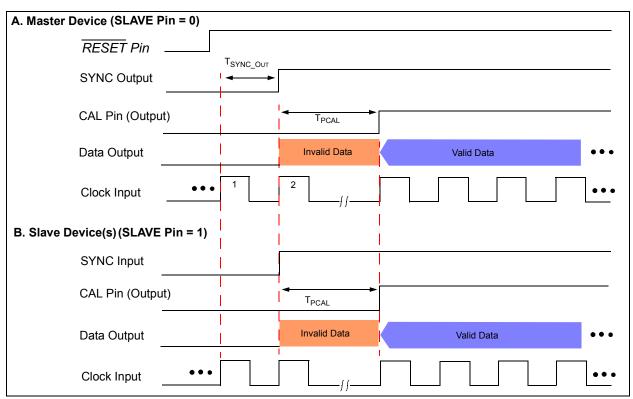
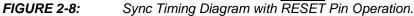


FIGURE 2-7:

Sync Timing Diagram with Power-On Reset.





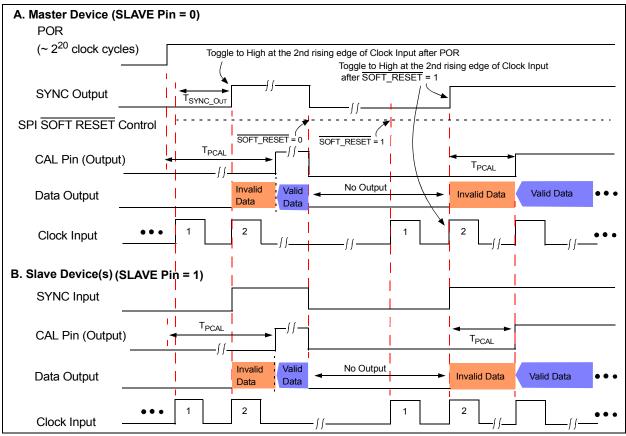


FIGURE 2-9: Sync Timing Diagram with SOFT_RESET Bit Setting.

TABLE 2-4: TEMPERATURE CHARACTERISTICS

Electrical Specifications: Unless otherwise specified, all parameters apply for $T_A = -40^{\circ}$ C to +85°C, AV_{DD18} = DV_{DD18} = 1.8V, AV_{DD12} = DV_{DD12} = 1.2V, GND = 0V, SENSE = AV_{DD12}, Single-channel mode, Differential Analog Input (A_{IN}) = Sine wave with amplitude of -1 dBFS, $f_{IN} = 70$ MHz, Clock Input = 200 MHz, $f_S = 200$ Msps (ADC Core), PLL and decimation filters are disabled, Output load: CMOS data pin = 10 pF, LVDS = 100 Ω termination, LVDS driver current setting = 3.5 mA, +25°C is applied for typical value.

	Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions
Temperature Ran	ges ⁽¹⁾						
Operating Tempera	T _A	-40	—	+85	°C		
Thermal Package	Resistances ⁽²⁾						
121L Ball-TFBGA	Junction-to-Ambient Thermal Resistance	θ_{JA}	—	40.2	—	°C/W	
(8 mm x 8 mm)	Junction-to-Case Thermal Resistance	θ_{JC}	—	8.4	_	°C/W	
124L – VTLA	Junction-to-Ambient Thermal Resistance		—	21	_	°C/W	
(9 mm x 9 mm)	Junction-to-Case (top) Thermal Resistance	θ_{JC}	—	8.7	—	°C/W	

Note 1: Maximum allowed power-dissipation (P_{DMAX}) = ($T_{JMAX} - T_A$)/ θ_{JA} .

2: This parameter value is achieved by package simulations.

NOTES:

3.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

Note: Unless otherwise specified, all parameters apply for $T_A = -40^{\circ}C$ to $+85^{\circ}C$, $AV_{DD18} = DV_{DD18} = 1.8V$, $AV_{DD12} = DV_{DD12} = 1.2V$, GND = 0V, SENSE = AV_{DD12} , Single-channel mode, Differential Analog Input (A_{IN}) = Sine wave with amplitude of -1 dBFS, $f_{IN} = 70$ MHz, Clock Input = 200 MHz, $f_S = 200$ Msps (ADC Core), PLL and decimation filters are disabled. When NSR option is used, 12-bit mode is applied and the noise is calculated within the NSR bandwidth (25% of sampling frequency).

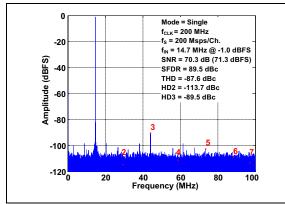


FIGURE 3-1: FFT for 14.7 MHz Input Signal: $f_S = 200$ Msps/Ch., $A_{IN} = -1$ dBFS.

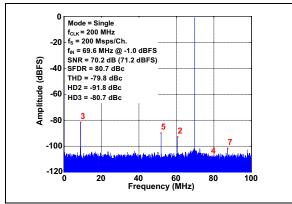


FIGURE 3-2: FFT for 69.6 MHz Input Signal: $f_S = 200$ Msps/Ch., $A_{IN} = -1$ dBFS.

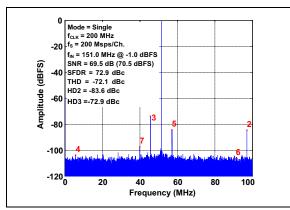


FIGURE 3-3: FFT for 151 MHz Input Signal: $f_S = 200$ Msps/Ch., $A_{IN} = -1$ dBFS.

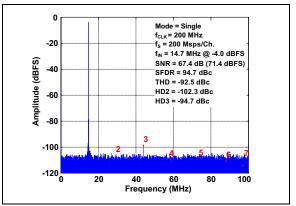


FIGURE 3-4: FFT for 14.7 MHz Input Signal: $f_S = 200$ Msps/Ch., $A_{IN} = -4$ dBFS.

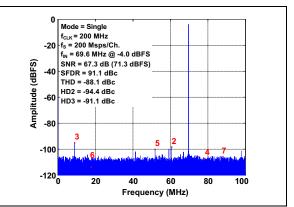


FIGURE 3-5: FFT for 69.6 MHz Input Signal: $f_S = 200$ Msps/Ch., $A_{IN} = -4$ dBFS.

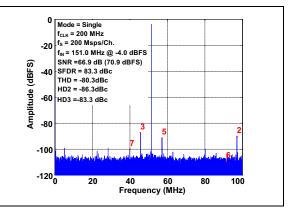


FIGURE 3-6: FFT for 151 MHz Input Signal: $f_S = 200$ Msps/Ch., $A_{IN} = -4$ dBFS.

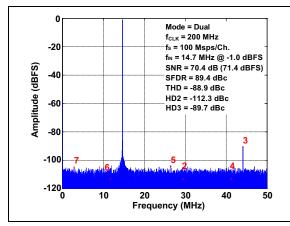


FIGURE 3-7: FFT for 14.7 MHz Input Signal: $f_S = 100$ Msps/Ch., Dual, $A_{IN} = -1$ dBFS.

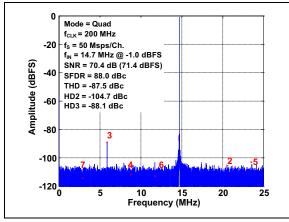


FIGURE 3-8: FFT for 14.7 MHz Input Signal: $f_S = 50$ Msps/Ch., Quad, $A_{IN} = -1$ dBFS.

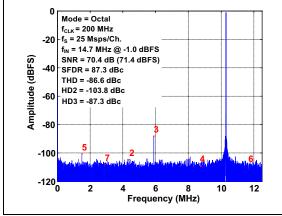


FIGURE 3-9: FFT for 14.7 MHz Input Signal: $f_S = 25$ Msps/Ch., Octal, $A_{IN} = -1$ dBFS.

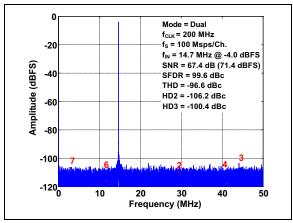


FIGURE 3-10: FFT for 14.7 MHz Input Signal: $f_S = 100$ Msps/Ch., Dual, $A_{IN} = -4$ dBFS.

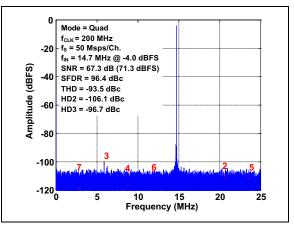


FIGURE 3-11: FFT for 14.7 MHz Input Signal: $f_S = 50$ Msps/Ch., Quad, $A_{IN} = -4$ dBFS.

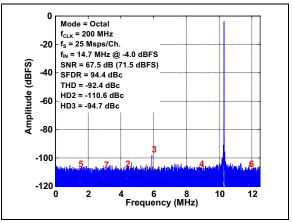


FIGURE 3-12: FFT for 14.7 MHz Input Signal: $f_S = 25$ Msps/Ch., Octal, $A_{IN} = -4$ dBFS.

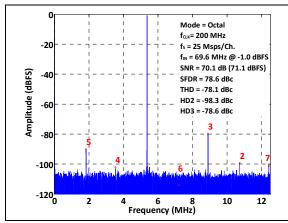


FIGURE 3-13: FFT for 69.6 MHz Input Signal: $f_S = 25$ Msps/Ch., Octal, $A_{IN} = -1$ dBFS.

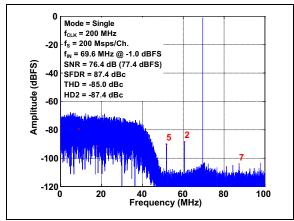


FIGURE 3-14: FFT for 69.6 MHz Input Signal with NSR enabled: NSR = 20, $f_S = 200$ Msps/Ch., $A_{IN} = -1$ dBFS.

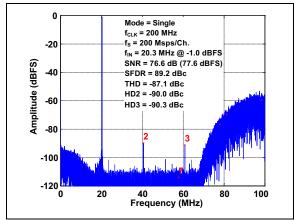


FIGURE 3-15: FFT for 20.3 MHz Input Signal with NSR enabled: NSR = 27, $f_S = 200$ Msps/Ch., $A_{IN} = -1$ dBFS.

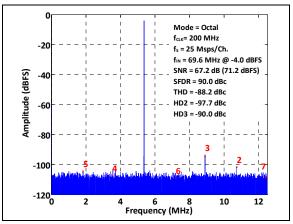


FIGURE 3-16: FFT for 69.6 MHz Input Signal: $f_S = 25$ Msps/Ch., Octal, $A_{IN} = -4$ dBFS.

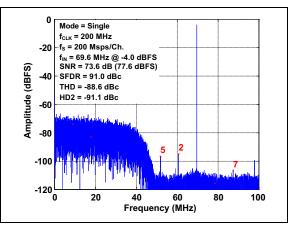


FIGURE 3-17: FFT for 69.6 MHz Input Signal with NSR enabled: NSR = 20, $f_S = 200$ Msps/Ch., $A_{IN} = -4$ dBFS.

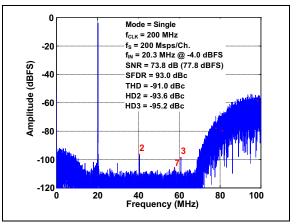


FIGURE 3-18: FFT for 20.3 MHz Input Signal with NSR enabled: NSR = 27, $f_S = 200$ Msps/Ch., $A_{IN} = -4$ dBFS.

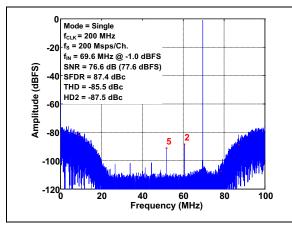


FIGURE 3-19: FFT for 69.6 MHz Input Signal with NSR enabled: NSR = 52, $f_S = 200$ Msps/Ch., $A_{IN} = -1$ dBFS.

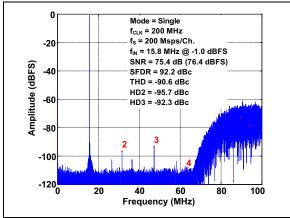


FIGURE 3-20: FFT for 15.8 MHz Input Signal with NSR enabled: NSR = 63, $f_S = 200$ Msps/Ch., $A_{IN} = -1$ dBFS.

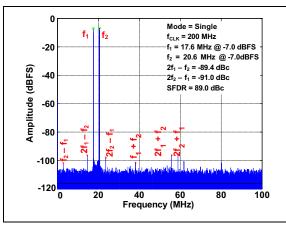


FIGURE 3-21: Two-Tone FFT: $f_{IN1} = 17.6 \text{ MHz}$ and $f_{IN2} = 20.6 \text{ MHz}$, $A_{IN} = -7 \text{ dBFS}$ per Tone, $f_S = 200 \text{ Msps}$.

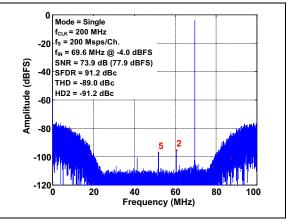


FIGURE 3-22: FFT for 69.6 MHz Input Signal with NSR enabled: NSR = 52, $f_S = 200$ Msps/Ch., $A_{IN} = -4$ dBFS.

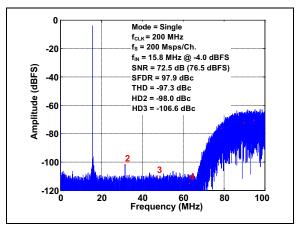


FIGURE 3-23: FFT for 15.8 MHz Input Signal with NSR enabled: NSR = 63, $f_S = 200$ Msps/Ch., $A_{IN} = -4$ dBFS.

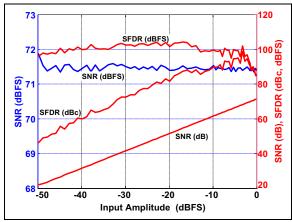


FIGURE 3-24: SNR/SFDR vs. Analog Input Amplitude: $f_S = 200$ Msps, $f_{IN} = 15$ MHz, High-Reference Mode (SENSE = AV_{DD12}).

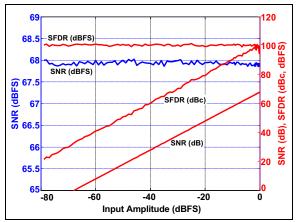


FIGURE 3-25: SNR/SFDR vs. Analog Input Amplitude: $f_S = 200$ Msps, $f_{IN} = 15$ MHz, Low-Reference Mode (SENSE = GND).

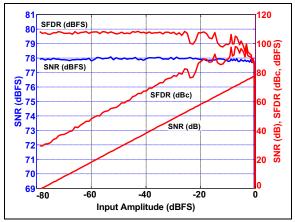


FIGURE 3-26: SNR/SFDR vs. Analog Input Amplitude: $f_S = 200$ Msps, $f_{IN} = 15$ MHz, High-Reference Mode (SENSE = AV_{DD12}) with NSR enabled. $A_{IN} \le 0.8$ dBFS for NSR.

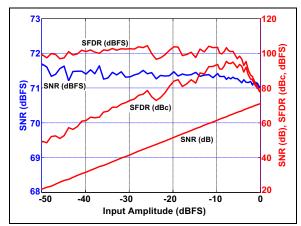


FIGURE 3-27: SNR/SFDR vs. Analog Input Amplitude: $f_S = 200$ Msps, $f_{IN} = 70$ MHz, High-Reference Mode (SENSE = AV_{DD12}).

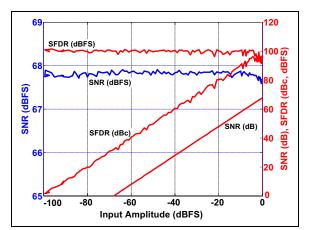


FIGURE 3-28: SNR/SFDR vs. Analog Input Amplitude: $f_S = 200$ Msps, $f_{IN} = 70$ MHz, Low-Reference Mode (SENSE = GND).

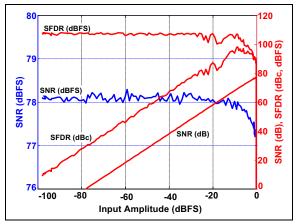


FIGURE 3-29: SNR/SFDR vs. Analog Input Amplitude: $f_S = 200$ Msps, $f_{IN} = 70$ MHz, High-Reference Mode (SENSE = AV_{DD12}) with NSR enabled. $A_{IN} \le 0.8$ dBFS for NSR.

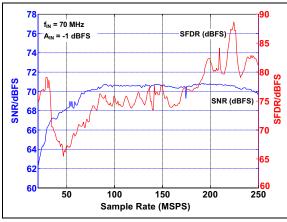


FIGURE 3-30: SNR/SFDR vs. Sample Rate (Msps): $f_{IN} = 70$ MHz.

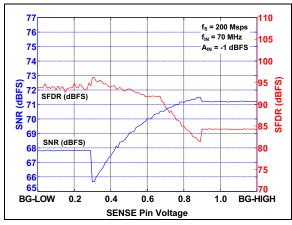


FIGURE 3-31: SNR/SFDR vs. SENSE Pin Voltage: $f_S = 200$ Msps, $f_{IN} = 70$ MHz.

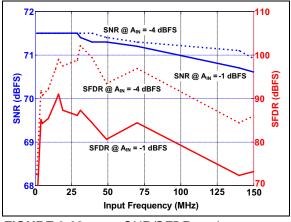


FIGURE 3-32: SNR/SFDR vs. Input Frequency.

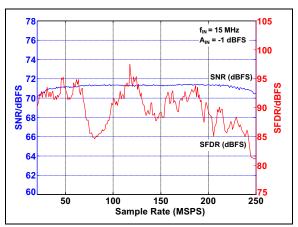


FIGURE 3-33: SNR/SFDR vs. Sample Rate (Msps): $f_{IN} = 15$ MHz.

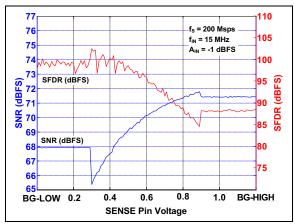


FIGURE 3-34: SNR/SFDR vs. SENSE Pin Voltage: $f_S = 200$ Msps, $f_{IN} = 15$ MHz.

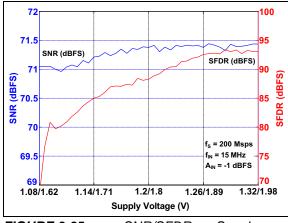


FIGURE 3-35: SNR/SFDR vs. Supply Voltage: $f_S = 200$ Msps, $f_{IN} = 15$ MHz.

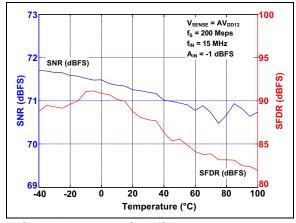


FIGURE 3-36: SNR/SFDR vs. Temperature: $f_S = 200$ Msps, $f_{IN} = 15$ MHz.

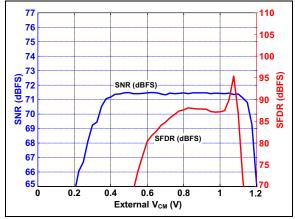


FIGURE 3-37: SNR/SFDR vs. V_{CM} Voltage (Externally Applied): $f_S = 200$ Msps, $f_{IN} = 15$ MHz.

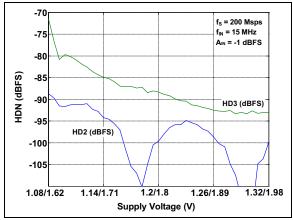
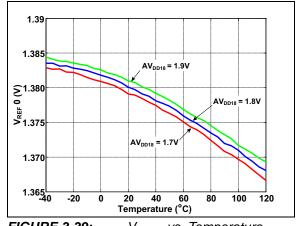


FIGURE 3-38: HD2/HD3 vs. Supply Voltage: $f_S = 200$ Msps, $f_{IN} = 15$ MHz.





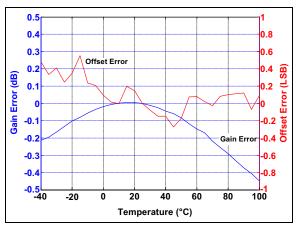


FIGURE 3-40: Gain and Offset Error Drifts vs. Temperature Using Internal Reference, with Respect to 25° C: $f_{S} = 200$ Msps.

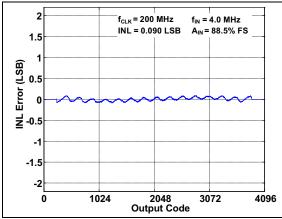


FIGURE 3-41: INL Error vs. Output Code: $f_S = 200 \text{ Msps}, f_{IN} = 4 \text{ MHz}.$

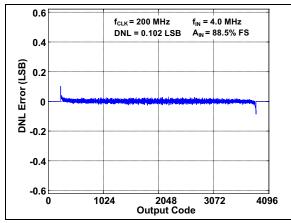
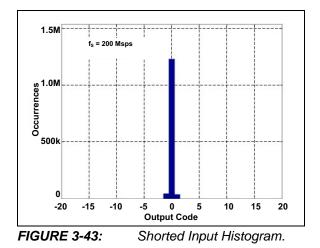
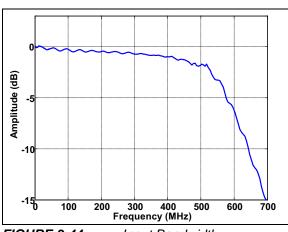


FIGURE 3-42: DNL Error vs. Output Code: $f_S = 200 \text{ Msps}, f_{IN} = 4 \text{ MHz}.$







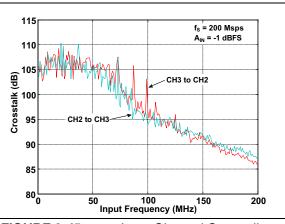


FIGURE 3-45: Input Channel Crosstalk.

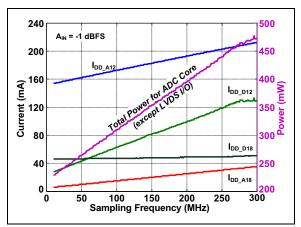


FIGURE 3-46: Power Consumption vs. Sampling Frequency (LVDS Mode).

4.0 THEORY OF OPERATION

The MCP37211-200 and MCP37D11-200 device family is a low-power, 12-bit, 200 Msps Analog-to-Digital Converter (ADC) with built-in features including Harmonic Distortion Correction (HDC), DAC Noise Cancellation (DNC), Dynamic Element Matching (DEM) and flash error calibration.

The devices offer various built-in digital signal postprocessing features. Both the MCP37211-200 and MCP37D11-200 offer high-order FIR digital decimation filters, noise-shaping requantizer (NSR), gain and offset adjustment per channel and fractional delay recovery (FDR). The MCP37D11-200 includes additional features such as digital down-conversion (DDC) and CW beamforming capability. These built-in advanced digital signal post-processing sub-blocks, which are individually controlled using Configuration register bit settings, can be used for various special applications such as I/Q demodulation, digital downconversion and ultrasound imaging.

When the device is first powered-up, it performs internal calibrations by itself and runs with default settings. From this point, the user can configure the device registers using the SPI command.

In multi-channel mode, the input channel selection and MUX scan order are user-configurable, and the inputs are sequentially multiplexed by the input MUX defined by the scan order.

The device samples the analog input on the rising edge of the clock. The digital output code is available after 28 clock cycles of data latency. Latency will increase if any of the various digital signal post-processing (DSPP) options are enabled.

The output data can be coded in two's complement or offset binary format, and randomized using the user option. Data can be output using either the CMOS or LVDS (Low-Voltage Differential Signaling) interface.

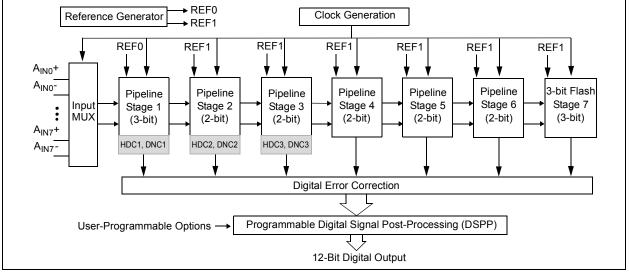
4.1 ADC Core Architecture

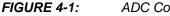
Figure 4-1 shows the simplified block diagram of the ADC core. The first stage consists of a 17-level flash ADC, multi-level Digital-to-Analog Converter (DAC) and a residue amplifier with a gain of 8. Stages 2 to 6 consist of a 9-level (3-bit) flash ADC, multi-level DAC and a residue amplifier with a gain of 4. The last stage is a 9-level 3-bit flash ADC. Dither is added in each of the first three stages. The digital outputs from all seven stages are combined in a digital error correction logic block and digitally processed for the final output.

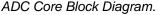
The first three stages include patented digital calibration features:

- Harmonic Distortion Correction (HDC) algorithm that digitally measures and cancels ADC errors arising from distortions introduced by the residue amplifiers
- DAC Noise Cancellation (DNC) algorithm that corrects DAC's nonlinearity errors
- Dynamic Element Matching (DEM) which randomizes DAC errors, thereby converting harmonic distortion to white noise

These digital correction algorithms are first applied during the Power-on Reset sequence and then operate in the background during normal operation of the pipelined ADC. These algorithms automatically track and correct any environmental changes in the ADC. More details of the system correction algorithms are shown in Section 4.13 "System Calibration".







4.2 Supply Voltage (DV_{DD}, AV_{DD}, GND)

The device operates from two sets of supplies and a common ground:

- Digital Supplies (DV_DD) for the digital section: 1.8V and 1.2V
- Analog Supplies (AV_{DD}) for the analog section: 1.8V and 1.2V
- Ground (GND): Common ground for both digital and analog sections.

The supply pins require an appropriate bypass capacitor (ceramic) to attenuate the high-frequency noise present in most application environments. The ground pins provide the current return path. These ground pins must connect to the ground plane of the PCB through a low-impedance connection. A ferrite bead can be used to separate analog and digital supply lines if a common power supply is used for both analog and digital sections.

The voltage regulators for each supply need to have sufficient output current capabilities to support a stable ADC operation.

4.3 Input Sample Rate

In single-channel mode, the device samples the input at full speed. In multi-channel mode, the core ADC is multiplexed between the selected channels. The resulting effective sample rate per channel is shown in Equation 4-1.

For example, with 200 Msps operation, the input is sampled at the full 200 Msps rate if a single channel is used, or at 25 Msps per channel if all eight channels are used.

EQUATION 4-1: SAMPLE RATE PER CHANNEL

Sample Rate/Channel= Full ADC Sample Rate(fs) Number of Channel Used

4.4 Analog Input Channel Selection

The analog input is auto-multiplexed sequentially as defined by the channel-order selection bit setting. The user can configure the input MUX using the following registers:

- SEL_NCH<2:0> in Address 0x01 (Register 5-2): Select the total number of input channels to be used.
- Addresses 0x7D 0x7F (Registers 5-38–5-40): Select auto-scan channel order.

The user can select up to eight input channels. If all eight input channels are to be used, SEL_NCH<2:0> is set to 000 and the input channel sampling order is set using Addresses 0x7D - 0x7F (Registers 5-38–5-40).

Regardless of how many channels are selected, all eight channels must be programmed in Addresses 0x7D - 0x7F (Registers 5-38–5-40) without duplication. Program the addresses of the selected channels in sequential order, followed by the unused channels. The order of the unused channels has no effect. The device samples the first N-Channels listed in Addresses 0x7D - 0x7F (Registers 5-38–5-40) sequentially, where N is the total number of channels to be used, defined by the SEL_NCH<2:0>. Table 4-1 shows examples of input channel selection using Addresses 0x7D - 0x7F (Registers 5-38–5-40).

No. of Channels (1)	Selected Channels	Channel Order ⁽²⁾	Address 0x7F						Address 0x7E							Address 0x7D										
			b 7							b 0	b 7							b 0	b 7							b 0
			Channel Order Bit Settings												·											
			5th Ch.		5th Ch. 4th Ch. 6th			h C	Ch. 3rd Ch.			h.	7th Ch.		h.	2nd Ch.		ĥ.	8th Ch.		h.	1st Ch		۱.		
8	[0 1 2 3 4 5 6 7]	[0 1 2 3 4 5 6 7] (Default)	1	0	0	0	1	1	1	0	1	0	1	0	1	1	0	0	0	1	1	1	1	0	0	0
-	[7 6 5 4 3 2 1 0]	[7 6 5 4 3 2 1 0]	0	1	1	1	0	0	0	1	0	1	0	1	0	0	1	1	1	0	0	0	0	1	1	1
	[0 2 4 6 1 3 5 7]	[0 2 4 6 1 3 5 7]	0	0	1	1	1	0	0	1	1	1	0	0	1	0	1	0	1	0	1	1	1	0	0	0
	[1 3 5 7 0 2 4 6]	[1 3 5 7 0 2 4 6]	0	0	0	1	1	1	0	1	0	1	0	1	1	0	0	0	1	1	1	1	0	0	0	1
								•				С	har	nne	101	rde	r Bi	t So	etti	ngs	;					
7			Uı	านร	ed	4t	h C	h.	5t	5th Ch.		3rd Ch.		h.	6th Ch.		h.	2nd Ch.		h.	7th Ch.		h.	1st Ch		ı.
7	[0 1 2 3 4 5 6]	[0 1 2 3 4 5 6 7]	1	1	1	0	1	1	1	0	0	0	1	0	1	0	1	0	0	1	1	1	0	0	0	0
	[0 2 4 6 1 3 5]	[0 2 4 6 1 3 5 7]	1	1	1	1	1	0	0	0	1	1	0	0	0	1	1	0	1	0	1	0	1	0	0	0

Note 1: Defined by SEL_NCH<2:0> in Address 0x01 (Register 5-2).

2: Individual channel order should not be repeated. Unused channels are still assigned after the selected channel address. The order of the unused channel addresses has no meaning since they are not used.

TABLE 4-1	EXAMF	PLE: CHANN	EL	OF	RDE	ER	SE	LE	СТ	ION	I U	SIN	IG	AD	DF	RES	SE	S ()X7	7D	- 0	X7	F			
No. of Channels (1)	Selected Channels	Channel Order ⁽²⁾			Adc	Ires	ss ()x7I	=			Address 0x7E				Address 0x7D										
			b 7							b 0	b 7							b 0	b 7							b 0
			'							U	1	С	har	nne		rdei	r Bi		-	nas	L					0
			Ur	านร	ed	Ur	านร	ed	4t	h C	h.		d C		-	h C			d C			h C	h.	1s	t C	h.
6	[0 1 2 3 4 5]	[0 1 2 3 4 5 6 7]	1	1	1	1	1	0	0	1	1	0	1	0	1	0	0	0	0	1	1	0	1	0	0	0
	[0 2 4 6 1 3]	[0 2 4 6 1 3 5 7]	1	1	1	1	0	1	1	1	0	1	0	0	0	0	1	0	1	0	0	1	1	0	0	0
		1			1		I					С	har	nne	10	rdei	r Bi	t Se	etti	ngs	5					
F			Ur	านร	ed	Ur	านร	ed	Ur	านร	ed	3r	d C	h.	4t	h C	h.	2 n	d C	ch.	5t	h C	h.	1s	t C	h.
5	[0 1 2 3 4]	[0 1 2 3 4 5 6 7]	1	1	0	1	0	1	1	1	1	0	1	0	0	1	1	0	0	1	1	0	0	0	0	0
	[0 2 4 6 1]	[0 2 4 6 1 3 5 7]	1	0	1	0	1	1	1	1	1	1	0	0	1	1	0	0	1	0	0	0	1	0	0	0
					•		•			•	•	С	har	nne	10	rdei	r Bi	t So	etti	ngs	6					
			Ur	านร	ed	Ur	านร	ed	Ur	านร	ed	Ur	านร	ed	3r	d C	h.	2n	nd C	h.	4t	h C	h.	1s	t C	h.
4	[0 1 2 3]	[0 1 2 3 4 5 6 7]	1	1	0	1	0	1	1	1	1	1	0	0	0	1	0	0	0	1	0	1	1	0	0	0
т	[4 5 6 7]	[4 5 6 7 0 1 2 3]	0	1	0	0	0	1	0	1	1	0	0	0	1	1	0	1	0	1	1	1	1	1	0	0
	[0 2 4 6]	[0 2 4 6 1 3 5 7]	1	0	1	0	1	1	1	1	1	0	0	1	1	0	0	0	1	0	1	1	0	0	0	0
	[1 3 5 7]	[1 3 5 7 0 2 4 6]	1	0	0	0	1	0	1	1	0	0	0	0	1	0	1	0	1	1	1	1	1	0	0	1
						_								nne						-				_		
3		T	Ur	านร	ed	Ur	านร	ed		านร	ed	Ur	-	ed		านร	ed	2n	d C	ch.	3r	d C	h.	1s	t C	h.
-	[0 1 2]	[0 1 2 3 4 5 6 7]	1	0	1	1	0	0	1	1	0	0	1	1	1	1	1	0	0	1	0	1	0	0	0	0
	[0 2 4]	[0 2 4 6 1 3 5 7]	0	1	1	0	0	1	1	0	1	1	1	0	1	1	1	0	1	0	1	0	0	0	0	0
											-			nne				_			-					
				านร			านร	1		านร			-	ed		านร	1		านร	r		nd C		1	t C	
2	[0 1]	[0 1 2 3 4 5 6 7]	1	0	1	1	0	0	1	1	0	0	1	1	1	1	1	0	1	0	0	0	1	0	0	0
	[2 3]	[2 3 0 1 4 5 6 7]	1	0	1	1	0	0	1	1	0	0	0	1	1	1	1	0	0	0	0	1	1	0	1	0
	[4 5]	[45012367]	0	1	1	0	1	0	1	1	0	0	0	1	1	0	1	0	0	0	1	0	1	1	0	0
	[6 7]	[6 7 0 1 2 3 4 5]	0	1	1	0	1	0	1	0	0	0	0	⊥ nne∣	1	0	1	0	0	0		1	Ţ	1	1	0
			110		od	11,		ed	11,		od									<u> </u>			od	10	t C	h
	[0]	[0 1 2 3 4 5 6 7]																								
	[1]	[10234567]	1	0	0	0	1	1	1	0	1	0	1	0	1	1	0		0		1	1	1	0	0	1
	[2]	[20134567]	1	0	0	0	1	1	1	0	1	0	0	1	1	1	0		0		1	1	1	0	1	-
1	[3]	[30124567]	1	0	0	0	1	0	1	0	1	0	0	1	1	1	0	0	0	0	1	1	1	0	1	1
	[4]	[40123567]	1	1	1	0	1	0	1	0	1	0	0	1	1	1	0	0	0	0	1	1	1	1	0	0
	[5]	[50123467]	0	1	1	0	1	0	1	0	0	0	0	1	1	1	0	0	0	0	1	1	1	1	0	1
	[6]	[6 0 1 2 3 4 5 7]	0	1	1	0	1	0	1	0	0	0	0	1	1	0	1	0	0	0	1	1	1	1	1	0
	[7]	[7 0 1 2 3 4 5 6]	0	1	1	0	1	0	1	0	0	0	0	1	1	0	1	0	0	0	1	1	0	1	1	1
			I	I	I		1	1		I	L		I			I			I	1		1	I			

Note 1: Defined by SEL_NCH<2:0> in Address 0x01 (Register 5-2).

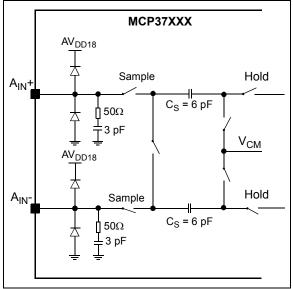
2: Individual channel order should not be repeated. Unused channels are still assigned after the selected channel address. The order of the unused channel addresses has no meaning since they are not used.

4.5 Analog Input Circuit

The analog input (A_{IN}) of all MCP37XXX devices is a differential, CMOS switched capacitor sample-and-hold circuit. Figure 4-2 shows the equivalent input structure of the device.

The input impedance of the device is mostly governed by the input sampling capacitor ($C_S = 6 \text{ pF}$) and input sampling frequency (f_S). The performance of the device can be affected by the input signal conditioning network (see Figure 4-3). The analog input signal source must have sufficiently low output impedance to charge the sampling capacitors ($C_S = 6 \text{ pF}$) within one clock cycle. A small external resistor (e.g., 5Ω) in series with each input is recommended, as it helps reduce transient currents and dampens ringing behavior. A small differential shunt capacitor at the chip side of the resistors may be used to provide dynamic charging currents and may improve performance. The resistors form a low-pass filter with the capacitor and their values must be determined by application requirements and input frequency.

The V_{CM} pin provides a common-mode voltage reference (0.9V), which can be used for a center-tap voltage of an RF transformer or balun. If the V_{CM} pin voltage is not used, the user may create a common-mode voltage at mid-supply level (AV_{DD18}/2).





Equivalent Input Circuit.

4.5.1 ANALOG INPUT DRIVING CIRCUIT4.5.1.1 Differential Input Configuration

The device achieves optimum performance when the input is driven differentially, where common-mode noise immunity and even-order harmonic rejection are significantly improved. If the input is single-ended, it must be converted to a differential signal in order to properly drive the ADC input. The differential conversion and common-mode application can be accomplished by using an RF transformer or balun with a center-tap. Additionally, one or more anti-aliasing filters may be added for optimal noise performance and should be tuned such that the corner frequency is appropriate for the system.

Figure 4-3 shows an example of the differential input circuit with transformer. Note that the input-driving circuits are terminated by 50Ω near the ADC side through a pair of 25Ω resistors from each input to the common-mode (V_{CM}) from the device. The RF transformer must be carefully selected to avoid artificially high harmonic distortion. The transformer can be damaged if a strong RF input is applied or an RF input is applied while the MCP37XXX is powered-off. The transformer has to be selected to handle sufficient RF input power.

Figure 4-4 shows an input configuration example when a differential output amplifier is used.

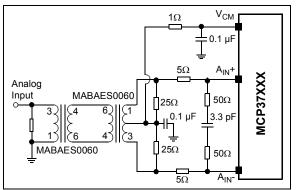
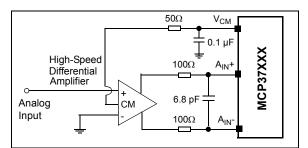
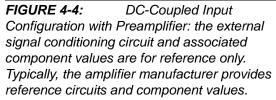


FIGURE 4-3: Transformer Coupled Input Configuration.





4.5.1.2 Single-Ended Input Configuration

Figure 4-5 shows an example of a single-ended input configuration. This single-ended input configuration is not recommended for the best performance. SNR and SFDR performance degrades significantly when the device is operated in a single-ended configuration. The unused negative side of the input should be AC-coupled to ground using a capacitor.

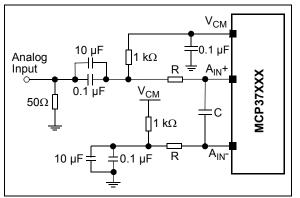


FIGURE 4-5: Configuration.

Singled-Ended Input

4.5.2 SENSE VOLTAGE AND INPUT FULL-SCALE RANGE

The device has a bandgap-based differential internal reference voltage. The SENSE pin voltage is used to select the reference voltage source and configure the input full-scale range. A comparator detects the SENSE pin voltage and configures the full-scale input range into one of the three possible modes which are summarized in Table 4-2. Figure 4-6 shows an example of how the SENSE pin should be driven.

The SENSE pin can sink or source currents as high as $500 \ \mu A$ across all operational conditions. Therefore, it may require a driver circuit, unless the SENSE reference source provides sufficient output current.

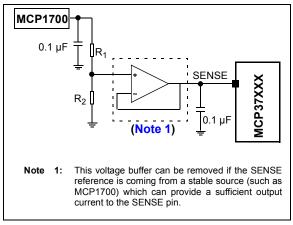


FIGURE 4-6: SENSE Pin Voltage Setup.

TABLE 4-2: SENSE PIN VOLTAGE AND INPUT FULL-SCALE RANGE

SENSE Pin Voltage (V _{SENSE})	Selected Reference Voltage (V _{REF})	Full-Scale Input Voltage Range (A _{FS})	LSb Size (Calculated with A _{FS})	Condition
Tied to GND	0.7V	1.4875 V _{P-P} ⁽¹⁾	363.16 µV	Low-Reference Mode ⁽⁴⁾
0.4V – 0.8V	0.7V – 1.4V	1.4875 V _{P-P} to 2.975 V _{P-P} ⁽²⁾	Adjustable	Sense Mode ⁽⁵⁾
Tied to AV _{DD12}	1.4875V	2.975 V _{P-P} ⁽³⁾	726.32 μV	High-Reference Mode ⁽⁴⁾

Note 1: $A_{FS} = (17/16) \times 1.4 V_{P-P} = 1.487 V_{P-P}$

2: $A_{FS} = (17/16) \times 2.8 V_{P-P} \times (V_{SENSE})/0.8 = 1.4875 V_{P-P}$ to 2.975 V_{P-P} .

3: A_{FS} = (17/16) x 2.8 V_{P-P} = 2.975 V_{P-P}.

4: Based on internal bandgap voltage.

5: Based on V_{SENSE}.

4.5.2.1 SENSE Selection Vs. SNR/SFDR Performance

The SENSE pin is used to configure the full-scale input range of the ADC. Depending on the application conditions, the SNR, SFDR and dynamic range performance are affected by the SENSE pin configuration. Table 4-3 summarizes these settings.

High-Reference Mode

This mode is enabled by setting the SENSE pin to AV_{DD12} (1.2V). This mode provides the highest input full-scale range (2.975 V_{P-P}) and the highest SNR performance. In this mode, the internal thermal noise is less than 1 LSb of the 12-bit ADC (726 μ V). This has the consequence of making it difficult to resolve small input signals unless some dither is added to the ADC input. In typical applications, thermal noise generated by the system driving the ADC will provide the necessary dithering effect. Figure 3-24 and Figure 3-27 show SNR/SFDR versus input amplitude in High-Reference mode.

Note:	Adding dither to the ADC has a negative					
	side effect of reducing the maximum					
	achievable SNR.					

Low-Reference Mode

This mode is enabled by setting the SENSE pin to ground. This mode is suitable for applications which have a smaller input full-scale range. This mode provides improved SFDR characteristics, but SNR is reduced by -3 dB compared to the High-Reference Mode.

SENSE Mode

This mode is enabled by driving the SENSE pin with an external voltage source between 0.4V and 0.8V. This mode allows the user to adjust the input full-scale range such that SNR and dynamic range are optimized in a given application system environment.

NSR Mode

The use of the Noise-Shaping Requantizer (NSR), further described in **Section 4.8.2** "**Noise-Shaping Requantizer (NSR)**", is best suited for applications which require a high SNR and a wide dynamic range as well as a relatively narrow bandwidth.

When the NSR is enabled, the noise level in a selected portion of the frequency band is reduced to a level below that of a conventional 12-bit ADC, while the noise level outside of this band remains significantly higher. The SNR achievable in this mode is about 78 dBFS when integrated across 50% of the Nyquist bandwidth. This is an optimum selection for applications where the full Nyquist bandwidth of the ADC is not needed, and where the digital signal post-processing of the ADC data is capable of removing the out-of-band noise added by the NSR.

Figures 3-26 and 3-29 show the SNR/SFDR versus input amplitude with NSR enabled.

SENSE	Descriptions
High-Reference Mode (SENSE pin = AV _{DD12})	High-input full-scale range (2.975 $V_{\text{P-P}})$ and optimized SNR
Low-Reference Mode (SENSE pin = ground)	Low-input full-scale range (1.4875 $V_{P\text{-}P})$ and reduced SNR, but optimized SFDR
Sense Mode (SENSE pin = 0.4V to 0.8V)	Adjustable-input full-scale range (1.4875 V _{P-P} - 2.975 V _{P-P}). Dynamic trade-off between High-Reference and Low-Reference modes can be used.
Noise-Shaping Requantizer (NSR)	Optimized SNR, but reduced usable bandwidth. NSR can be employed in any SENSE pin configuration.

TABLE 4-3: SENSE VS. SNR/SFDR PERFORMANCE

4.5.3 DECOUPLING CIRCUITS FOR INTERNAL VOLTAGE REFERENCE AND BANDGAP OUTPUT

4.5.3.1 Decoupling Circuits for REF1 and REF0 Pins

The device has two internal voltage references, and these references are available at pins REF0 and REF1. REF0 is the internal voltage reference for the ADC input stage, while REF1 is for all remaining stages.

VTLA-124 Package Device: Figure 4-7 shows the recommended circuit for the REF1 and REF0 pins for the VTLA-124 package. Placing a 2.2 μ F ceramic capacitor with two additional optional capacitors (22 nF and 220 nF) between the positive and negative reference pins is recommended. The negative reference pin is then grounded through a 220 nF capacitor. The capacitors should be placed as close to the ADC as possible with short and thick traces. Vias on the PCB are not recommended for this reference pin circuit.

TFBGA-121 Package Device: The decoupling capacitor is embedded in the package. Therefore, no external circuit is required on the PCB.

4.5.3.2 Decoupling Circuit for V_{BG} Pin

The bandgap circuit is a part of the reference circuit and the output is available at the $\rm V_{BG}$ pin.

VTLA-124 Package Device: V_{BG} pin needs an external decoupling capacitor (2.2 μ F) as shown in Figure 4-7.

TFBGA-121 Package Device: The decoupling capacitor is embedded in the package. Therefore, no external circuit is required on the PCB.

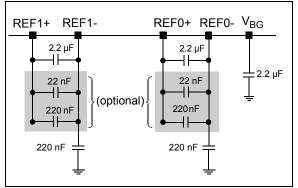


FIGURE 4-7:External Circuit for VoltageReference and V_{BG} pins for the VTLA-124Package. Note that this external circuit is notrequired for the TFBGA-121 package.

4.6 External Clock Input

For optimum performance, the MCP37XXX requires a low-jitter differential clock input at the CLK+ and CLK- pins. Figure 4-8 shows the equivalent clock input circuit.

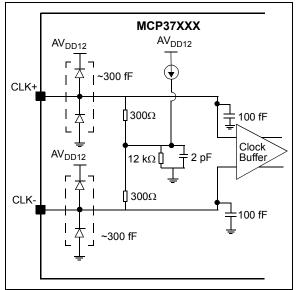


FIGURE 4-8: Equivalent Clock Input Circuit.

The clock input amplitude range is between 300 mV_{P-P} and 800 mV_{P-P}. When a single-ended clock source is used, an RF transformer or balun can be used to convert the clock into a differential signal for the best ADC performance. Figure 4-9 shows an example clock input circuit. The common-mode voltage is internally generated and a center-tap is not required. The back-to-back Schottky diodes across the transformer's secondary current limit the clock amplitude to approximately 0.8 V_{P-P} differential. This limiter helps prevent large voltage swings of the input clock while preserving the high slew rate that is critical for low jitter.

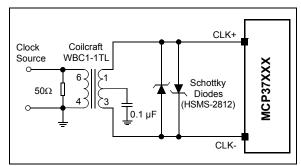


FIGURE 4-9: Transformer-Coupled Differential Clock Input Configuration.

4.6.1 CLOCK JITTER AND SNR PERFORMANCE

In a high-speed pipelined ADC, the SNR performance is directly limited by thermal noise and clock jitter. Thermal noise is independent of input clock and dominant term at low-input frequency. On the other hand, the clock jitter becomes a dominant term as input frequency increases. Equation 4-2 shows the SNR jitter component, which is expressed in terms of the input frequency ($f_{\rm IN}$) and the total amount of clock jitter ($T_{\rm Jitter}$), where $T_{\rm Jitter}$ is a sum of the following two components:

- Input clock jitter (phase noise)
- Internal aperture jitter (due to noise of the clock input buffer).

EQUATION 4-2: SNR VS.CLOCK JITTER

 $SNR_{Jitter}(dBc) = -20 \times log_{10}(2\pi \times f_{IN} \times T_{Jitter})$

where the total jitter term (T_{jitter}) is given by:

$$T_{Jitter} = \sqrt{\left(t_{Jitter, Clock Input}\right)^2 + \left(t_{Aperture, ADC}\right)^2}$$

The clock jitter can be minimized by using a highquality clock source and jitter cleaners as well as a band-pass filter at the external clock input, while a faster clock slew rate improves the ADC aperture jitter.

With a fixed amount of clock jitter, the SNR degrades as the input frequency increases. This is illustrated in Figure 4-10. If the input frequency increases from 10 MHz to 20 MHz, the maximum achievable SNR degrades about 6 dB. For every decade (e.g. 10 MHz to 100 MHz), the maximum achievable SNR due to clock jitter is reduced by 20 dB.

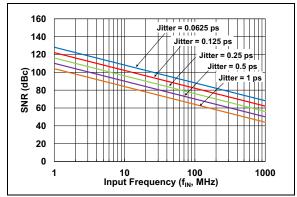


FIGURE 4-10: SNR vs. Clock Jitter.

4.7 ADC Clock Selection

This section describes the ADC clock selection and how to use the built-in Delay-Locked Loop (DLL) and Phase-Locked Loop (PLL) blocks.

When the device is first powered-up, the external clock input (CLK+/-) is directly used for the ADC timing as default. After this point, the user can enable the DLL or PLL circuit by setting the register bits. Figure 4-11 shows the clock control blocks. Table 4-4 shows an example of how to select the ADC clock depending on the operating conditions.

		Fea		
Operating Conditions	Control Bit Settings ⁽¹⁾	Input Clock Duty Cycle Correction	DCLK Output Phase Delay Control	
CLI				
 DLL output is not used Decimation is not used (Default)⁽³⁾ 	EN_DLL = 0 EN_DLL_DCLK = 0 EN_PHDLY = 0	Not Available	Not Available	
	EN_DLL = 1 EN_DLL_DCLK = 0 EN_PHDLY = 0	Available		
DLL output is usedDecimation is not used	EN_DLL = 1 EN_DLL_DCLK = 1 EN_PHDLY = 1	Available	Available	
 DLL output is not used Decimation is used⁽⁴⁾ 	EN_DLL = 0 EN_DLL_DCLK = X EN_PHDLY = 1	Not Available		
	EN_DLL = 1 EN_DLL_DCLK = 0 EN_PHDLY = 1	Available		
	CLK_SOURCE = 1 ⁽⁵⁾			
 Decimation is not used 	EN_DLL = X EN_DLL_DCLK = X EN_PHDLY = 0	Not Available	Available	
 Decimation is used⁽⁴⁾ 	EN_DLL = X EN_DLL_DCLK = X EN_PHDLY = 1			

TABLE 4-4: ADC CLOCK SELECTION (EXAMPLE)

Note 1: See Addresses 0x52, 0x53, and 0x64 for bit settings.

2: The sampling frequency (f_S) of the ADC core comes directly from the input clock buffer

3: Output data is synchronized with the output data clock (DCLK), which comes directly from the input clock buffer.

4: While using decimation, output clock rate and phase delay are controlled by the digital clock output control block

5: The sampling frequency (f_S) is generated by the PLL circuit. The external clock input is used as the reference input clock for the PLL block.

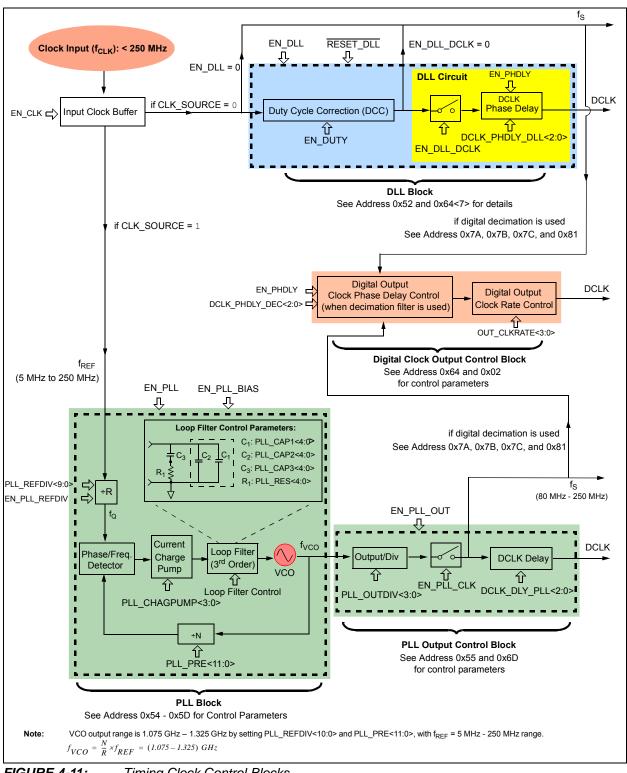


FIGURE 4-11: Timing Clock Control Blocks.

4.7.1 USING DLL MODE

Using the DLL block is the best option when output clock phase control is needed while the clock multiplication and digital decimation are not required. When the DLL block is enabled, the user can control the input clock Duty Cycle Correction (DCC) and the output clock phase delay.

See the DLL block in Figure 4-11 for details. Table 4-5 summarizes the DLL control register bits. In addition, see Table 4-24 for the output clock phase control.

TABLE 4-5: DLL CONTROL REGISTER BITS

Control Parameter	Register	Descriptions
CLK_SOURCE	0x53	CLK_SOURCE = 0: external clock input becomes input of the DLL block
EN_DUTY	0x52	Input clock duty cycle correction control bit ⁽¹⁾
EN_DLL	0x52	EN_DLL = 1: enable DLL block
EN_DLL_DCLK	0x52	DLL output clock enable bit
EN_PHDLY<2:0>	0x52	Phase delay control bits of digital output clock (DCLK) when DLL or decimation filter is used ⁽²⁾
RESET_DLL	0x52	Reset control bit for the DLL block

Note 1: Duty cycle correction is not recommended when a high-quality external clock is used.

2: If decimation is used, the output clock phase delay is controlled using DCLK_PHDLY_DEC<2:0> in Address 0x64.

4.7.1.1 Input Clock Duty Cycle Correction

The ADC performance is sensitive to the clock duty cycle. The ADC achieves optimum performance with 50% duty cycle, and all performance characteristics are ensured when the duty cycle is 50% with \pm 1% tolerance.

When CLK_SOURCE = 0, the external clock is used as the sampling frequency (f_S) of the ADC core. When the external input clock is not high-quality (for example, duty cycle is not 50%), the user can enable the internal clock duty cycle correction circuit by setting the EN_DUTY bit in Address 0x52 (Register 5-7). When duty cycle correction is enabled (EN_DUTY=1), only the falling edge of the clock signal is modified (rising edge is unaffected).

Because the duty cycle correction process adds additional jitter noise to the clock signal, this option is recommended only when an asymmetrical input clock source causes significant performance degradation or when the input clock source is not stable.

Note: The clock duty cycle correction is only applicable when the DLL block is enabled (EN_DLL = 1). It is not applicable for the PLL output.

4.7.1.2 DLL Block Reset Event

The DLL must be reset if the clock frequency is changed. The DLL reset is controlled by using the RESET_DLL bit in Address 0x52 (Register 5-7). The DLL has an automatic reset with the following events:

- During power-up: Stay in reset until the RESET_DLL bit is cleared.
- When a SOFT_RESET command is issued while the DLL is enabled: the RESET_DLL bit is automatically cleared after reset.

4.7.2 USING PLL MODE

The PLL block is mainly used when clock multiplication is needed. When CLK_SOURCE = 1, the sampling frequency (f_S) of the ADC core is coming from the internal PLL block.

The recommended PLL output clock range is from 80 MHz to 250 MHz. The external clock input is used as the PLL reference frequency. The range of the clock input frequency is from 5 MHz to 250 MHz.

Note:	The PLL mode is only supported for
	sampling frequencies between 80 MHz
	and 250 MHz.

4.7.2.1 PLL Output Frequency and Output Control Parameters

The internal PLL can provide a stable timing output ranging from 80 MHz to 250 MHz. Figure 4-11 shows the PLL block using a charge-pump-based integer N PLL and the PLL output control block. The PLL block includes various user control parameters for the desired output frequency. Table 4-6 summarizes the PLL control register bits and Table 4-7 shows an example of register bit settings for the PLL charge pump and loop filter.

The PLL block consists of:

- Reference Frequency Divider (R)
- Prescaler which is a feedback divider (N)
- Phase/Frequency Detector (PFD)
- Current Charge Pump
- Loop Filter a 3rd order RC low-pass filter
- Voltage-Controlled Oscillator (VCO)

The external clock at the CLK+ and CLK- pins is the input frequency to the PLL. The range of input frequency (f_{REF}) is from 5 MHz to 250 MHz. This input frequency is divided by the reference frequency divider (R) which is controlled by the 10-bit-wide PLL_REFDIV<9:0> setting. In the feedback loop, the VCO frequency is divided by the prescaler (N) using PLL_PRE<11:0>.

The ADC core sampling frequency (f_S), ranging from 80 MHz to 250 MHz, is obtained after the output frequency divider (PLL_OUTDIV<3:0>). For stable operation, the user needs to configure the PLL with the following limits:

- Input clock frequency (f_{REF}) = 5 MHz to 250 MHz
- Charge pump input frequency = 4 MHz to 50 MHz (after PLL reference divider)
- VCO output frequency = 1.075 to1.325 GHz
- PLL output frequency after = 80 MHz to 250 MHz output divider

The charge pump is controlled by the PFD, and forces sink (DOWN) or source (UP) current pulses onto the loop filter. The charge pump bias current is controlled by the PLL_CHAGPUMP<3:0> bits, approximately 25 μ A per step. The loop filter consists of a 3rd order passive RC filter. Table 4-7 shows the recommended

settings of the charge pump and loop filter parameters, depending on the charge pump input frequency range (output of the reference frequency divider).

When the PLL is locked, it tracks the input frequency (f_{REF}) with the ratio of dividers (N/R). The PLL operating status is monitored by the PLL status indication bits: <PLL_VCOL_STAT> and <PLL_VCOH_STAT> in Address 0xD1 (Register 5-81).

Equation 4-3 shows the VCO output frequency (f_{VCO}) as a function of the two dividers and reference frequency:

EQUATION 4-3: VCO OUTPUT FREQUENCY

$$f_{VCO} = \left(\frac{N}{R}\right) f_{REF} = 1.075 \ (GHz) \ to \ 1.325 \ (GHz)$$

Where:

N = 1 to 4095 controlled by PLL_PRE<11:0>

R = 1 to 1023 controlled by PLL_REFDIV<9:0>

See Addresses 0x54 to 0x57 (Registers 5-9 – 5-12) for these bits settings.

The tuning range of the VCO is 1.075 GHz to 1.325 GHz. N and R values must be chosen so the VCO is within this range. In general, lower values of the VCO frequency (f_{VCO}) and higher values of the charge pump frequency (f_Q) should be chosen to optimize the clock jitter. Once the VCO output frequency is determined to be within this range, set the final ADC sampling frequency (f_S) with the PLL output divider using PLL_OUTDIV<3:0>. Equation 4-4 shows how to obtain the ADC core sampling frequency:

EQUATION 4-4: SAMPLING FREQUENCY

$$f_{S} = \left(\frac{f_{VCO}}{PLL_OUTDIV}\right) = 80 \text{ MHz to } 250 \text{ MHz}$$

Table 4-8showsanexampleofgenerating $f_S = 200$ MHz output using the PLL control parameters.

4.7.2.2 PLL Calibration

The PLL should be recalibrated following a change in clock input frequency or in the PLL Configuration register bit settings (Addresses 0x54 - 0x57; Registers 5-9 - 5-12).

The PLL can be calibrated by toggling the PLL_-CAL_TRIG <u>bit in Address</u> 0x6B (Register 5-27) or by sending a SOFT_RESET command (See Address 0x00, Register 5-1). The PLL calibration status is observed by the PLL_CAL_STAT bit in Address 0xD1 (Register 5-81).

4.7.2.3 Monitoring of PLL Drifts

The PLL drifts can be monitored using the status monitoring bits in Address 0xD1 (Register 5-81). Under normal operation, the PLL maintains a lock across all temperature ranges. It is not necessary to actively monitor the PLL unless extreme variations in the supply voltage are expected or if the input reference clock frequency has been changed.

TABLE 4-0. FLL CON		
Control Parameter	Register	Descriptions
PLL Global Control Bits		
EN_PLL	0x59	Master enable bit for the PLL circuit
EN_PLL_OUT	0x5F	Master enable bit for the PLL output
EN_PLL_BIAS	0x5F	Master enable bit for the PLL bias
EN_PLL_REFDIV	0x59	Master enable bit for the PLL reference divider
PLL Block Setting Bits		
PLL_REFDIV<9:0>	0x54-0x55	PLL reference divider (R) (See Table 4-8)
PLL_PRE<11:0>	0x56-0x57	PLL prescaler (N) (See Table 4-8)
PLL_CHAGPUMP<3:0>	0x58	PLL charge pump bias current control: from 25 μA to 375 $\mu A,$ 25 μA per step
PLL_RES<4:0>	0x5A	PLL loop filter resistor value selection (See Table 4-7)
PLL_CAP3<4:0>	0x5B	PLL loop filter capacitor 3 value selection (See Table 4-7)
PLL_CAP2<4:0>	0x5D	PLL loop filter capacitor 2 value selection (See Table 4-7)
PLL_CAP1<4:0>	0x5C	PLL loop filter capacitor 1 value selection (See Table 4-7)
PLL Output Control Bits		
PLL_OUTDIV<3:0>	0x55	PLL output divider (See Table 4-8)
DCLK_DLY_PLL<2:0>	0x6D	Delay DCLK output up to 15 cycles of VCO clocks
EN_PLL_CLK	0x6D	EN_PLL_CLK = 1 enable PLL output clock to the ADC circuits
PLL Drift Monitoring Bits		
PLL_VCOL_STAT	0xD1	PLL drift status monitoring bit
PLL_VCOH_STAT	0xD1	PLL drift status monitoring bit
PLL Block Calibration Bits	;	
PLL_CAL_TRIG	0x6B	Forcing recalibration of the PLL
SOFT_RESET	0x00	PLL is calibrated when exiting soft reset mode
PLL_CAL_STAT	0xD1	PLL auto-calibration status indication

TABLE 4-6:PLL CONTROL REGISTER BITS

TABLE 4-7: RECOMMENDED PLL CHARGE PUMP AND LOOP FILTER BIT SETTINGS

PLL Charge Pump and Loop Filter	f _Q = f _{REF} /PLL_REFDIV							
Parameter	f _Q <5 MHz	5 MHz ≤ f _Q < 25 MHz	f _Q ≥ 25 MHz					
PLL_CHAGPUMP<3:0>	0x04	0x04	0x04					
PLL_RES<4:0>	0x1F	0x1F	0x07					
PLL_CAP3<4:0>	0x07	0x02	0x07					
PLL_CAP2<4:0>	0x07	0x01	0x08					
PLL_CAP1<4:0>	0x07	0x01	0x08					

TABLE 4-8:EXAMPLE OF PLL CONTROL BIT SETTINGS FOR $f_S = 200$ MHz WITH $f_{REF} = 100$ MHz

		0 (12)
PLL Control Parameter	Value	Descriptions
f _{REF}	100 MHz	f _{REF} is coming from the external clock input
Target f _S ⁽¹⁾	200 MHz	ADC sampling frequency
Target f _{VCO} ⁽²⁾	1.2 GHz	Range of f _{VCO} = 1.0375 GHz – 1.325 GHz
Target f _Q ⁽³⁾	10 MHz	f _Q = f _{REF} /PLL_REFDIV (See Table 4-7)
PLL Reference Divider (R)	10	PLL_REFDIV<9:0> = 0x0A
PLL Prescaler (N)	120	PLL_PRE<11:0> = 0x78
PLL Output Divider	6	PLL_OUTDIV<3:0> = 0x06

Note 1: $f_S = f_{VCO}/PLL_OUTDIV = 1.2 \text{ GHz}/6 = 200 \text{ MHz}$

2: $f_{VCO} = (N/R) \times f_{REF} = (12) \times 100 \text{ MHz} = 1.2 \text{ GHz}$

3: f_Q should be maximized for the best noise performance.

4.8 Digital Signal Post-Processing (DSPP) Options

While the device converts the analog input signals to digital output codes, the user can enable various digital signal post-processing (DSPP) options for special applications. These options are individually enabled or disabled by setting the Configuration bits. Table 4-9 summarizes the digital signal post-processing (DSPP) options that are available for each device family.

TABLE 4-9: DIGITAL SIGNAL POST PROCESSING (DSPP) OPTIONS

Digital Signal Post Processing Option	Available Operating Mode	Offering Device		
Fractional Delay Recovery (FDR)	Dual and octal-channel modes			
FIR Decimation Filters	Single and dual-channel modes			
	CW octal-channel mode	MCP37211-200		
	DDC for I and Q data			
Noise-Shaping Requantizer (NSR)	Single and dual-channel modes	-		
Digital Gain and Offset correction per channel	Available for all channels			
Digital-Down Conversion (DDC)	Single and dual-channel modes			
	CW octal-channel mode	MCP37D11-200		
Continuous Wave (CW) Beamforming	CW octal-channel mode			

4.8.1 FRACTIONAL DELAY RECOVERY FOR DUAL- AND OCTAL-CHANNEL MODES

The FDR feature is available in dual and octal-channel modes only. When FDR is enabled, the built-in highorder, band-limited interpolation filter compensates for the time delay between input samples of different channels. Due to the finite bandwidth of the interpolation filter, the fractional delay recovery is not guaranteed for input frequencies near the Nyquist frequency $(f_{S}/2)$. For example, in dual-channel mode, FDR can operate correctly for input frequencies in the range from 0 to 0.45*f_S (or from 0.55*fs to f_S if the input is in the 2nd Nyquist band). In octal-channel mode, FDR can operate correctly for input frequencies in the range from 0 to 0.38*f_S. See Table 4-11 for the summary of the input bandwidth requirement for FDR. The FDR process takes place in the digital domain and requires 59 clock cycles of processing time. Therefore, the output data latency is also increased by 59 clock periods.

Figure 4-12 shows the simplified block diagram for the ADC output data path with FDR. The related Configuration register bits are listed in Table 4-10. Table 4-11 shows the input bandwidth limits of the FDR feature for distortion less than 0.1 mdB (0.1×10^{-3} dB), where f_S is the sampling frequency per channel. Figures 4-13 and 4-14 show the responses of the dual-channel and octal-channel FDRs, respectively.

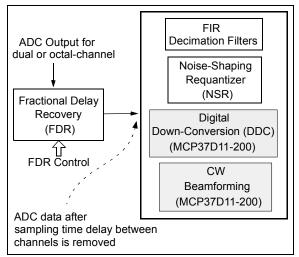


FIGURE 4-12: Simplified Block Diagram for ADC Output Data Path with Fractional Delay Recovery Option. Note that Fractional Delay Recovery occurs prior to other DSPP features.

TABLE 4-10: CONTROL PARAMETERS FOR FRACTIONAL DELAY RECOVERY (FDR)

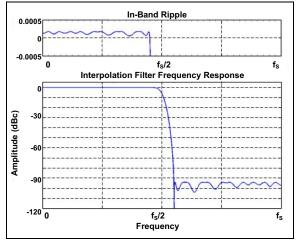
Channel Operation	Control Parameter	Register	Descriptions
Global control for both	EN_FDR = 1	0x7A	Enable FDR features
dual and octal-channel modes	FDR_BAND	0x81	Select 1 st or 2 nd Nyquist band
Dual-channel	SEL_FDR = 0	0x81	Select FDR for dual-channel mode
	EN_DSPP_8 = 0	0x81	Select digital signal post-processing feature for dual-channel mode
	EN_DSPP_2 = 1	0x79	Enable all digital post-processing functions for dual-channel operation
Octal-channel	SEL_FDR = 1	0x81	Select FDR for octal-channel mode
	EN_DSPP_8 = 1	0x81	Select digital signal post-processing feature for octal-channel operation

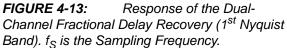
TABLE 4-11: INPUT BANDWIDTH REQUIREMENT FOR FDR

Bandwidth in percentage of f _S ⁽¹⁾	Nyquist Band ⁽²⁾			
	Dual-Channel Mode			
0 – 45%	1 st Nyquist Band (FDR_BAND = 0)			
55 – 100%	2 nd Nyquist Band (FDR_BAND = 1)			
45 – 55%	Avoid			
	Octal-Channel Mode			
0 – 38%	1 st Nyquist Band (FDR_BAND = 0)			

Note 1: f_s is sampling frequency per channel. Distortion is less than 0.1 mdB.

2: See Address 0x81 for FDR_BAND bit setting





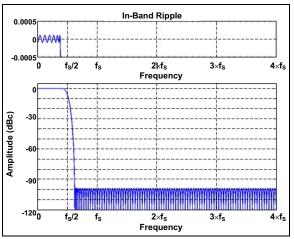


FIGURE 4-14: Response of the Octal-Channel Fractional Delay Recovery (1^{st} Nyquist Band). f_S is the Sampling Frequency.

4.8.2 NOISE-SHAPING REQUANTIZER (NSR)

The device includes 11-bit and 12-bit digital Noise-Shaping Requantizer (NSR) options. When this function is enabled (see Register 5-33), output data is requantized to 11-bit or 12-bit, respectively. The NSR reshapes the requantization noise function and pushes most of the noise outside the frequency band of interest. As a result, the noise floor within the selected bandwidth is substantially lower than that of a typical 12-bit ADC.

To ensure the stability of the NSR, the input signal to the NSR should be limited to less than -0.8 dBFS (~90% of full scale). This can be achieved either by limiting the analog input level or by adjusting the digital gain control. See **Section 4.9** "**Digital Offset and Digital Gain Settings**" and Registers 5-63 to 5-70 for details on the digital gain control. Input levels higher than -0.8 dBFS may corrupt the NSR output and should be avoided.

The NSR feature is available only for the single- and dual-channel modes and can be independently controlled per channel via the register settings. Two NSRs are used:

- NSRA for channel A
- NSRB for channel B

In single-channel mode, only NSRA is used. In dual-channel mode, both NSRA and NSRB are used: NSRA is used for the first selected channel, and NSRB is used for the second selected channel. Both have 11-bit and 12-bit options. Each NSR block consists of a series of filters which are selectable using the NSRA<6:0> and NSRB<6:0> register bit settings. Each filter is defined by a specific percentage bandwidth and center frequency. The available percentage bandwidths are:

- 11-bit mode: 22% and 25% of the sampling frequency
- 12-bit mode: 25% and 29% of the sampling frequency

The center frequency of the band is tunable such that the frequency band of interest can be placed anywhere within the Nyquist band. Table 4-12 lists all the NSR-related registers. Equations 4-5 and 4-6 describe the NSR bandwidth of the 11-bit and 12-bit options, respectively.

EQUATION 4-5: NSR BANDWIDTH FOR 11-BIT OPTION

(a) 22% BW:

$$\frac{f_{Center}}{f_{S}} = 0.12 + \frac{0.26}{20} \times NSR$$
where $0 \le NSR \le 20$
(b) 25% BW:

$$\frac{f_{Center}}{f_{S}} = 0.125 + \frac{0.25}{20} \times (NSR - 21)$$
where $21 \le NSR \le 41$

NSR represents the NSR filter number. See Tables 4-13 and 4-14 for details.

EQUATION 4-6: NSR BANDWIDTH FOR 12-BIT OPTION

(a) 25% BW:

$$\frac{f_{Center}}{f_{S}} = 0.125 + \frac{0.25}{20} \times (NSR - 42)$$
where $42 \le NSR \le 62$
(b) 29% BW:

$$\frac{f_{Center}}{f_{S}} = 0.15 + \frac{0.2}{12} \times (NSR - 63)$$
where $63 \le NSR \le 76$

NSR represents the NSR filter number. See Tables 4-13 and 4-14 for details.

The center frequency of the band is tuned such that the frequency spectrum of interest can be placed anywhere within the Nyquist band. Figure 4-15 shows a graphical demonstration of the NSR bandwidth, which is a percentage of the ADC sampling frequency.

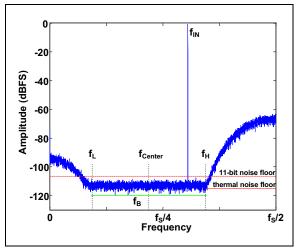


FIGURE 4-15: Graphical demonstration of the NSR filter's transfer function. Note that f_B is controlled as a percentage of the sampling frequency (f_S).

Tables 4-13 and 4-14 show the NSR filter selections. The selectable filters (tuning word) for each mode are:

- 11-bit mode: 0 to 41
- 12-bit mode: 42 to 76

NSR does not affect harmonic distortion. Various FFT spectrum plots when NSR is applied are shown in Figures 3-14 to 3-15, Figures 3-17 to 3-20 and Figures 3-22 to 3-23. SNR and SFDR performance versus input amplitude when NSR is enabled is shown in Figures 3-26 and 3-29.

In this case, SNR and SFDR are measured within the 12-bit mode NSR bandwidth (25% of the sampling frequency). When the NSR block is disabled, the ADC data is provided directly to the output.

TABLE 4-12: REGISTER CONTROL PARAMETERS FOR NSR

Control Parameter	Register	Descriptions			
NSR Enable bits					
<en_nsra_11></en_nsra_11>	0x7A	Enable 11-bit NSR for channel A			
<en_nsra_12></en_nsra_12>	0x7A	Enable 12-bit NSR for channel A			
<en_nsrb_11></en_nsrb_11>	0x7A	Enable 11-bit NSR for channel B			
<en_nsrb_12></en_nsrb_12>	0x7A	Enable 12-bit NSR for channel B			
NSR Settings		•			
NSRA<6:0>	0x78	NSR A settings for single-channel or channel A for dual-channel mode			
NSRB<6:0>	0x79	NSR B settings for channel B in dual-channel mode			
NSR Block Reset Control		•			
<en_nsr_reset></en_nsr_reset>	0x78	Resets NSR in the event of overload			
Digital Post Processing (I	OPP) Functio	n Block Settings			
EN_DPPDUAL	0x79	Enable DPP block for dual-channel mode			

TABLE 4-13: 11-BIT NSR FILTER SELECTION⁽¹⁾

OLLEGHON							
f _{Center} /f _S	f _B (% of f _S)	NSRA<6:0> NSRB<6:0>					
0.12	22	000-0000					
0.133	22	000-0001					
0.146	22	000-0010					
_							
—							
0.367	22	001-0011					
0.38	22	001-0100					
0.125	25	001-0101					
0.1375	25	001-0110					
0.15	25	001-0111					
_							
_							
0.3625	25	010-1000					
0.375	25	010-1001					
	0.12 0.133 0.146 — 0.367 0.38 0.125 0.1375 0.15 — 0.15 — 0.3625	Center/IS (% of fs) 0.12 22 0.133 22 0.146 22 0.146 22 0.33 22 0.367 22 0.38 22 0.125 25 0.1375 25 0.1375 25 0.15 25 0.3625 25					

Note 1: Filters 0 - 41 are used for 11-bit mode only. If these are used for 12-bit mode, the output becomes unknown state.

TABLE 4-14:12-BIT NSR FILTERSELECTION⁽¹⁾

NSR Filter No. (Tuning Word)	f _{Center} /f _S	f _B (% of f _S)	NSRA<6:0> NSRB<6:0>				
42	0.125	25	010-1010				
43	0.1375	25	010-1011				
44	0.15	25	010-1100				
		_					
61	0.3625	25	011-1101				
62	0.375	25	011-1110				
63	0.15	29	011-1111				
64	0.1667	29	100-0000				
65	0.1833	29	100-0001				
		_					
75	0.35	29	100-1011				
76	0.3667	29	100-1100				

Note 1: Filters 42 - 76 are used for 12-bit mode only. If these are used for 11-bit mode, the output becomes unknown state.

4.8.3 DECIMATION FILTERS

The decimation feature is available in single and dualchannel modes and CW octal-channel mode. Figure 4-16 shows a simplified decimation filter block, and Table 4-16 shows the register settings. The decimation rate is controlled by FIR_A<8:0> and FIR_B<7:0> register settings (Addresses 0x7A - 0x7C: Registers 5-35 - 5-37). These registers are thermometer encoded.

In single-channel mode, FIR B is disabled and only FIR A is used. In this mode, the maximum programmable decimation rate is 512x using nine cascaded decimation stages.

In dual-channel mode or when using the Digital Down-Conversion (DDC) in I/Q mode, both FIR A and FIR B are used (see Figure 4-16). In this case, both channels are set to the same decimation rate. Note that stage 1A in FIR A is unused: the user must clear FIR_A<0> in Address 0x7A (Register 5-35). In dual-channel mode, the maximum programmable decimation rate is up to 256x, which is half the single-channel decimation rate (512x).

The overall SNR performance can be improved with higher decimation rate, but limited to about 73.7 dBFS after 16x. This limitation is mainly due to the relative quantization noise level with respect to the 12-bit LSB size. Decimation rates beyond 16x do not further improve SNR but do serve to filter the output data and reduce the overall output data rate. Table 4-15 summarizes decimation rate versus SNR.

TABLE 4-15 :	DECIMATION RATE VS. SNR
	PERFORMANCE

Decimation Rate	SNR (dBFS)
2x	71.4
4x	72.2
8x	72.9
16x	73.3
32x	
64x	
128x	73.7
256x	
512x	

Note: The above data is validated with $f_S = 200$ Msps, $f_{IN} = 5$ MHz, $A_{IN} = -1$ dBFS.

4.8.3.1 Output Data Rate and Clock Phase Control When Decimation is Used

When decimation is used, it also reduces the output clock rate and output bandwidth by a factor equal to the decimation rate applied: the output clock rate is therefore no longer equal to the ADC sampling clock. The user needs to adjust the output clock and data rates in Address 0x02 (Register 5-3) based on the decimation applied. This allows the output data to be synchronized to the output data clock.

Phase shifts in the output clock can be achieved using DCLK_PHDLY_DEC<2:0> in Address 0x64 (Register 5-22). Only four output sampling phases are available when a decimation rate of 2x is used, while all eight clock phases are available for other decimation rates. See Section 4.12.8 "Output Data and Clock Rates" for more details.

4.8.3.2 Using Decimation with CW Beamforming and Digital Down-Conversion

Decimation can be used in conjunction with CW octalchannel mode or DDC. In CW octal-channel mode operation, the eight input channels are summed into a single channel prior to entering the decimation filters. When DDC is enabled, the I and Q outputs can be decimated using the same signal path for the dualchannel mode: I and Q data are fed into Channel A and B, respectively.

In DDC mode, the half-band filter already includes a 2x decimation rate. Therefore, the maximum decimation rate setting for I/Q filtering is 128x for the FIR_A<8:1> and FIR_B<7:0>. See Section 4.8.4 "Digital Down-Conversion (MCP37D11-200 only)" for details.

Note: Fractional Delay Recovery, Digital Gain/Offset adjustment and DDC for I/Q data options occur prior to the decimation filters if they are enabled.

TABLE 4-16: REGISTER CONTROL PARAMETERS FOR USING DECIMATION FILTERS

Control Parameter	Register	Descriptions					
Decimation Filter Settings							
FIR_A<8:0>	0x7A, 0x7B	Channel A FIR configuration for single- or dual-channel mode					
FIR_B<7:0>	0x7C	Channel B FIR configuration for single- or dual-channel mode					
Output Data Rate and Clock	Rate Settings ⁽¹⁾						
OUT_DATARATE<3:0>	0x02	Output data rate: Equal to decimation rate					
OUT_CLKRATE<3:0>	0x02	Output clock rate: Equal to decimation rate					
Output Clock Phase Contro	Control Settings ⁽²⁾						
EN_PHDLY	0x64	Enable digital output phase delay when decimation filter is used					
DCLK_PHDLY_DEC<2:0>	0x64	Digital output clock phase delay control					
Digital Signal Post-Process	ing (DSPP) Function	on Block Settings					
EN_DSPP_2 = 1	0x79	Enable dual-channel decimation					

Note 1: The output data and clock rates must be updated when decimation rates are changed.

 Output clock (DCLK) phase control is used when the output clock is divided by OUT_CLKRATE<3:0> bit settings.

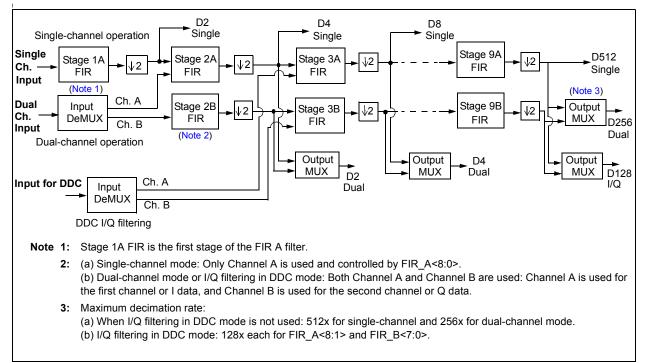


FIGURE 4-16: Simplified Block Diagram of Decimation Filters.

4.8.4 DIGITAL DOWN-CONVERSION (MCP37D11-200 ONLY)

The Digital Down-Conversion (DDC) feature is available in single-, dual- and CW octal-channel modes in the MCP37D11-200. This feature can be optionally combined with the decimation filter and used to:

- translate the input frequency spectrum to a lower frequency band
- · remove the unwanted out-of-band portion
- output the resulting signal as either I/Q data or as a real signal centered at 25% of the output data rate.

Figure 4-17 and Figure 4-18 show the DDC configuration for single- and dual-channel DDC mode, respectively. The DDC includes a 32-bit, complex numerically controlled oscillator (NCO), a selectable (high/low) half-band filter, optional decimation, and two output modes (I/Q or $f_S/8$).

Frequency translation is accomplished with the NCO. The NCO frequency is programmable from 0 Hz to f_S . Phase and amplitude dither can be enabled to improve spurious performance of the NCO.

This DDC feature can be used in a variety of highspeed signal-processing applications, including digital radio, wireless base stations, radar, cable modems, digital video, MRI imaging, etc.

Example:

If the ADC is sampling an input at 200 Msps, but the user is only interested in a 5 MHz span which is centered at 67 MHz, the digital down-conversion may be used to mix the sampled ADC data with 67 MHz to convert it to DC. The resulting signal can then be decimated by 16x such that the bandwidth of the ADC output is 6.25 MHz (200 Msps/16x decimation gives 12.5 Msps with 6.25 MHz Nyquist bandwidth). If fs/8 mode is selected, then a single 25 Msps channel is output, where 6.25 MHz in the output data corresponds to 67 MHz at the ADC input. If I/Q mode is selected, then two 12.5 Msps channels are output, where DC corresponds to 67 MHz and the channels represent inphase (I) and quadrature (Q) components of the down-conversion.

4.8.4.1 Single-Channel DDC

Figure 4-17 shows the single-channel DDC configuration. Each of these processing sub-blocks are individually controlled. Examples of setting registers for selected output type are shown in Tables 4-17 and 4-18.

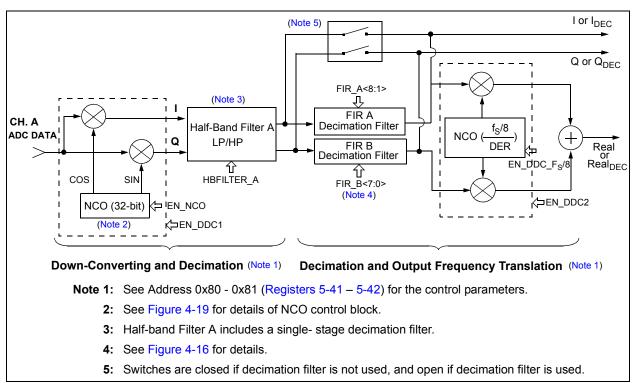


FIGURE 4-17: Simplified DDC Block Diagram for Single-Channel Mode. See <u>Tables 4-17</u> and <u>4-18</u> for Using This DDC Block.

4.8.4.2 Dual-Channel DDC

Figure 4-18 shows the dual-channel DDC configuration. Each channel includes the same processing elements as shown in the single-channel DDC, however the I/Q outputs cannot be separately decimated since the device only supports two channels of decimation (four would be required for I/Q of Channel A and I/Q of Channel B). The decimation option can be used if the DDC output after the half-band filter is up-converted by $f_S/8$ for each channel. Otherwise, I/Q of each channel will be output separately, similar to a four-channel input device with the WCK output pin toggling synchronously with the I-data of Channel A. Note that the NCO phase can be adjusted uniquely for each of the two input channels (see Figure 4-19). Examples of setting registers for selected output type are shown in Tables 4-19 and 4-20.

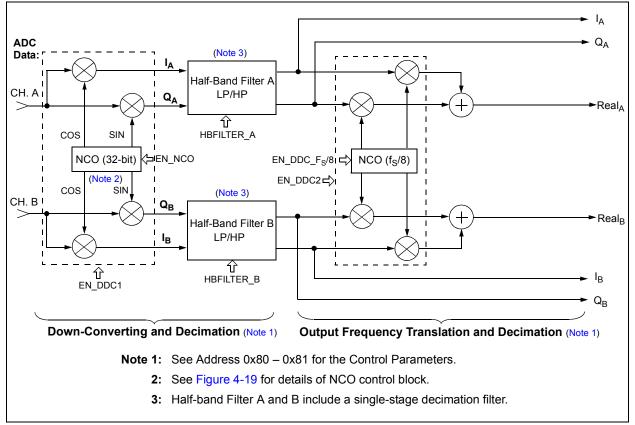


FIGURE 4-18: Simplified DDC Block Diagram for Dual-Channel Mode. See Tables 4-19 and 4-20 for Using this DDC Block.

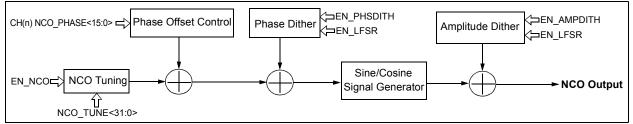
4.8.4.3 Numerically Controlled Oscillator (NCO)

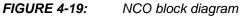
The on-board Numerically Controlled Oscillator (NCO) provides the frequency reference for the in-phase and quadrature mixers in the digital down-converter (DDC).

The NCO serves as a quadrature local oscillator, capable of producing an NCO frequency of between 0 Hz and f_S with a resolution of $f_S/2^{32}$, where f_S is the ADC core sampling frequency.

Figure 4-19 shows the control signals associated with the NCO. In octal- or dual-channel mode, the NCO allows the output phase to be adjusted on a per-channel basis.

Note: The NCO is only used for DDC or CW octalchannel mode. It should be disabled when not in use.





• NCO Frequency Control:

The NCO frequency is programmed from 0 Hz to f_S , using the 32-bit-wide unsigned register variable NCO_TUNE<31:0> in Addresses 0x82 - 0x85 (Registers 5-43 - 5-46).

The following equation is used to set the NCO_TUNE<31:0> register:

EQUATION 4-7: NCO FREQUENCY

<i>NCO_TUNE<</i> Where:	31:($D >= round\left(2^{32} \times \frac{Mod(f_{NCO}, f_S)}{f_S}\right)$
f _S	=	sampling frequency (Hz)
f _{NCO}	=	desired NCO frequency (Hz)
$\text{Mod} \ (f_{\text{NCO}}, \ f_{\text{S}})$	=	gives the remainder of $\mathrm{f}_{\mathrm{NCO}}/\mathrm{f}_{\mathrm{S}}$

Mod() is a remainder function. For example, Mod(5,2) = 1 and Mod(1.999, 2) = 1.999.

Example 1:

If f_{NCO} is 100 MHz and f_S is 200 MHz:

$$Mod(f_{NCO}, f_S) = Mod(100, 200) = 100$$
$$NCO_TUNE < 31:0 > = round \left(2^{32} \times \frac{Mod(100, 200)}{200}\right)$$
$$= 0 \times 8000\ 0000$$

Example 2:

If f_{NCO} is 199.9999994 MHz and f_{S} is 200 MHz:

 $\begin{aligned} Mod(f_{NCO}, f_S) &= Mod(199.99999994, 200) = 199.999999994\\ NCO_TUNE < 31:0 > = round \left(2^{32} \times \frac{Mod(199.99999994, 200)}{200}\right) \\ &= 0 \times FFFF \ FFFF \end{aligned}$

4.8.4.4 NCO Amplitude and Phase Dither

The EN_AMPDITH and EN_PHSDITH parameters in Address 0x80 (Register 5-41) can be used for amplitude and phase dithering, respectively. In principle, these will dither the quantization error created by the use of digital circuits in the mixer and local oscillator, thus reducing spurs at the expense of noise. In practice, the DDC circuitry has been designed with sufficient noise and spurious performance for most applications. In the worst-case scenario, the NCO has an SFDR of greater than 116 dB when the amplitude dither is enabled, and 112 dB when disabled. Although the SNR (\approx 93 dB) of the DDC is not significantly affected by the dithering option, using the NCO with dithering options enabled is always recommended for the best performance.

4.8.4.5 NCO for $f_S/8$ and $f_S/(8xDER)$

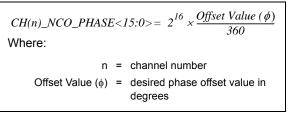
The output of the first down-conversion block (DDC1) is a complex signal (comprising I and Q data) which can then be optionally decimated further up to 128x to provide both a lower output data rate and input channel filtering. If $f_S/8$ mode is enabled, a second mixer stage (DDC2) will convert the I/Q signals to a real signal centered at half of the current Nyquist frequency; i.e., if the output data rate in I/Q mode is 25 Msps per channel (12.5 MHz Nyquist), then in $f_S/8$ mode the output data rate would be 50 Msps (25 Msps each for I and Q), and the signal would be re-centered around 12.5 MHz. In single-channel mode, this is done at the output of the decimation filters (if used). In dual-channel mode, this must be done prior to the decimation.

When decimation is enabled, the I/Q outputs are upconverted by $f_S/(8xDER)$, where DER is the additional decimation rate added by the FIR decimation filters. This provides a decimated output signal centered at $f_S/8$ or $f_S/(8xDER)$ in the frequency domain.

4.8.4.6 NCO Phase Offset Control

The user can add phase offset to the NCO frequency using the NCO phase offset control registers (Addresses 0x86 to 0x95, Registers 5-47 – 5-62). CH(n)_NCO_PHASE<15:0> is the 16-bit-wide NCO phase offset control parameter for Channel *n*. A 0x0000 value in the register corresponds to no offset, and a 0xFFFF corresponds to an offset of 359.995°. The phase offset can be controlled with 0.005° per step. The following equation is used to program the NCO phase offset register:

EQUATION 4-8: NCO PHASE OFFSET



A decimal number is used for the binary contents of CH(n)_NCO_PHASE<15:0>.

4.8.4.7 In-Phase and Quadrature Signals

When the first down-conversion is enabled, it produces In-phase (I) and Quadrature (Q) components as shown in Equation 4-9:

EQUATION 4-9: I AND Q SIGNALS

$$I = ADC \times COS(2\pi f_{NCO}t + \phi)$$
(a)

$$Q = ADC \times SIN(2\pi f_{NCO}t + \phi)$$
(b)

where:

$$\phi = 360 \times \frac{CH(n)_NCO_PHASE < 15:0>}{2^{16}}$$
 (c)

where:

- ADC = output of the ADC block

$$t = k/f_S$$
, with k =1, 2, 3,..., n
 $f_{NCO} = NCO$ frequency

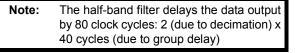
I and Q outputs are interleaved where I data is output on the rising edge of the WCK. If I and Q outputs are selected in dual-channel mode with DDC enabled, I data of Channel 0 is output at the rising edge of WCK, followed by Q data of Channel 0, then I and Q data of

4.8.4.8 Half-Band Filter

The frequency translation is followed by a half-band digital filter, which is used to reduce the sample rate by a factor of two while rejecting aliases that fall into the band of interest.

The user can select high- or low-pass half-band filter using the HBFILTER_A and HBFILTER_B bits in Address 0x80 (Register 5-41). These filters provide greater than 90 dB of attenuation in the attenuation band and less than 1 mdB (10^{-3} dB) of ripple in the passband region of 20% of the input sampling rate. For example, for an ADC sample rate of 200 MSPS, these filters provide less than 1 mdB of ripple over a bandwidth of 40 MHz.

The filter responses shown in Figures 4-16 and 4-17 indicate a ripple of 0.5 mdB and an alias rejection of 90 dB. The output of the half-band filter is a DC-centered complex signal (I and Q). This I and Q signal is then carried to the next down-conversion stage (DDC2) for frequency translation (up-conversion), if the DDC is enabled.



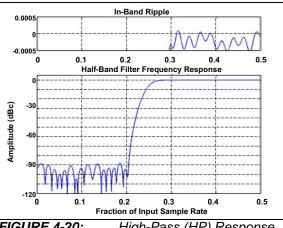


FIGURE 4-20: High-Pass (HP) Response of Half-Band Filter.

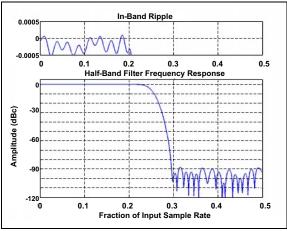


FIGURE 4-21: Low-Pass (LP) Response of Half-Band Filter.

Channel 1 in the same way.

4.8.5 EXAMPLES OF REGISTER SETTINGS FOR USING DDC AND DECIMATION

The following tables show examples of setting registers for using decimation and digital down-conversion (DDC) depending on the output type selection. This feature is available in the MCP37D11-200 device only.

TABLE 4-17:REGISTER SETTINGS FOR DECIMATION AND DDC OPTIONS
FOR SINGLE-CHANNEL MODE – EXAMPLE

ו Rate FIR B) ⁽¹⁾			FIR A	Filter	FIR B Filter	DDC1	DDC2	Dual-Channel DSPP Control	
Decimation R (by FIR A and FI	DDC Mode	Addr. 0x02 ⁽²⁾	0x7A<6> (FIR_A<0>)	0x7B (FIR_A<8:1>)	0x7C (FIR_B<7:0>)	0x80<5,1,0> ⁽³⁾	0x81<6,3,2> ⁽⁴⁾	0x79<7> (EN_DSPP_2)	Output
0	Disabled	0x00	0	0x00	0x00	0,0,0	0,0,0	0	ADC
8	Disabled	0x33	1	0x03	0x00	0,0,0	0,0,0	0	ADC with decimation (÷8)
512	Disabled	0x99	1	0xFF	0x00	0,0,0	0,0,0	0	ADC with decimation (÷512)
0	I/Q	0x00 ⁽⁵⁾	0	0x00	0x00	1,0,1	0,0,0	0	I/Q Data
8	I/Q	0x33	0	0x07	0x07	1,0,1	0,0,0	0	Decimated I/Q (÷8)
0	f _S /8	0x11 ⁽⁶⁾	0	0x00	0x00	1,1,1	0,0,0	0	Real without additional decimation
8	f _S /8	0x44	0	0x07	0x07	1,0,1	1,0,0	0	Real with decimation (÷16)

Note 1: When DDC is used, the actual total decimation is 2x larger since 2x is included from the DDC Half-Band Filter. Example: Decimation = 8x with DDC-I/Q option actually has 16x decimation with 8x provided by the decimation filter and 2x from the DDC Half-Band Filter.

- 2: Output data and clock rate control register.
- **3:** 0x80<5,1,0> = <EN_NCO, EN_DDC_FS/8, EN_DDC1>.
- 4: 0x81<6,3,2> = <EN_DDC2, EN_DSPP_8, 8CH_CW>.
- 5: Each of I/Q has 1/2 of f_S bandwidth. The combined bandwidth is the same as the f_S bandwidth. Therefore the data rate adjustment is not needed.
- 6: The Half-Band Filter A includes decimation of 2.

TABLE 4-18:OUTPUT TYPE VS. CONTROL PARAMETERS FOR SINGLE-CHANNEL DDC
(EXAMPLE)

Output Type	Control Parameter	Register	Descriptions				
Complex: I and Q	EN_DDC1 = 1	0x80	Enable DDC1 block				
	EN_NCO = 1	0x80	Enable 32-bit NCO				
	HBFILTER_A = 1	0x80	Enable Half-Band Filter A, includes 2x decimation				
	EN_DDC_FS/8 = 0	0x80	NCO(f _S /8/DER) is disabled				
	EN_DDC2 = 0	0x81	DDC2 is disabled				
	FIR_A<8:1> = 0x00	0x7B	FIR A decimation filter is disabled				
	FIR_B<7:0> = 0x00	0x7C	FIR B decimation filter is disabled				
	OUT_CLKRATE<3:0>	0x02	Output clock rate is not affected (no need to change)				
Decimated I and	EN_DDC1 = 1	0x80	Enable DDC1 block				
Q:I _{DEC} , Q _{DEC}	EN_NCO = 1	0x80	Enable 32-bit NCO				
	HBFILTER_A = 1	0x80	Enable Half-Band Filter A, includes 2x decimation				
	EN_DDC_FS/8 = 0	0x80	NCO(f _S /8/DER) is disabled				
	EN_DDC2 = 0	0x81	DDC2 is disabled				
	FIR_A<8:1>	0x7B	Program FIR A filter for extra decimation ⁽¹⁾				
	FIR_B<7:0>	0x7C	Program FIR B filter for extra decimation ⁽¹⁾				
	OUT_CLKRATE<3:0>	0x02	Adjust the output clock rate to the decimation rate				
Real: Real _A after	EN_DDC1 = 1	0x80	Enable DDC1 block				
DDC(f _S /8/DER)	EN_NCO = 1	0x80	Enable 32-bit NCO				
without using Decimation Filter	HBFILTER_A = 1	0x80	Enable Half-Band Filter A, includes 2x decimation				
	EN_DDC_FS/8 = 1	0x80	NCO(f_S/8/DER) is enabled. This translates the input signal from dc to $f_S/8^{(2)}$				
	EN_DDC2 = 1	0x81	DDC2 is enabled				
	FIR_A<8:1> = 0x00	0x7B	Decimation filter FIR A is disabled				
	FIR_B<7:0> = 0x00	0x7C	Decimation filter FIR B is disabled				
	OUT_CLKRATE<3:0> = 0001	0x02	Adjust the output clock rate to divided by 2 ⁽³⁾				
Decimated Real:	EN_DDC1 = 1	0x80	Enable DDC1 block				
Real _{A_DEC}	EN_NCO = 1	0x80	Enable 32-bit NCO				
after Decimation Filter and	HBFILTER_A = 1	0x80	Enable Half-Band Filter A, includes 2x decimation				
DDC(f _S /8/DER)	EN_DDC_FS/8 = 1	0x80	NCO(f _S /8/DER) is enabled. This translates the input signal from dc to $f_S/8/\text{DER}^{(2)}$				
	EN_DDC2 = 1	0x81	DDC2 is enabled				
	FIR_A<8:1>	0x7B	Program FIR B filter for extra decimation ⁽⁴⁾				
	FIR_B<7:0>	0x7C	Program FIR B filter for extra decimation ⁽⁴⁾				
	OUT_CLKRATE<3:0>	0x02	Adjust the output clock rate to the total decimation rate including the 2x decimation by the Half-Band Filter A				

Note 1: For I/Q decimation, the maximum decimation rate for the FIR A and FIR B filters is 128x each since the input is already decimated by 2x in the Half-Band Filter. See Figure 4-16 for details.

2: DER is the decimation rate setting of the FIR A and FIR B filters.

3: Divided by 2 is due to the 2x decimation included in the Half-Band Filter A.

4: When this filter is used, the up-conversion frequency is reduced by the extra decimation rates (DER).

TABLE 4-19: REGISTER SETTINGS FOR DECIMATION AND DDC OPTIONS FOR DUAL-CHANNEL MODE EXAMPLE MODE EXAMPLE

ation Rate and FIR B) ⁽¹⁾	de	0x02 ⁽²⁾	FIR A	Filter	FIR B Filter	DDC1	DDC2	Dual-Channel DSPP Control	
Decimation (by FIR A and I	DDC-Mode	Address 0x	0x7A<6> (FIR_A<0>)	0x7B (FIR_A<8:1>)	0x7C (FIR_B<7:0>)	0x80<5,1,0> ⁽³⁾	0x81<6,3,2> ⁽⁴⁾	0x79<7> (EN_DSPP_2)	Output
0	Disabled	0x00	0	0x00	0x00	0,0,0	0,0,0	0	ADC
8	Disabled	0x33	0	0x07	0x07	0,0,0	0,0,0	0	ADC with decimation (+8)
256	Disabled	0x88	0	0xFF	0xFF	0,0,0	0,0,0	0	ADC with decimation (+256)
0	I/Q	0x00 ⁽⁵⁾	0	0x00	0x00	1,0,1	0,0,0	1	I/Q data
0	f _S /8	0x11 ⁽⁶⁾	0	0x00	0x00	1,1,1	0,0,0	1	Real without additional decimation

Note 1: When DDC is used, the actual total decimation is 2x larger since 2x is included from the DDC Half-Band Filter. Example: Decimation = 8x with DDC-f_S/2 option actually has 16x decimation with 8x provided by the decimation filter and 2x from the DDC Half-Band Filter.

2: Output data and clock rate control register.

3: 0x80<5,1,0> = <EN_NCO, EN_DDC_FS/8, EN_DDC1>.

4: 0x81<6,3,2> = <EN_DDC2, EN_DSPP_8, 8CH_CW>.

5: Each of I/Q has 1/2 of f_S bandwidth. The combined bandwidth is the same as the f_S bandwidth. Therefore the data rate adjustment is not needed.

6: The Half-Band Filter A/B includes decimation of 2.

7: 0x0E takes into account the stages 1 and 2 are bypassed. See Figure 4-16 for "dual-channel Input" for DDC.

Output Type	Control Parameter	Register	Descriptions
Complex: I and Q	EN_DSPP_2 = 1	0x79	Enable all digital post-processing functions for dual-channel operations
	EN_DDC1 = 1	0x80	Enable DDC1 block
	EN_NCO = 1	0x80	Enable 32-bit NCO
	HBFILTER_A = 1	0x80	Enable Half-Band Filter A, includes 2x decimation
	HBFILTER_B = 1	0x80	Enable Half-Band Filter B, includes 2x decimation
	EN_DDC_FS/8 = 0	0x80	NCO(f _S /8/DER) is disabled
	EN_DDC2 = 0	0x81	DDC2 is disabled
	FIR_A<8:1> = 0x00	0x7B	FIR A decimation filter is disabled
	FIR_B<7:0> = 0x00	0x7C	FIR B decimation filter is disabled
	OUT_CLKRATE<3:0>	0x02	Output clock rate is not affected (no need to change)
Real: Real _A for Channel A	EN_DSPP_2 = 1	0x79	Enable all digital post-processing functions for dual-channel operations
and Real _B for	EN_DDC1 = 1	0x80	Enable DDC1 block
Channel B after NCO(f _S /8/DER)	EN_NCO = 1	0x80	Enable 32-bit NCO
Without Using	HBFILTER_A = 1	0x80	Enable Half-Band Filter A, includes 2x decimation
Decimation Filter	HBFILTER_B = 1	0x80	Enable Half-Band Filter B, includes 2x decimation
	EN_DDC_FS/8 = 1	0×80	NCO(f_S /8/DER) is enabled. This translates the input signal from DC to f_S /8 ⁽¹⁾
	EN_DDC2 = 1	0x81	DDC2 is enabled
	FIR_A<8:1> = 0x00	0x7B	Decimation filter FIR A is disabled
	FIR_B<7:0> = 0x00	0x7C	Decimation filter FIR B is disabled
	OUT_CLKRATE<3:0> = 0001	0x02	Adjust the output clock rate to divided by 2 ⁽²⁾
Decimated Real: Real _{A_DEC} for	EN_DSPP_2 = 1	0×79	Enable all digital signal post-processing functions for dual- channel operation
Channel A and	EN_DDC1 = 1	0x80	Enable DDC1 block
Real _{B_DEC} for Channel B after	EN_NCO = 1	0x80	Enable 32-bit NCO
NCO(f _S /8/DER) and	HBFILTER_A = 1	0x80	Enable Half-Band Filter A, includes 2x decimation
Decimation Filter	HBFILTER_B = 1	0x80	Enable Half-Band Filter B, includes 2x decimation
	EN_DDC_FS/8 = 1	0×80	NCO(f_S /8/DER) is enabled. This translates the input signal from DC to f_S /8/DER ⁽¹⁾
	EN_DDC2 = 1	0x81	DDC2 is enabled
	FIR_A<8:1>	0x7B	Program FIR A filter for extra decimation ⁽³⁾
	FIR_B<7:0>	0x7C	Program FIR B filter for extra decimation ⁽³⁾
	OUT_CLKRATE<3:0>	0x02	Adjust the output clock rate to the total decimation rate including the 2x decimation by the Half-Band Filter A

TABLE 4-20: OUTPUT TYPE VS. CONTROL PARAMETERS FOR DUAL-CHANNEL DDC EXAMPLE

Note 1: DER is the decimation rate setting of the FIR A and FIR B filters.

2: Divided by 2 is due to the 2x decimation included in the Half-Band Filter A.

3: When this filter is used, the up-conversion frequency is reduced by the extra decimation rates (DER).

4.9 Digital Offset and Digital Gain Settings

Figure 4-22 shows a simplified block diagram of the digital offset and gain settings. Offset is applied prior to the gain. Offset and gain adjustments occur prior to DDC, Decimation or FDR when these features are used.

4.9.1 DIGITAL OFFSET SETTINGS

The offset can be corrected using a 16-bit-wide global offset correction register (0x66) for all channels, offset correction registers for individual channels (0x9E-0xA7) or by combining both global and individual offset correction registers. The offset control for individual channels can be used with DIG_OFFSET_WEIGHT <1:0> in 0xA7. The corresponding registers for each correction are shown in Figure 4-22.

Note that, except for the octal-channel mode, the offset setting registers for individual channels, 0x9E-0xA7 (Registers 5-71 – 5-79), do not sequentially correspond to the channel order defined by CH_ORDER<23:0>. Table 4-21 shows the details of the offset registers that correspond to the actual channels, depending on the number of channels used.

4.9.2 DIGITAL GAIN SETTINGS

CH(N)_DIG_GAIN<7:0> in Addresses 0x96 - 0x9D (Registers 5-63 - 5-70) is used to adjust the digital gain per channel.

- Note 1: Digital Offset Setting: Register mapping (0x9E – 0xA7) to the corresponding channel is not sequential to the channel order defined by CH_ORDER<23:0>, except for the octal-channel mode. See Table 4-21 for details.
 - Gain and NCO Phase Offset: Register mapping to the corresponding channel is sequential to the channel order defined by CH_ORDER<23:0>.

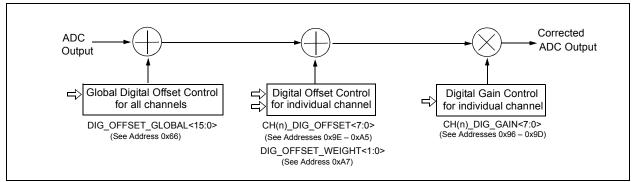


FIGURE 4-22: Simplified Block Diagram for Digital Offset and Gain Settings.

Number of Channel Used		Register Address for Offset Setting						
	1 st Channel	2 nd Channel	3 rd Channel	4 th Channel	5 th Channel	6 th Channel	7 th Channel	8 th Channel
1	0x9F	-	_	_	-	-	—	—
2	0xA0	0x9F	—	-	_	—	_	_
3	0xA1	0x9F	0xA0	_	_	—	—	_
4	0xA2	0x9F	0xA0	0xA1	_	—	—	_
5	0xA3	0x9F	0xA0	0xA1	0xA2	_	_	_
6	0xA4	0x9F	0xA0	0xA1	0xA2	0xA3	—	_
7	0xA5	0x9F	0xA0	0xA1	0xA2	0xA3	0xA4	_
8	0x9E	0x9F	0xA0	0xA1	0xA2	0xA3	0xA4	0xA5

TABLE 4-21: REGISTER ASSIGNMENT FOR OFFSET SETTING

4.10 Continuous Wave (CW) Beamforming and Ultrasound Doppler Signal Processing Using CW Octal-Channel Mode (MCP37D11-200 only)

In modern ultrasound medical applications, large numbers of transducers are often used. The signals from these sensors are then coherently combined for higher transducer gain and directivity. The signals from each sensor arrive at the detection device with a different time delay. Also, in multi-channel scanning operations using the MUX, there is a time delay between acquiring input signals (see Section 4.8.1 "Fractional Delay Recovery for Dual- and Octal-Channel Modes"). These time delays may need to be corrected before all input signals are combined for the signal processing.

Digital beamforming is a digital signal processing technique that requires summing all input signals from different channels after correcting for time delay. The time-delay correction involves the phase alignment of the detected signals with respect to a reference. Along with beamforming, many modern medical ultrasound devices support Doppler imaging, which processes phase information in addition to the classical magnitude detection (for brightness imaging). Ultrasound Doppler signal processing is used to determine movement in the body as represented by blood flow, which can help diagnose the functioning of a heart valve or blood vessel, etc. In a traditional ultrasound system, all of these functions are typically accomplished with discrete components. Figure 4-24 shows an example of an ultrasound system implementation using various specialized components.

The MCP37D11-200 device has a built-in feature that can perform some of the functions that are done traditionally using extra components. Continuous wave (CW) digital beamforming and Doppler signal processing features are available, but these are offered in octal-channel operation only.

Figure 4-23 shows a simplified block diagram for the ultrasound CW beamforming with DDC I/Q decimation. Note that the sub-blocks shown after the MUX are commonly used for all input channels.

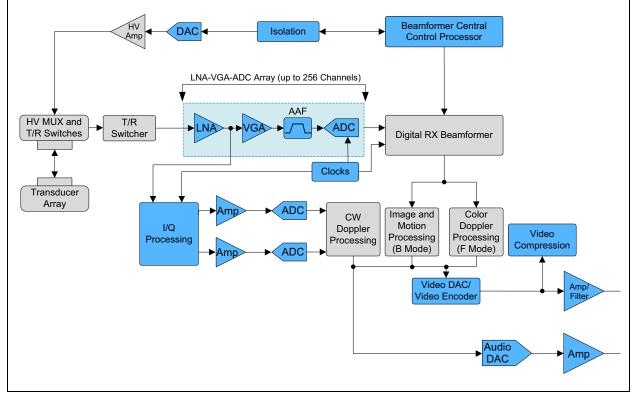


FIGURE 4-23: Example of Ultrasound System Building Block.

4.10.1 BEAMFORMING

Beamforming is achieved by scanning all inputs while correcting the phase of each channel with respect to a reference. This can be done using:

- Fractional Delay Recovery (FDR)
- · Phase offset settings of each individual channel
- · Gain setting per channel

While the CW input channel is multiplexed sequentially, the phase offset can be added to the NCO output (each channel individually). CH(n)_NCO_PHASE<15:0>, in Addresses 0x86 to 0x95 (Registers 5-47 - 5-62), corrects the time delay of the incoming signals with respect to the reference.

The phase-compensated input signal is then downconverted by a wide dynamic range I/Q demodulator. The digital beamforming of the inputs is then obtained by summing I and Q data from individual channels. The combined I and Q data are fed to the half-band filter. Equation 4-10 shows the I and Q data of an individual channel with phase correction (phase offset), and the resulting digital beamforming signal.

The processing blocks after the digital beamforming are the same as the sub-blocks used in single-channel operation described in **Section 4.8.4.1** "**Single-Channel DDC**", except only limited decimation rates of the FIR A and FIR B filters are used due to the processing time requirement for summing the input signals from all channels.

EQUATION 4-10: BEAMFORMING SIGNALS

$$I_{CH(n)} = ADC \times COS(2 \pi f_{NCO}t + \phi(n))$$

$$Q_{CH(n)} = ADC \times SIN(2 \pi f_{NCO}t + \phi(n))$$

$$I = \sum_{n=0}^{N} I_{CH(n)}$$

$$Q = \sum_{n=0}^{N} Q_{CH(n)}$$

$$\phi(n) = 360^{\circ} \times \frac{CH(n) NCO_{PHASE} < 15:0>}{2^{16}}$$

$$= 0.005493164^{\circ} \times CH(n) NCO_{PHASE} < 15:0>$$
Where:

$$\phi(n) = NCO \text{ phase offset of channel } n$$
ADC = the output of the ADC block

The NCO phase offset can be controlled by 0.005493164° per step. See **Section 4.8.4.6 "NCO Phase Offset Control**" for details.

4.10.2 ULTRASOUND DOPPLER SIGNAL PROCESSING

Doppler shift measurement requires summing the input signals from multiple transducer channels and mixing them with a phase-controlled local oscillator frequency. The resulting low-frequency output is then centered near DC and can measure a Doppler shift produced by moving objects, such as blood flow and changes in blood pressure in arteries, etc. In traditional Doppler measurement, many discrete analog components are typically used along with a high-resolution ADC (~18-bit range).

This device has unique built-in features that are suitable for ultrasound Doppler shift measurements. By utilizing these features, system engineers can reduce many discrete components which are otherwise necessary for an ultrasound Doppler measurement system.

The following built-in digital signal post-processing (DSPP) features in the MCP37D11-200 can be effectively used for the ultrasound Doppler signal processing applications:

- Fractional Delay Recovery (FDR): Correct the time delay of signal sampled between channels. See details in Section 4.8.1 "Fractional Delay Recovery for Dual- and Octal-Channel Modes".
- Digital Gain and Offset adjustment for each channel: See details in Section 4.9 "Digital Offset and Digital Gain Settings".
- **Down-Conversion for each channel** with a unique phase of the same NCO frequency prior to summing the eight channels as shown in Figure 4-24.
- After down-conversion by the DDC, the resulting signal can then be decimated to achieve very high SNR in a narrow bandwidth.

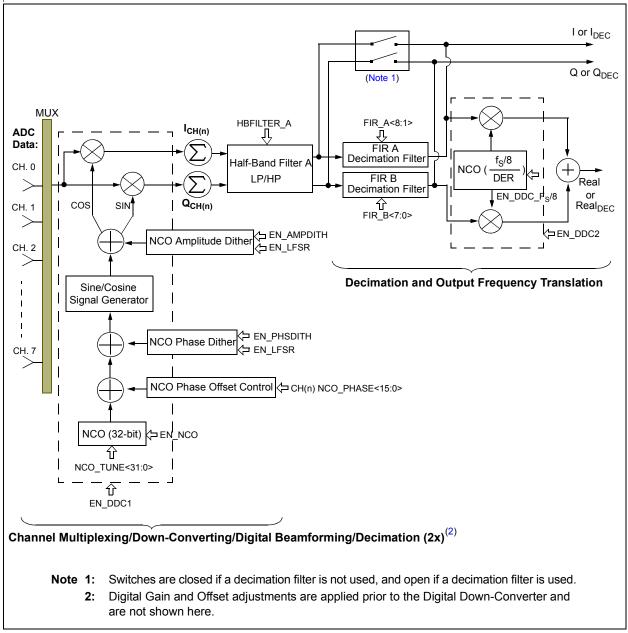


FIGURE 4-24: Simplified Block Diagram of CW Beamforming and I/Q Signal Processing - Available in MCP37D11-200 Only.

4.11 Output Data format

The device can output the ADC data in offset binary or two's complement. The data format is selected by the DATA_FORMAT bit in Address 0x62 (Register 5-20).

Table 4-22 shows the relationship between the analog input voltage, the digital data output bits and the overrange bit. By default, the output data format is two's complement.

TABLE 4-22 :	ADC OUTPUT CODE VS.	INPUT VOLTAGE (12-BIT MODE)
---------------------	---------------------	-----------------------------

Input Range	Offset Binary ⁽¹⁾	Two's Complement ⁽¹⁾	Overrange (OVR)
A _{IN} > A _{FS}	1111-1111-1111	0111-1111-1111	1
A _{IN} = A _{FS}	1111-1111-1111	0111-1111-1111	0
A _{IN} = A _{FS} – 1 LSb	1111-1111-1110	0111-1111-1110	0
A _{IN} = A _{FS} – 2 LSb	1111-1111-1100	0111-1111-1100	0
	•		
	•		
$A_{IN} = A_{FS}/2$	1100-0000-0000	0100-0000-0000	0
A _{IN} = 0	1000-0000-0000	0000-0000-0000	0
$A_{IN} = -A_{FS}/2$	0011-1111-1111	1011-1111-1111	0
	•		
	•		
A _{IN} = -A _{FS} + 2 LSb	0000-0000-0010	1000-0000-0010	0
A _{IN} = -A _{FS} + 1 LSb	0000-0000-0001	1000-0000-0001	0
A _{IN} = -A _{FS}	0000-0000-0000	1000-0000-0000	0
A _{IN} < -A _{FS}	0000-0000-0000	1000-0000-0000	1

Note 1: MSb is sign bit

4.12 Digital Output

The device can operate in one of the following two digital output modes:

- Full-Rate CMOS
- Double-Data-Rate (DDR) LVDS

The outputs are powered by DV_{DD18} and GND. LVDS mode is recommended for data rates above 80 Msps. The digital output mode is selected by the OUTPUT_MODE<1:0> bits in Address 0x62 (Register 5-20). Figures 2-1 – 2-2 show the timing diagrams of the digital output.

4.12.1 FULL RATE CMOS MODE

In full-rate CMOS mode, the data outputs (Q11 to Q0, overrange indicator (OVR), word clock (WCK) and the data output clock (DCLK+, DCLK–) have CMOS output levels. The digital output should drive minimal capacitive loads. If the load capacitance is larger than 10 pF, a digital buffer should be used.

4.12.2 DOUBLE DATA RATE LVDS MODE

In double-data-rate LVDS mode, the output is a parallel data stream which changes on each edge of the output clock. See Figure 2-2 for details.

In multi-channel configuration, the data is output sequentially with the WCK that is synchronized to the first sampled channel.

The device outputs the following LVDS output pairs:

- Output Data: Q5+/Q5- through Q0+/Q0-
- OVR/WCK
- DCLK+/DCLK-

A 100 Ω differential termination resistor is required for each LVDS output pin pair. The termination resistor should be located as close as possible to the LVDS receiver. By default, the outputs are standard LVDS levels: 3.5 mA output current with a 1.15V output common-mode voltage on a 100 Ω differential load. See Address 0x63 (Register 5-21) for more details of the LVDS mode control.

Note:	Output Data Rate in LVDS Mode: In octal-
	channel mode, the input sample rate per
	channel is f _S /8. Therefore, the output data
	rate required to shift out all 12 bits in DDR is
	still equivalent to f_S . For example, if f_S =
	200 Msps, each channel's sample rate is
	$f_S/8 = 25$ Msps, and the output clock rate
	(DCLK) for 12-bit DDR output is 200 MHz.

4.12.3 OVERRANGE BIT (OVR)

The input overrange status bit is asserted (logic high) when the analog input has exceeded the full-scale range of the ADC in either the positive or negative direction. In LVDS DDR Output mode, the OVR bit is multiplexed with the word clock (WCK) output bit such that OVR is output on the falling edge of the data output clock and WCK on the rising edge.

The OVR bit has the same pipeline latency as the ADC data bits. In multi-channel mode, the OVR is output independently for each input channel and is synchronized to the data. See Address 0x68 (Register 5-26) for OVR and WCK control options.

If DSPP options are enabled, OVR pipeline latency will be unaffected; however, the data will incur additional delay. This has the effect of allowing the OVR indicator to precede the affected data.

4.12.4 WORD CLOCK (WCK)

The word clock output bit indicates the start of a new data set. In single-channel mode, this bit is disabled except for I/Q output mode. In DDR output with multichannel mode, it is always asserted coincidentally with the data from the first sampled channel, and multiplexed with the OVR bit. See Address 0x07 (Register 5-5) and Address 0x68 (Register 5-26) for OVR and WCK control options.

4.12.5 LVDS OUTPUT POLARITY CONTROL

In LVDS mode, the output polarity can be controlled independently for each LVDS pair. Table 4-23 summarizes the LVDS output polarity control register bits.

TABLE 4-23:LVDS OUTPUT POLARITY
CONTROL

Control Parameter	Register	Descriptions
POL_LVDS<7:0>	0x65	Control polarity of LVDS data pairs
POL_WCK_OVR	0x68	Control polarity of WCK and OVR bit pair

4.12.6 PROGRAMMABLE LVDS OUTPUT

In LVDS mode, the default output driver current is 3.5 mA. This current can be adjusted by using the LVDS_IMODE<2:0> bit setting in Address 0x63 (Register 5-21). Available output drive currents are 1.8 mA, 3.5 mA, 5.4 mA and 7.2 mA.

4.12.7 OPTIONAL LVDS DRIVER INTERNAL TERMINATION

In most cases, using an external 100 Ω termination resistor will give excellent LVDS signal integrity. In addition, an optional internal 100 Ω termination resistor can be enabled by setting the LVDS_LOAD bit in

Address 0x63 (Register 5-21). The internal termination helps absorb any reflections caused by imperfect impedance termination at the receiver.

4.12.8 OUTPUT DATA AND CLOCK RATES

The user can reduce output data and output clock rates using Address 0x02 (Register 5-3). When decimation or digital down-conversion (DDC) is used, the output data rate has to be reduced to synchronize with the reduced output clock rate.

4.12.9 PHASE SHIFTING OF OUTPUT CLOCK (DCLK)

In full-rate CMOS mode, the data output bit transition occurs at the rising edge of DCLK+, so the falling edge of DCLK+ can be used to latch the output data.

In double-data-rate LVDS mode, the data transition occurs at both the rising and falling edges of DCLK+. For adequate setup and hold time when latching the data into the external host device, the user can shift the phase of the digital clock output (DCLK+/DCLK-) relative to the data output bits.

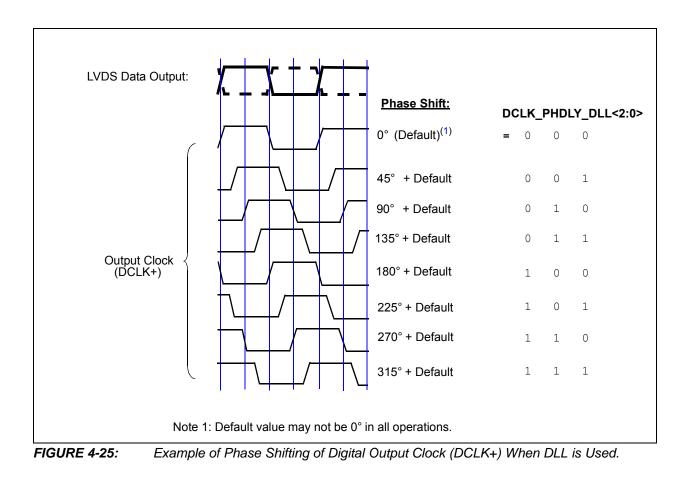
The output phase shift (delay) is controlled by each unique register depending on which timing source is used or if decimation is used. Table 4-24 shows the output clock phase control registers for each Configuration mode: (a) when DLL is used, (b) when decimation is used, and (c) when PLL is used.

Figure 4-25 shows an example of the output clock phase delay control using the DCLK_PHD-LY_DLL<2:0> when DLL is used.

TABLE 4-24: OUTPUT CLOCK (DCLK) PHASE CONTROL PARAMETERS

Control Parameter	Register	Operating Condition ⁽¹⁾		
When DLL is used:				
EN_PHDLY 0x64 EN_PHDLY = 1: Enable output clock phase delay control				
DCLK_PHDLY_DLL<2:0> 0x52 DCLK phase delay control when DLL is used. Decimation is not used.				
When decimation is used:				
EN_PHDLY 0x64 EN_PHDLY = 1: Enable output clock phase delay control				
DCLK_PHDLY_DEC<2:0> DCLK phase delay control when decimation filter is used. The phase delay is controlled in digital clock output control block.				
When PLL is used:				
DCLK_DLY_PLL<2:0>	DCLK_DLY_PLL<2:0> 0x6D DCLK delay control when PLL is used.			
DCLK_PHDLY_DEC<2:0>		is controlled in digital clock output control block. When PLL is used:		

Note 1: See Figure 4-11 for details.



4.12.10 DIGITAL OUTPUT RANDOMIZER

Depending on PCB layout considerations and power supply coupling, SFDR may be improved by decorrelating the ADC input from the ADC digital output data. The device includes an output data randomizer option. When this option is enabled, the digital output is randomized by applying an exclusive-OR logic operation between the LSb (D0) and all other data output bits. To decode the randomized data, the reverse operation is applied: an exclusive-OR operation is applied between the LSb (D0) and all other bits. The DCLK, OVR, WCK and LSb (D0) outputs are not affected. Figure 4-26 shows the block diagram of the data randomizer and decoder logic. The output randomizer is enabled by setting the EN_OUT_RANDOM bit in Address 0x07 (Register 5-5).

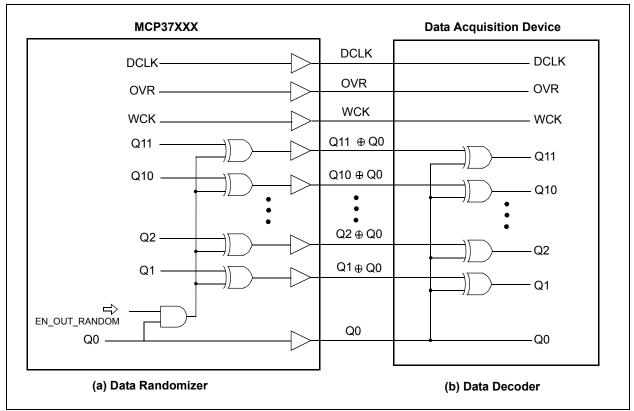


FIGURE 4-26: Logic Diagram for Digital Output Randomizer and Decoder.

4.12.11 OUTPUT DISABLE

The digital output can be disabled by setting OUTPUT_MODE<1:0> = 00 in Address 0x62 (Register 5-20). All digital outputs are disabled, including OVR, WCK, DCLK, etc.

4.12.12 OUTPUT TEST PATTERNS

To facilitate testing of the I/O interface, the device can produce various predefined or user-defined patterns on the digital outputs. See TEST_PATTERNS<2:0> in Address 0x62 (Register 5-20) for the predefined test patterns. For the user-defined patterns, Addresses 0x74 - 0x77 (Registers 5-29 - 5-32) can be programmed using the SPI interface. When an output test mode is enabled, the ADC's analog section can still be operational, but does not drive the digital outputs. The outputs are driven only with the selected test pattern.

4.12.12.1 Pseudo-Random Number (PN) Sequence Output

When TEST_PATTERNS<2:0> = 111, the device outputs a pseudo-random number (PN) sequence which is defined by the polynomial of degree 16, as shown in Equation 4-11. Figure 4-27 shows the block diagram of a 16-bit Linear Feedback Shift Register (LFSR) for the PN sequence.

EQUATION 4-11: POLYNOMIAL FOR PN

$$P(x) = 1 + x^4 + x^{13} + x^{15} + x^{16}$$

The output PN[15:4] is directly applied to the output pins Qn[11:0]. In addition to the output at the Qn[11:0] pins, the two MSbs, PN[15] and PN[14], are copied to the OVR and WCK pins, respectively.

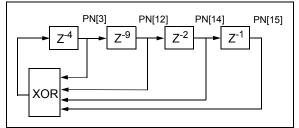


FIGURE 4-27: Block Diagram of 16-Bit LFSR for Pseudo-Random Number (PN) Sequence for Output Test Pattern.

4.13 System Calibration

The built-in system calibration algorithm includes:

- Harmonic Distortion Correction (HDC)
- DAC Noise Cancellation (DNC)
- Dynamic Element Matching (DEM)

HDC and DNC correct the nonlinearity in the residue amplifier and DAC, respectively. The system calibration is performed by:

- Power-up calibration, which takes place during the Power-on Reset sequence (requires 2²⁷ clock cycles)
- Background calibration, which takes place during normal operation (per 2³⁰ clock cycles).

Background calibration time is invisible to the user, and primarily affects the ADC's ability to track variations in ambient temperature.

The calibration status is monitored by the CAL pin or the ADC_CAL_STAT bit in Address 0xC0 (Register 5-80). See Address 0x07 (Register 5-5) and 0x1E (Register 5-6) for time delay control of the autocalibration. Table 4-25 shows the calibration time for various ADC core sample rates.

TABLE 4-25 :	CALIBRATION TIME VS. ADC
	CORE SAMPLE RATE

f _S (Msps)	200	150	100	70	50
Power-Up Calibration Time (s)	0.67	0.9	1.34	1.92	2.68
Background Calibration Time (s)	5.37	7.16	10.73	15.34	21.48

4.13.1 RESET COMMAND

Although the background calibration will track changes in temperature or supply voltage, changes in clock frequency or register configuration should be followed by a recalibration of the ADC. This can be accomplished via either the Hard or Soft Reset command. The recalibration time is the same as the power-up calibration time (2^{27} clock cycles). Resetting the device is highly recommended when exiting from Shutdown or Standby mode after an extended amount of time. During the reset, the device has the following state:

- No ADC output
- No change in power-on condition of internal reference
- Most of the internal clocks are not distributed
- Contents of internal user registers:
 - Not affected by Soft Reset
 - Reset to default values by Hardware Reset
- Current consumption of the digital section is negligible, but no change in the analog section.

4.13.1.1 Hardware Reset

A hard reset is triggered by toggling the $\overrightarrow{\text{RESET}}$ pin. On the rising edge, all internal calibration registers and user registers are initialized to their default states and recalibration of the ADC begins. The recalibration time is the same as the power-up calibration time. See Figure 2-6 for the timing details of the hardware $\overrightarrow{\text{RESET}}$ pin.

4.13.1.2 Soft Reset

The user can issue a Soft Reset command for a fast recalibration of the ADC by setting the SOFT_RESET bit to '0' in Address 0x00 (Register 5-1). During Soft Reset, all internal calibration registers are initialized to their initial default states. User registers are unaffected. When exiting the Soft Reset (changing from '0' to '1'), an automatic device calibration takes place.

4.14 Power Dissipation and Power Savings

The power dissipation of the ADC core is proportional to the sample rate (f_S). The digital power dissipation of the CMOS outputs are determined primarily by the strength of the digital drivers and the load condition on each output pin. The maximum digital load current (I_{LOAD}) can be calculated as:

EQUATION 4-12: CMOS OUTPUT LOAD CURRENT

$$I_{LOAD} = DV_{DDI.8} \times f_{DCLK} \times N \times C_{LOAD}$$

Where:
N = Number of bits
C_{LOAD} = Capacitive load of output pin

The capacitive load presented at the output pins needs to be minimized to minimize digital power consumption. The output load current of the LVDS output is constant, since it is set by LVDS_IMODE<2:0> in Address 0x63 (Register 5-21).

4.14.1 POWER-SAVING MODES

This device has two power-saving modes:

- Shutdown
- Standby

They are set by the SHUTDOWN and STANDBY bits in Address 0x00 (Register 5-1).

In Shutdown mode, most of the internal circuitry, including the reference and clock, are turned off with the exception of the SPI interface. During Shutdown, the device consumes 23 mA (typical), primarily due to digital leakage. When exiting from Shutdown, issuing a Soft Reset at the same time is highly recommended.

This will perform a fast recalibration of the ADC. The contents of the internal registers are not affected by the Soft Reset.

In Standby mode, most of the internal circuitry is disabled except for the reference, clock and SPI interface. If the device has been in standby for an extended period of time, the current calibration value may not be accurate. Therefore, when exiting from Standby mode, executing the device Soft Reset at the same time is highly recommended.

4.15 AutoSync Mode: Synchronizing Multiple ADCs at the Same Clock using Master and Slave Configuration

AutoSync allows multiple devices to sample input synchronously at the same clock, and output the conversion data at the same times if they are using the same digital signal post-processing. Figure 4-28 shows the system configuration using the AutoSync feature. Three examples with timing diagram are shown in Figure 2-7 – Figure 2-9.

Once the devices are synchronized, each device performs internal calibration (T_{PCAL}) before sending out valid data output. Any ADC data output before the calibration is complete should be ignored.

Note that the calibration time varies slightly from device to device, and the internal calibration status can be monitored using the CAL pin or ADC_CAL_STAT bit in the Register Address 0xC0.

The valid synchronized output is available when all devices complete their own internal calibration. For this reason, the user has two options for the synchronized output: (a) monitor the calibration status of individual devices and wait until all devices complete calibrations or (b) use an external AND gate as shown in Figure 4-27. Master and all Slave devices are synchronized when the AND gate output toggles to "High".

The AutoSync feature can be used with the following steps:

- Master device is selected by setting SLAVE pin to "GND": SYNC pin becomes output pin.
- Slave device is selected by setting SLAVE pin to "High" (or tie to DVDD18): SYNC pin becomes input pin.
- Feed the Master's SYNC pin output to Slave's SYNC pin.
- Use AutoSync mode using (a) Power-On Reset (Figure 2-7), (b) RESET Pin (Figure 2-8), or (c) SOFT RESET bit (Figure 2-9).

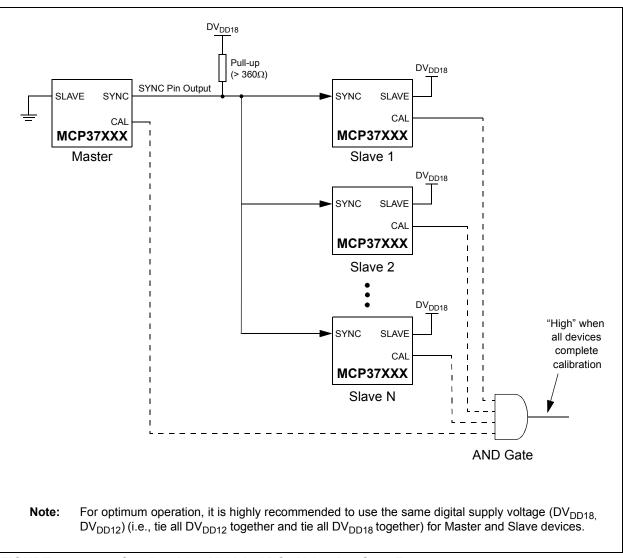


FIGURE 4-28: Synchronizing Multiple ADCs Using AutoSync Feature.

NOTES:

5.0 SERIAL PERIPHERAL INTERFACE (SPI)

The user can configure the ADC for specific functions or optimized performance by setting the device's internal registers through the serial peripheral interface (SPI). The SPI communication uses three pins: \overline{CS} , SCLK and SDIO. Table 5-1 summarizes the SPI pin functions. The SCLK is used as a serial timing clock and can be used up to 50 MHz. SDIO (Serial Data Input/Output) is a dual-purpose pin that allows data to be sent or read from the internal registers. The Chip Select pin (CS) enables SPI communication when active-low. The falling edge of \overline{CS} followed by a rising edge of SCLK determines the start of the SPI communication. When \overline{CS} is tied to high, SPI communication is disabled and the SPI pins are placed in high-impedance mode. The internal registers are accessible by their address.

Figures 5-1 and 5-2 show the SPI data communication protocols for this device with MSb-first and LSb-first options, respectively. It consists of:

 16-bit wide instruction header + Data byte 1 + Data byte 2 + . . . + Data Byte N

Table 5-2 summarizes the bit functions. The R/\overline{W} bit of the instruction header indicates whether the command is a read ('1') or a write ('0'):

• If the R/W bit is '1', the SDIO pin changes direction from an input (SDI) to an output (SDO) after the 16-bit wide instruction header.

By selecting the R/W bit, the user can write the register or read back the register contents. The W1 and W2 bits in the instruction header indicate the number of data bytes to transmit or receive in the following data frame.

Bits A2 – A0 are the SPI device address bits. These bits are used when multiple devices are used in the same SPI bus. A2 is internally hardcoded to '0'. Bits A1 and A0 correspond to the logic level of the ADR1 and ADR0 pins, respectively.

Note:	In	the	VTLA-124	package,	ADR1	is
	inte	ernall	y bonded to	ground (log	gic '0').	

The R9 – R0 bits represent the starting address of the Configuration register to write or read. The data bytes following the instruction header are the register data. All register data is eight bits wide. Data can be sent in MSb-first mode (default) or in LSb-first mode, which is determined by the <LSb_FIRST> bit setting in Address 0x00 (Register 5-1). In Write mode, the data is clocked in at the rising edge of the SCLK. In the Read mode, the data is clocked out at the falling edge of the SCLK.

TABLE 5-1: SPI PIN FUNCTIONS

Pin Name	Descriptions
CS	Chip Select pin. SPI mode is initiated at the falling edge. It needs to maintain active-low for the entire period of the SPI communication. The device exits the SPI communication at the rising edge.
SCLK	 Serial clock input pin. Writing to the device: Data is latched at the rising edge of SCLK Reading from the device: Data is latched at the falling edge of SCLK
SDIO	 Serial data input/output pin. This pin is initially an input pin (SDI) during the first 16-bit instruction header. After the instruction header, its I/O status can be changed depending on the R/W bit: if R/W = 0: Data input pin (SDI) for writing if R/W = 1: Data output pin (SDO) for reading

TABLE 5-2: SPI DATA PROTOCOL BIT FUNCTIONS

Bit Name	Descriptions
R/W	1 = Read Mode 0 = Write Mode
W1, W0 (Data Length)	 00 = Data for one register (1 byte) 01 = Data for two registers (2 bytes) 10 = Data for three registers (3 bytes) 11 = Continuous reading or writing by clocking SCLK⁽¹⁾
A2 - A0	Device SPI Address for multiple devices in SPI bus A2: Internally hardcoded to '0' A1: Logic level of ADR1 pin A0: Logic level of ADR0 pin
R9 - R0	Address of starting register
D7 - D0	Register data. MSb or LSb first, depending on the LSb_FIRST bit setting in 0x00

Note 1: The register address counter is incremented by one per step. The counter does not automatically reset to 0x00 after reaching the last address (0x15D). Be aware that the user registers are not sequentially allocated.

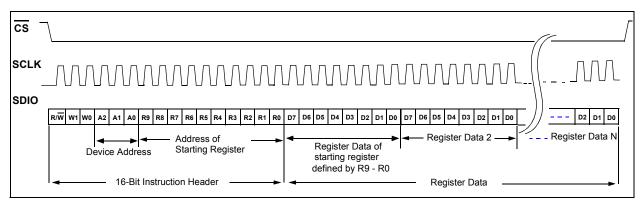


FIGURE 5-1: SPI Serial Data Communication Protocol with MSb-first. See Figures 2-3 and 2-4 for Timing Specifications.

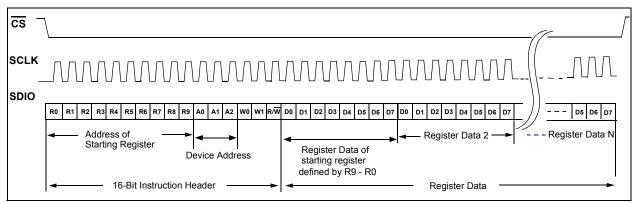


FIGURE 5-2: SPI Serial Data Communication Protocol - with LSb-First. See Figures 2-3 and 2-4 for Timing Specifications.

5.1 Register Initialization

The internal Configuration registers are initialized to their default values under two different conditions:

- After 2²⁰ clock cycles of delay from the power-on reset (POR).
- Resetting the hardware reset pin (RESET).

Figures 2-3 and 2-4 show the timing details.

5.2 Configuration Registers

The internal registers are mapped from Addresses 0x00 - 0x15D. These user registers are not sequentially located. Some user Configuration registers include factory-controlled bits. The factory-controlled bits should not be overwritten by the user.

All user Configuration registers are read/write, except for the last four registers, which are read-only. Each register is made of an 8-bit-wide volatile memory, and their default values are loaded during the power-up sequence or by using the hardware RESET pin. All registers are accessible by the SPI command using the register address. Table 5-3 shows the user-register memory map, and Registers 5-1 – 5-83 show the details of the register bit functions.

- Note 1: All address and bit locations that are not included in the following register map table should not be written or modified by the user.
 - 2: Some registers include factory-controlled bits (FCB). Do not overwrite these bits.

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TABLE 5-3:	REGISTER MAP TABLE

		Bits								
Addr.	Register Name	b7	b6	b5	b4	b3	b2	k		
0x00	SPI Bit Ordering and ADC	SHUTDOWN	LSb-FIRST	SOFT_RESET	STANDBY	STANDBY	SOFT_RESET	LSb-		
	Mode Selection	1 = Shutdown	1 = LSb first 0 = MSb first	0 = Soft Reset	1 = Standby	1 = Standby	0=Soft Reset	1 = LSb 0 = MSt		
0x01	No. of Channel Selection and Independency Control of Output Data and Clock Divider	EN_DATCLK_IND	FCB<3> = 0		SEL_NCH<2:0>			FCB<2:0		
0x02	Output Data and Clock Rate Control		OUT_DAT	ARATE<3:0>			OUT_CLKF	RATE<3:0		
0x04	SPI SDO Timing Control	SDO_TIME			FCE	3<6:0> = 0011111				
0x07	Output Randomizer and WCK Polarity Control	POL_WCK	EN_AUTOCAL_ TIMEDLY		F	CB<4:0> = 10001				
0x1E	Auto-Calibration Time Delay Control				AUTOCAL_TIME	EDLY<7:0>				
0x52	DLL Control	EN_DUTY	C	OCLK_PHDLY_DLL<2:	0>	EN_DLL_DCLK	EN_DLL	EN_		
0x53	Clock Source Selection		FCB<6:4>= 010			FCB<3:0	>= 0101			
0x54	PLL Reference Divider		PLL_REFDIV<7:0>							
0x55	PLL Output and Reference Divider		PLL_OU	JTDIV<3:0>		FCB<1:0> = 10				
0x56	PLL Prescaler (LSb)				PLL_PRE (LS	SB)<7:0>				
0x57	PLL Prescaler (MSb)		FCB<3	: 0> = 0100			PLL_PRE (N	/ISB)<11:8		
0x58	PLL Charge Pump		FCB<2:0> = 000		PLL_BIAS		PLL_CHAG	PUMP<3:		
0x59	PLL Enable Control 1	U	FCB<4	1:3> = 10	EN_PLL_REFDIV	FCB<	2:1> = 00	EN_		
0x5A	PLL Loop Filter Resistor	U	FCB<1	:0> = 01			PLL_RES<4:0>			
0x5B	PLL Loop Filter Cap3	U	FCB<1	1:0> = 01			PLL_CAP3<4:0>			
0x5C	PLL Loop Filter Cap1	U	FCB<1	1:0> = 01			PLL_CAP1<4:0>			
0x5D	PLL Loop Filter Cap2	U	FCB<1	1: 0> = 01			PLL_CAP2<4:0>			
0x5F	PLL Enable Control 2		FCB<5	: 2> = 1111		EN_PLL_OUT	EN_PLL_BIAS			
0x62	Output Data Format and Output Test Pattern	U	FCB<0> = 0	DATA_FORMAT	OUTPUT_M	10DE<1:0>	TE	ST_PATT		
0x63	LVDS Output Load and Drive Current Control		FCB<3	: 0> = 0000		LVDS_LOAD	L	VDS_IMC		
0x64	Output Clock Phase Control when Decimation Filter is used	EN_PHDLY	EN_PHDLY DCLK_PHDLY_DEC<2:0>				FCB<3:0	> = 0011		
0x65	LVDS Output Polarity Control			POL_LVE)S<5:0>					
0x66	Digital Offset Correction - Lower Byte		DIG_OFFSET_GLOBAL<7:0>							

REGISTER MAP TABLE (CONTINUED) TABLE 5-3:

					Bits			
Addr.	Register Name	b7	b6	b5	b4	b3	b2	b1
0x67	Digital Offset Correction - Upper Byte				DIG_OFFSET_GL	OBAL<15:8>	L	1
0x68	WCK and OVR		FCB<5	: 2> = 0010		POL_WCK_OVR	EN_WCK_OVR	
0x6B	PLL Calibration			FCB<6:2> = 00001			PLL_CAL_TRIG	
0x6D	PLL Output and Output Clock Phase	U<	1:0>	EN_PLL_CLK	FCB<1> = 0	C	OCLK_DLY_PLL<2:0	
0x74	User-Defined Output Pattern A - Lower Nibble		PATTE	RN A<3:0>			Do not use (Leave t	hese bits as
0x75	User-Defined Output Pattern A - Upper Byte				PATTERN A	<11:4>		
0x76	User-Defined Output Pattern B - Lower Nibble		PATTE	RN B<3:0>			Do not use (Leave t	hese bits as
0x77	User-Defined Output Pattern B - Upper Byte				PATTERN B	<11:4>		
0x78	Noise-Shaping Requantizer Channel A Filter	NSR_RESET				NSRA<6:0>		
0x79	Dual-Channel DSPP Control	EN_DSPP_2				NSRB<6:0>		
0x7A	FIRA0 Filter, FDR and NSR Control	FCB<1> = 0	FIR_A<0>	EN_FDR	FCB<0> = 0	EN_NSRB_11	EN_NSRB_12	EN_NSF
0x7B	FIR A Filter			1	FIR_A<8	:1>		
0x7C	FIR B Filter				FIR_B<7	:0>		
0x7D	Auto-Scan Channel Order - Lower Byte				CH_ORDER	<7:0>		
0x7E	Auto-Scan Channel Order - Middle Byte				CH_ORDER	<15:8>		
0x7F	Auto-Scan Channel Order - Upper Byte				CH_ORDER<	23:16>		
0x80	Digital Down-Converter Control 1	HBFILTER_B	HBFILTER_A	EN_NCO	EN_AMPDITH	EN_PHSDITH	EN_LFSR	EN_DDC
0x81	Digital Down-Converter Control 2	FDR_BAND	EN_DDC2	GAIN_HBF_DDC	SEL_FDR	EN_DSPP_8	8CH_CW	
0x82	Numerically Controlled Oscillator (NCO) Tuning - Lower Byte				NCO_TUNE	<7:0>		-
0x83	Numerically Controlled Oscillator (NCO) Tuning - Middle Lower Byte				NCO_TUNE	<15:8>		
0x84	Numerically Controlled Oscillator (NCO) Tuning - Middle Upper Byte				NCO_TUNE<	:23:16>		
Legend	U = Unimplemented bit, rea Read-only register. Preprog		actory-Controlled Bi	ts. Do not program	1 = bit is set 0 =	bit is cleared	x = bit is unknown	

TABLE 5-3: **REGISTER MAP TABLE (CONTINUED)**

Addr.	Register Name	Bits									
Addr.		b7	b6	b5	b4	b3	b2	b'			
0x85	Numerically Controlled Oscillator (NCO) Tuning - Upper Byte		NCO_TUNE<31:24>								
0x86	CH0 NCO Phase Offset in CW or DDC Mode - Lower Byte				CH0_NCO	_PHASE<7:0>					
0x87	CH0 NCO Phase Offset in CW or DDC Mode - Upper Byte				CH0_NCO_	PHASE<15:8>					
0x88	CH1 NCO Phase Offset in CW or DDC Mode - Lower Byte				CH1_NCO	PHASE<7:0>					
0x89	CH1 NCO Phase Offset in CW or DDC Mode - Upper Byte				CH1_NCO_	PHASE<15:8>					
0x8A	CH2 NCO Phase Offset in CW or DDC Mode - Lower Byte				CH2_NCO	PHASE<7:0>					
0x8B	CH2 NCO Phase Offset in CW or DDC Mode - Upper Byte				CH2_NCO_	PHASE<15:8>					
0x8C	CH3 NCO Phase Offset in CW or DDC Mode - Lower Byte				CH3_NCO	PHASE<7:0>					
0x8D	CH3 NCO Phase Offset in CW or DDC Mode - Upper Byte				CH3_NCO_	PHASE<15:8>					
0x8E	CH4 NCO Phase Offset in CW or DDC Mode - Lower Byte				CH4_NCO	PHASE<7:0>					
0x8F	CH4 NCO Phase Offset in CW or DDC Mode - Upper Byte				CH4_NCO_	PHASE<15:8>					
0x90	CH5 NCO Phase Offset in CW or DDC Mode - Lower Byte				CH5_NCO	PHASE<7:0>					
0x91	CH5 NCO Phase Offset in CW or DDC Mode - Upper Byte				CH5_NCO_	PHASE<15:8>					
0x92	CH6 NCO Phase Offset in CW or DDC Mode - Lower Byte				CH6_NCO	PHASE<7:0>					
0x93	CH6 NCO Phase Offset in CW or DDC Mode - Upper Byte				CH6_NCO_	PHASE<15:8>					
0x94	CH7 NCO Phase Offset in CW or DDC Mode - Lower Byte				CH7_NCO	PHASE<7:0>					
0x95	CH7 NCO Phase Offset in CW or DDC Mode - Upper Byte		CH7_NCO_PHASE<15:8>								
0x96	CH0 Digital Gain				CH0_DIG	_GAIN<7:0>					
0x97	CH1 Digital Gain				CH1_DIG						
0x98	CH2 Digital Gain				CH2_DIG						
0x99	CH3 Digital Gain					 GAIN<7:0>					

Legend: 2:

U = Unimplemented bit, read as '0' FCB = Factory-Controlled Bits. Do not program Read-only register. Preprogrammed at the factory for internal use.

TABLE 5-3: REGISTER MAP TABLE (CONTINUED)

Addr.Register Name0x9ACH4 Digital Gain0x9BCH5 Digital Gain0x9CCH6 Digital Gain				Bits				
Addr.	Register Name	b7	b6	b5	b4	b3	b2	b1
0x9A	CH4 Digital Gain				CH4_DIG_GA	IN<7:0>		I
0x9B	CH5 Digital Gain				CH5_DIG_GA	IN<7:0>		
0x9C	CH6 Digital Gain				CH6_DIG_GA	IN<7:0>		
0x9D	CH7 Digital Gain				CH7_DIG_GA	IN<7:0>		
0x9E	CH0 Digital Offset				CH0_DIG_OFF	SET<7:0>		
0x9F	CH1 Digital Offset				CH1_DIG_OFF	SET<7:0>		
0xA0	CH2 Digital Offset				CH2_DIG_OFF	SET<7:0>		
0xA1	CH3 Digital Offset				CH3_DIG_OFF	SET<7:0>		
0xA2	CH4 Digital Offset				CH4_DIG_OFF	SET<7:0>		
0xA3	CH5 Digital Offset				CH5_DIG_OFF	SET<7:0>		
0xA4	CH6 Digital Offset				CH6_DIG_OFF	SET<7:0>		
0xA5	CH7 Digital Offset				CH7_DIG_OFF	SET<7:0>		
0xA7	Digital Offset Weight Control		FCB<5:3> = 010		DIG_OFFSET_	WEIGHT<1:0>		FCB<2:0>
0xC0	Calibration Status Indication (Read only)	ADC_CAL_STAT			FCB	< 6:0> = 000-0000		
0xD1	PLL Calibration Status and PLL Drift Status Indication (Read only)	FCB<4:	3> = _{××}	PLL_CAL_STAT	FCB<2:	1> = _{XX}	PLL_VCOL_STAT	PLL_VCOF
0x15C	CHIP ID - Lower Byte ⁽²⁾ (Read only)				CHIP_ID<	7:0>		
0x15D	CHIP ID - Upper Byte ⁽²⁾ (Read only)				CHIP_ID<	15:8>		
I a mand	II - Unimplemented bit re-		Controlled Di	b Do not program	1 - bit is set 0 -	, hit is cleared	v – hitis unknown	

 Legend:
 U = Unimplemented bit, read as '0'
 FCB = Factory-Controlled Bits. Do not program
 1 = bit is set
 0 = bit is cleared
 x = bit is unknown

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 Read-only register. Preprogrammed at the factory for internal use.
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REGISTER 5-1: ADDRESS 0X00 – SPI BIT ORDERING AND ADC MODE SELECTION⁽¹⁾

R/W-0	R/W-0	R/W-1	R/W-0	R/W-0	R/W-1	R/W-0	R/W-0
SHUTDOWN	LSb_FIRST	SOFT_RESET	STANDBY	STANDBY	SOFT_RESET	LSb_FIRST	SHUTDOWN
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as	ʻ0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7	<pre>SHUTDOWN: Shutdown mode setting for power-saving⁽²⁾ 1 = ADC in Shutdown mode 0 = Not in Shutdown mode (Default)</pre>
bit 6	LSb_FIRST: Select SPI communication bit order 1 = Start SPI communication with LSb first 0 = Start SPI communication with MSb first (Default)
bit 5	SOFT_RESET: Soft Reset control bit ⁽³⁾ 1 = Not in Soft Reset mode (Default)0 = ADC in Soft Reset
bit 4	<pre>STANDBY: Send the device into a power-saving Standby mode⁽⁴⁾ 1 = ADC in Standby mode 0 = Not in Standby mode (Default)</pre>
bit 3	<pre>STANDBY: Send the device into a power-saving Standby mode⁽⁴⁾ 1 = ADC in Standby mode 0 = Not in Standby mode (Default)</pre>
bit 2	SOFT_RESET: Soft Reset control bit ⁽³⁾ 1 = Not in Soft Reset mode (Default) 0 = ADC in Soft Reset
bit 1	LSb_FIRST: Select SPI communication bit order 1 = Start SPI communication with LSb first 0 = Start SPI communication with MSb first (Default)
bit 0	SHUTDOWN: Shutdown mode setting for power-saving ⁽²⁾ 1 = ADC in Shutdown mode 0 = Not in Shutdown mode (Default)
Note	 Upper and lower nibble are mirrored, which makes the MSb- or LSb-first mode interchangeable. The lower nibble (bit <3:0>) has a higher priority when the mirrored bits have different values. During Shutdown mode, most of the internal circuits including the reference and clock are turned-off except for the SPI interface. When exiting from Shutdown (changing from '1' to '0'), executing the device Soft Reset simultaneously is highly recommended for a fast recalibration of the ADC. The internal user registers are not affected.
	3. This hit forces the device into Soft Reset mode, which initializes the internal calibration registers to their initial default states

3: This bit forces the device into Soft Reset mode, which initializes the internal calibration registers to their initial default states. The user-registers are not affected. When exiting Soft Reset mode (changing from '0' to '1'), the device performs an automatic device calibration including PLL calibration if PLL is enabled. DLL is reset if enabled. During Soft Reset, the device has the following states:

- no ADC output
- no change in power-on condition of internal reference
- most of the internal clocks are not distributed
- power consumption: (a) digital section negligible, (b) analog section no change
- 4: During Standby mode, most of the internal circuits are turned off except for the reference, clock and SPI interface. When exiting from Standby mode (changing from '1' to '0') after an extended amount of time, executing Soft Reset simultaneously is highly recommended. The internal user registers are not affected.

REGISTER 5-2: ADDRESS 0X01 – NUMBER OF CHANNELS, INDEPENDENCY CONTROL OF OUTPUT DATA AND CLOCK DIVIDER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-1	R/W-1	R/W-1	R/W-1
EN_DATCLK_IND	FCB<3>	S	EL_NCH<2:0>			FCB<2:0>	
bit 7							bit (
Legend:							
R = Readable bit		W = Writable bit	:	U = Unimplem	nented bit, read	as '0'	
-n = Value at POR		'1' = Bit is set		'0' = Bit is clea	ared	x = Bit is unknow	/n
bit 7	1 =Enabled0 =Disabled	IND: Enable data (Default)			-		
bit 6	FCB<3>: Facto	ory-Controlled Bit.	This is not for	the user. Do no	t change defau	It setting.	
bit 5-3	SEL_NCH<2:0 111 = 7 inputs 110 = 6 inputs 101 = 5 inputs 100 = 4 inputs 011 = 3 inputs 010 = 2 inputs 001 = 1 input (000 = 8 inputs	>: Select the tota	l number of inp	ut channels to t	be used ⁽²⁾		
bit 2-0	FCB<2:0>: Fac	ctory-Controlled B	Bits. This is not	for the user. Do	not change de	fault settings.	
_	_	ables OUT_CLKRA 7F (Registers 5-38		5	· · ·).	

REGISTER 5-3: ADDRESS 0X02 – OUTPUT DATA AND CLOCK RATE CONTROL⁽¹⁾

2: 1100 - 1010: Do not reprogram. These settings are used for the internal test only. If these bits are reprogrammed with different settings, the outputs will be in an undefined state.

3: Bits <3:0> become active if EN_DATCLK_IND = 1 in Address 0x01 (Register 5-2).

4: When no clock output is selected (Bits 1110 - 1010): clock output is not available at the DCLK+/DCLK- pins.

REGISTER 5-4: ADDRESS 0X04 – SPI SDO OUTPUT TIMING CONTROL

R/W-1	R/W-0	R/W-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
SDO_TIME				FCB<6:0>			
bit 7							bit 0
Legend:							
R = Readable bit		W = Writable bit		U = Unimplem	ented bit, read a	is '0'	

R = Readable bit	W = Writable bit	U = Unimplemented bit, read a	is '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

b	it	7

SDO_TIME: SPI SDO output timing control bit 1 = SDO output at the falling edge of clock (**Default**)

0 = SDO output at the rising edge of clock

bit 6-0

FCB<6:0>: Factory-Controlled Bits. This is not for the user. Do not change default settings.

REGISTER 5-5: ADDRESS 0X07 – OUTPUT RANDOMIZER AND WCK POLARITY CONTROL

R/W-0	R/W-1	R/W-1	R/W-0	R/W-0	R/W-0	R/W-1	R/W-0
POL_WCK	EN_AUTOCAL TIMEDLY	FCB<4:0>					EN_OUT_RANDOM
bit 7	bit 0						

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	d as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 POL_WCK: WCK polarity contro	bit ⁽¹⁾
------------------------------------	--------------------

- 1 = Inverted
- 0 = Not inverted (Default)
- bit 6 EN_AUTOCAL_TIMEDLY: Auto-calibration starter time delay counter control bit⁽²⁾
 - 1 = Enabled (Default)
 - 0 = Disabled

bit 5-1 **FCB<4:0>:** Factory-Controlled Bits. This is not for the user. Do not change default settings.

- bit 0 EN_OUT_RANDOM: Output randomizer control bit
 - 1 = Enabled: ADC data output is randomized
 - 0 = Disabled (Default)
- Note 1: See Address 0x68 (Register 5-26) for WCK/OVR pair control.
 - 2: This bit enables the AUTOCAL_TIMEDLY<7:0> settings. See Address 0x1E (Register 5-6).

REGISTER 5-6:	ADDR	ESS 0X1E – AUTO	CAL TIME	DELAY CONT	ROL ⁽¹⁾		
R/W-1	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
		А	UTOCAL_TI	MEDLY<7:0>			
bit 7							
Legend:							
R = Readable bit		W = Writable bit		U = Unimpleme	ented bit, read	as '0'	
-n = Value at POR		'1' = Bit is set		'0' = Bit is clear	ed	x = Bit is unknow	wn

bit 7-0 AUTOCAL_TIMEDLY<7:0>: Auto-calibration start time delay control bits

1111-1111 = Maximum value

1000-0000 = (Default)

•••

0000-0000 = Minimum value

Note 1: EN_AUTOCAL_TIMEDLY in Address 0x07 (Register 5-5) enables this register setting. This register controls the time delay before the auto-calibration starts. The value increases linearly with the bit settings, from minimum to maximum values.

REGISTER 5-7: ADDRESS 0X52 – DLL CONTROL

R/W-0	R/W-0	R/W-0	R/W-0	R/W-1	R/W-0	R/W-1	R/W-0
EN_DUTY	DCLK_PHDLY_DLL<2:0>		EN_DLL_DCLK	EN_DLL	EN_CLK	RESET_DLL	
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7		 EN_DUTY: Enable DLL circuit for duty cycle correction (DCC) of input clock 1 = Correction is ON 0 = Correction is OFF (Default)
bit 6-4	Ļ	DCLK_PHDLY_DLL<2:0>: Select the phase delay of the digital clock output when using DLL ⁽¹⁾ 111 = +315° phase-shifted from default 100 = +270° phase-shifted from default 101 = +225° phase-shifted from default 100 = +180° phase-shifted from default 011 = +135 phase-shifted from default 010 = +90° phase-shifted from default 011 = +45° phase-shifted from default 001 = (Default)
bit 3		 EN_DLL_DCLK: Enable DLL digital clock output 1 = Enabled (Default) 0 = Disabled: DLL digital clock is turned off. ADC output is not available when DLL is used.
bit 2		 EN_DLL: Enable DLL circuitry to provide a selectable phase clock to digital output clock. 1 = Enabled 0 = Disabled. DLL block is disabled (Default)
bit 1		 EN_CLK: Enable clock input buffer 1 = Enabled (Default). 0 = Disabled. No clock is available to the internal circuits, ADC output is not available.
bit 0		RESET_DLL : DLL circuit reset control ⁽²⁾ 1 = DLL is active 0 = DLL circuit is held in reset (Default)
Note	1: 2:	These bits have an effect only if EN_PHDLY = 1 and decimation is not used. DLL reset control procedure: Set this bit to '0' (reset) and then to '1'.

R/W-0

bit 0

REGISTER 5-8: ADDRESS 0X53 – CLOCK SOURCE SELECTION

R/W-0	R/W-1	R/W-0	R/W-0	R/W-0	R/W-1	R/W-0	R/W-1	
	FCB<6:4>		CLK_SOURCE		FC	3<3:0>		
bit 7							bit (
Legend:								
R = Readable bit W = Writable b		W = Writable bi	it U = Unimplemented bit, read as '0'					
-n = Value at POR		'1' = Bit is set		'0' = Bit is clear	red	x = Bit is unkn	known	
			Dite This is not for	the user De ret	ahanan dafa	ut a attice as		
bit 7-5	FCB<6:4>:1	-actory-Controlled	Bits. This is not for	the user. Do not	change defai	uit settings.		
bit 4	CLK_SOUR	CE: Select interna	al timing source					
	1 = PLL o	utput is selected a	s timing source					
	0 = Extern	al clock input is se	elected as timing sou	Irce (Default)				

bit 3-0 **FCB<3:0>:** Factory-Controlled Bits. This is not for the user. Do not change default settings.

REGISTER 5-9: ADDRESS 0X54 – PLL REFERENCE DIVIDER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0		
	PLL_REFDIV<7:0>								
bit 7							bit 0		

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0	PLL_REFDIV<7:0>: PLL Reference clock divider control bits ⁽¹⁾
	1111-1111 = PLL reference divided by 255 (if PLL_REFDIV<9:8> = 00)
	1111-1110 = PLL reference divided by 254 (if PLL_REFDIV<9:8> = 00)
	•••
	0000-0011 = PLL reference divided by 3 (if PLL_REFDIV<9:8> = 00)
	0000-0010 = Do not use (No effect)
	0000-0001 = PLL reference divided by 1 (if PLL_REFDIV<9:8> = 00)
	0000-0000 = PLL reference not divided (if PLL_REFDIV<9:8> = 00) (Default)

Note 1: PLL_REFDIV is a 10-bit wide setting. See Address 0x55 (Register 5-10) for the upper two bits and Table 5-4 for PLL_REF-DIV<9:0> bit settings. This setting controls the clock division ratio of the PLL reference clock (external clock input at the CLK pin) before the PLL phase-frequency detector circuitry. Note that the divider value of 2 is not supported. EN_PLL_REFDIV in Address 0x59 (Register 5-14) must be set.

REGISTER	R 5-10: A	DDRES	S 0X55 – PLL	OUTPUT AN	D REFERENC	E DIVIDER		
R/W-0	R/\	V-1	R/W-0	R/W-0	R/W-1	R/W-0	R/W-0	R/W-0
	PL	L_OUTD	V<3:0>		FCB<1:0>		PLL_REFD	V<9:8>
bit 7								bit 0
Legend:								
R = Readal	ole bit	,	W = Writable bit		U = Unimpleme	ented bit, read a	is '0'	
-n = Value a	at POR		1' = Bit is set		'0' = Bit is clear	ed	x = Bit is unknow	n
	0100 = 0011 = 0010 = 0001 = 0000 =	PLL outp PLL outp PLL outp PLL outp PLL outp	ut divided by 14 ut divided by 4 (ut divided by 3 ut divided by 2 ut divided by 1 ut not divided	Default)				
bit 3-2			,		or the user. Do no	0	It settings.	
bit 1-0			8>: Upper two N 5-4. (Default)	ISb bits of PLL_	_REFDIV<9:0> ⁽²)		
Note 1: 2:		x54 (<mark>Regi</mark>	ster 5-9) and Tabl				OUTDIV<3:0> settin EFDIV in Address 0x	

TABLE 5-4:EXAMPLE – PLL REFERENCE DIVIDER BIT SETTINGS VS. PLL REFERENCE INPUT
FREQUENCY

PLL_REFDIV<9:0>	PLL Reference Frequency
11-1111-1111	Reference frequency divided by 1023
11-1111-1110	Reference frequency divided by 1022
_	_
00-0000-0011	Reference frequency divided by 3
00-0000-0010	Do not use (not supported)
00-0000-0001	Reference frequency divided by 1
00-0000-0000	Reference frequency divided by 1

REGISTER 5-11: ADDRESS 0X56 – PLL PRESCALER (LSB)

R/W-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-0	R/W-0	R/W-0
			PLL_PF	RE<7:0>			
bit 7							bit 0
Legend:							

Logonan			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as	ʻ0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0	PLL_PRE<7:0>: PLL prescaler selection ⁽¹⁾ 1111-1111 = VCO clock divided by 255 (if PLL_PRE<11:8> = 0000) 0111-1000 = VCO clock divided by 120 (if PLL_PRE<11:8> = 0000) (Default)
	•••• 0000-0010 = VCO clock divided by 2 (if PLL_PRE<11:8> = 0000) 0000-0001 = VCO clock divided by 1 (if PLL_PRE<11:8> = 0000) 0000-0000 = VCO clock not divided (if PLL_PRE<11:8> = 0000)

Note 1: PLL_PRE is a 12-bit-wide setting. The upper four bits (PLL_PRE<11:8>) are defined in Address 0x57. See Table 5-5 for the PLL_PRE<11:0> settings. The PLL Prescaler is used to divide down the VCO output clock in the PLL phase-frequency detector loop circuit.

REGISTER 5-12: ADDRESS 0X57 – PLL PRESCALER (MSB)

R/W-0	R/W-1	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	FCB<3:0>			PLL_PRE<11:8>			
bit 7						bit 0	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as	'0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

```
bit 7-4 FCB<3:0>: Factory-Controlled Bits. This is not for the user. Do not change default settings.

bit 3-0 PLL_PRE<11:8>: PLL prescaler selection<sup>(1)</sup>

1111 = 2<sup>12</sup> - 1 (max), if PLL_PRE<7:0> = 0xFF

...

0000 = Default)
```

Note 1: PLL_PRE is a 12-bit-wide setting. See the lower eight bit settings (PLL_PRE<7:0>) in Address 0x56 (Register 5-11). See Table 5-5 for the PLL_PRE<11:0> settings for PLL feedback frequency.

TABLE 5-5: Example: PLL Prescaler Bit Settings and PLL Feedback Frequency

PLL_PRE<11:0>	PLL Feedback Frequency
1111-1111-1111	VCO clock divided by 4095 (2 ¹² - 1)
1111-1111-1110	VCO clock divided by 4094 (2 ¹² - 2)
_	-
0000-0000-0011	VCO clock divided by 3
0000-0000-0010	VCO clock divided by 2
0000-0000-0001	VCO clock divided by 1
0000-0000-0000	VCO clock divided by 1

REGISTER 5-13: ADDRESS 0X58 – PLL CHARGE-PUMP

R/W-0	R/W-0	R/W-0	R/W-1	R/W-0	R/W-0	R/W-1	R/W-0
	FCB<2:0>:		PLL_BIAS		PLL_CHAG	PUMP<3:0>	
bit 7							bit
Legend:							
R = Readable	e bit	W = Writable bi	t	U = Unimplemente	d bit, read as	s 'O'	
-n = Value at I	POR	'1' = Bit is set		'0' = Bit is cleared		x = Bit is unknown	
		sing coming from		(1.0) ()			
	0 = Bandga	p voltage from the	e reference gene	erator (1.2V)			
bit 3-0	PLL_CHAGP	UMP<3:0>: PLL o	0	s current control bit	s ⁽¹⁾		
bit 3-0	•	UMP<3:0>: PLL o	0	· ,	ş(1)		
bit 3-0	PLL_CHAGP	UMP<3:0>: PLL c num current	0	· ,	s ⁽¹⁾		
bit 3-0	PLL_CHAGP	UMP<3:0>: PLL c num current	0	· ,	s ⁽¹⁾		

increases linearly with increasing the bit setting values. The increase is from approximately 25 μA to 375 μA, 25 μA per step. See Section 4.7.2.1, "PLL Output Frequency and Output Control Parameters" for more details of the PLL block.

REGISTER 5-14: ADDRESS 0X59 – PLL ENABLE CONTROL 1

U-0	R/W-1	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-1
_	FCB<4:3>		EN_PLL_REFDIV	FCB<2:1>		EN_PLL	FCB<0>
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit	, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7	Unimplemented: Not used.
bit 6-5	FCB<4:3>: Factory-Controlled Bits. This is not for the user. Do not change default settings.
bit 4	 EN_PLL_REFDIV: Enable PLL Reference Divider (PLL_REFDIV<9:0>). 1 = Enabled 0 = Reference divider is bypassed (Default)
bit 3-2	FCB<2:1>: Factory-Controlled Bits. This is not for the user. Do not change default settings.
bit 1	<pre>EN_PLL: Enable PLL circuit. 1 = Enabled 0 = Disabled (Default)</pre>
bit 0	FCB<0>: Factory-Controlled Bit. This is not for the user. Do not change default setting.

REGISTER 5-15: ADDRESS 0X5A – PLL LOOP FILTER RESISTOR

U-0	R/W-0	R/W-1	R/W-0	R/W-1	R/W-1	R/W-1	R/W-1
—	FCB	<1:0>			PLL_RES<4:0>	•	
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as	ʻO'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7	Unimplemented: Not used.
bit 6-5	FCB<1:0>: Factory-Controlled Bits. This is not for the user. Do not change default settings.
bit 4-0	PLL_RES<4:0>: Resistor value selection bits for PLL loop filter ⁽¹⁾ 11111 = Maximum value 01111= (Default) 00000 = Minimum value

Note 1: PLL_RES<4:0> should be set based on the phase detector comparison frequency. The resistor value increases linearly with the bit settings, from minimum to maximum values. See the PLL loop filter section in Section 4.7, "ADC Clock Selection".

REGISTER 5-16: ADDRESS 0X5B – PLL LOOP FILTER CAP3

U-0	R/W-0	R/W-1	R/W-0	R/W-0	R/W-1	R/W-1	R/W-1
—	FCB	<1:0>			PLL_CAP3<4:0	>	
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as	'0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7		Unimplemented: Not used.
bit 6-5		FCB<1:0>: Factory-Controlled Bits. This is not for the user. Do not change default settings.
bit 4-0		PLL_CAP3<4:0>: Capacitor 3 value selection bits for PLL loop filter ⁽¹⁾
		11111 = Maximum value
		00111= (Default)
		00000 = Minimum value
Note 1	l:	This capacitor is in series with the shunt resistor, which is set by PLL_RES<4:0>. The capacitor value increases linearly with the

Note 1: This capacitor is in series with the shunt resistor, which is set by PLL_RES<4:0>. The capacitor value increases linearly with the bit settings, from minimum to maximum values. This setting should be set based on the phase detector comparison frequency.

REGISTER 5-17: ADDRESS 0X5C – PLL LOOP FILTER CAP1

U-0	R/W-0	R/W-1	R/W-0	R/W-0	R/W-1	R/W-1	R/W-1
_	FCB<1:0>		PLL_CAP1<4:0>				
bit 7 bit				bit 0			

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, re	ead as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7	Unimplemented: Not used.
bit 6-5	FCB<1:0>: Factory-Controlled Bits. This is not for the user. Do not change default settings.
bit 4-0	PLL_CAP1<4:0>: Capacitor 1 value selection bits for PLL loop filter ⁽¹⁾
	11111 = Maximum value
	••••
	00111 = (Default)
	••••
	00000 = Minimum value
Note 1:	This capacitor is located between the charge pump output and ground, and in parallel with the shunt resistor which is defined

Note 1: This capacitor is located between the charge pump output and ground, and in parallel with the shunt resistor which is defined by the PLL_RES<4:0>. The capacitor value increases linearly with the bit settings, from minimum to maximum values. This setting should be set based on the phase detector comparison frequency.

REGISTER 5-18: ADDRESS 0X5D – PLL LOOP FILTER CAP2

U-0	R/W-0	R/W-1	R/W-0	R/W-0	R/W-1	R/W-1	R/W-1
—	FCB	<1:0>			PLL_CAP2<4:0	>	
bit 7							bit 0

Legend:				
R = Readable bit	W = Writable bit	U = Unimplemented bit, r	ead as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown	

bit 7	Unimplemented: Not used.
bit 6-5	FCB<1:0>: Factory-Controlled Bits. This is not for the user. Do not change default settings.
bit 4-0	PLL_CAP2<4:0>: Capacitor 2 value selection bits for PLL loop filter ⁽¹⁾
	11111 = Maximum value
	•••
	00111 = (Default)
	•••
	00000 = Minimum value
Note 1:	This capacitor is located between the charge pump output and ground, and in parallel with CAP1 which is defined by the PLL

Note 1: This capacitor is located between the charge pump output and ground, and in parallel with CAP1 which is defined by the PLL_-CAP1<4:0>. The capacitor value increases linearly with the bit settings, from minimum to maximum values. This setting should be set based on the phase detector comparison frequency.

REGISTER 5-19	: ADDRES	SS 0X5F – PLL	ENABLE CO	ONTROL 2 ⁽¹⁾			
R/W-1	R/W-1	R/W-1	R/W-1	R/W-0	R/W-0	R/W-0	R/W-1
	FCB<	5:2>		EN_PLL_OUT	EN_PLL_BIAS	FCB<1	:0>
bit 7							bit C
Lanandi							
Legend: R = Readable bit		W = Writable bit		U = Unimplem	ented bit, read as	ʻ0'	
-n = Value at POF	n = Value at POR '1' = Bit is set			'0' = Bit is cleared x = Bit is unknown			n
bit 7-4 bit 3		Enable PLL output		or the user. Do n	ot change the def	ault settings.	
bit 2	1 = Enabled 0 = Disabled (,					
bit 1-0					ot change default	0	
Note 1: To ena	able PLL output, E	N_PLL_OUT, EN_I	PLL_BIAS and	EN_PLL in Addre	ess 0x59 (Register §	5-14) must be set.	

U-0	R/W-0	R/W-0	R/W-1	R/W-0	R/W-0	R/W-0	R/W-0
_	FCB	DATA_FORMAT	OUTPUT	MODE<1:0>	TES	T_PATTERNS<	2:0>
oit 7							bit
_egend:							
	dable bit	W = Writable bit		U = Unimplem			
n = Valu	e at POR	'1' = Bit is set		'0' = Bit is clea	ared	x = Bit is unkn	lown
oit 7	Unimplomo	nted: Not used.					
	-		a not for the	user De net eb	ange defeult	ootting	
bit 6		y-controlled bit. This i			ange delauit	setting.	
bit 5		MAT: Output data form	hat selection				
		binary (unsigned) complement (Default)					
bit 4-3		ODE<1:0>: Output m		- (1)			
л 4-5		use. Output is undefin		1. /			
		DDR LVDS output mo		n bit first ⁽²⁾ (Defa	ult)		
		CMOS output mode		,	,		
	00 = Output	disabled					
oit 2-0		ERNS<2:0>: Test out					
		t data is pseudo-rand		(PN) sequence ⁽	4)		
		Pattern for LVDS outp					
		tput: '11111111 000					
		ating Sequence for LV tput: '01010101 101					
		ating Sequence for C					
		tput: '111111111 111		g with '000000	0000'		
		ating Sequence for C		0			
		tput: ' 01010101 010					
		Pattern: Output (Q0)	is increment	ted by1 LSB per	64 clock cyc	les ⁽⁵⁾	
		e Custom Patterns	ana nattaria A		- 0X74 0X		
		tput: Alternating custo d custom pattern B (se					5 5-29 -5-30
		al Operation. Output:			legisters 5-51	- 3-32)**	
Note 1:		-2-2 for the timing dia	•				
2:		0, Q8, Q6, Q4, Q2, Q					
		1, Q9, Q7, Q5, Q3, Q					
3:	See Section 4.4	12.12 "Output Test P	atterns" for	more details.			
		: only the active pins (
		de: all data output pin		output test pins	(TP), OVR a	nd WCK pins	are active,
		disabled by register set		his tost the suit		a a a draw a str	a automatif
		test pins (TP) can toget ed to the supply pin of					
	•	ea to the supply pill (or ground. I			ws, aiways lea	
	pins floating (not	connected)					
4:	pins floating (not Pseudo-random	connected). number (PN) code is	generated b	v the linear feed	lback shift re	gister (LFSR).	See

5: OVR and WCK bits are incremented by 1 per 219 and 218 clock cycles, respectively.

6: Pattern A<11:0> and B<11:0> are applied to Q<11:0>. Q11 = OVR, Q10 = WCK.

REGISTER 5	5-21:	ADDRESS 0X63 -	- LVDS OUTPU	JT LOAD AND DRI	VER CURREN	T CONTROL	
R/W-0	R/W-	0 R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-1
FCB<3:0>				LVDS_LOAD	LVI	DS_IMODE<2:	:0>
bit 7							bit 0
Legend:							
R = Readab	le bit	W = Writable	e bit	U = Unimplement	ted bit, read as	'0'	
-n = Value a	t POR	'1' = Bit is se	et	'0' = Bit is cleared	t	x = Bit is unk	nown
bit 3	1 = En 0 = Dis	OAD: Internal LVE hable internal load sable internal load	termination termination (De	efault)			
bit 2-0	111 = 7. 011 = 5. 001 = 3. 000 = 1. Do not u	4 mA 5 mA (Default)		control bits			
Note 1: D			ese settings ca	n result in unknowr	n output curren	ts.	

Note 1: Do not use these settings. These settings can result in unknown output currents.

REGISTER 5-22:	ADDRESS 0	X64 – OUTPl	JT CLOCK PH	IASE CONTRO	DL WHEN DE	CIMATION FIL	TER IS USED	
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-1	R/W-1	
EN_PHDLY	DCLK	_PHDLY_DEC	<2:0>		FCB	<3:0>		
bit 7				·			bit (
Legend:								
R = Readable bit		W = Writable b	oit	U = Unimplem	ented bit, read	as '0'		
-n = Value at POR		'1' = Bit is set		'0' = Bit is clea	red	x = Bit is unkr	nown	
	111 = +315° ph 110 = +270° ph	- ase-shifted fro	m default ⁽²⁾					
bit 6-4			•	ck phase delay o	control when de	cimation filter is	used ⁽²⁾	
		101 = +225° phase-shifted from default ⁽²⁾ 100 = +180° phase-shifted from default						
		011 = +135° phase-shifted from default ⁽²⁾						
	010 = +90° pha							
	001 = +45° pha 000 = Default⁽³							
bit 3-0			Bits. This is no	ot for the user. D	o not change de	efault settings.		
	ts have an effect on ilable when the decir	· —		• •	,			

2. Only available when the decimation inter setting is greater than 2. When Pir_AB <0.12 = 0.5 (default) and Pir_AC2 = 0, only 4 = phase shifts are available (+45°, +135°, +225°, +315°) from default. See Addresses 0x7A, 0x7B and 0x7C (Registers 5-35 – 5-37). See Addresses 0x6D and 0x52 (Registers 5-28 and 5-7) for DCLK phase shift for other modes.</p>

3: The phase delay for all other settings is referenced to this default phase.

REGISTER 5-23: ADDRESS 0X65 – LVDS OUTPUT POLARITY CONTROL

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
POL_LVDS<5:0>							ECT<1:0>
bit 7	bit 7						

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as	s 'O'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-2	POL_LVDS<5:0>: Control polarity of LVDS data pairs (Q5+/Q5- – Q0+/Q0-) 111111 = Invert all LVDS pairs 111110 = Invert all LVDS pairs except the LSb pair
	100000 = Invert MSb LVDS pair
	•••
	000001 = Invert LSb LVDS pair 000000 = No inversion of LVDS bit pairs (Default)
bit 1-0	NO EFFECT<1:0>: No effect bits.

REGISTER 5-22: ADDRESS 0X64 – OUTPUT CLOCK PHASE CONTROL WHEN DECIMATION FILTER IS USED

REGISTER 5-24: ADDRESS 0X66 – DIGITAL OFFSET CORRECTION (LOWER BYTE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			DIG_OFFSET_0	GLOBAL<7:0>			
bit 7							bit 0
Legend:							

Logona.			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as	ʻ0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0

DIG_OFFSET_GLOBAL<7:0>: Lower byte of DIG_OFFSET_GLOBAL<15:0> for all channels⁽⁻⁾ 0000-0000 = **Default**

-Offset is added to the ADC output. Setting is two's complement using two combined registers (16-bits wide). Setting range: $(-2^{15} \text{ to } 2^{15} - 1) \times 0.125 \text{ LSb}(s)$

REGISTER 5-25: ADDRESS 0X67 – DIGITAL OFFSET CORRECTION (UPPER BYTE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0			
DIG_OFFSET_GLOBAL<15:8>									
bit 7									
	R/W-0								

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, r	ead as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 DIG_OFFSET_GLOBAL<15:8>: Upper byte of DIG_OFFSET_GLOBAL<15:0> for all channels⁽¹⁾

0000-0000 = **Default**

Note 1: See Note - in Address 0x66 (Register 5-24)

REGISTER 5-26: ADDRESS 0X68 – WCK AND OVR BIT CONTROL

R/W-0	R/W-0	R/W-1	R/W-0	R/W-0	R/W-1	R/W-0	R/W-0
FCB<5:2>			POL_WCK_OVR	EN_WCK_OVR	FC	B<1:0>	
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-4 **FCB<5:2>:** Factory-controlled bits. This is not for the user. Do not change default settings.

bit 3 **POL_WCK_OVR**: Polarity control for WCK and OVR bit pair in LVDS mode

1 = Inverted

- 0 = Not inverted (Default)
- bit 2 EN_WCK_OVR: Enable WCK and OVR output bit pair
 - 1 = Enabled (Default)
 - 0 = Disabled
- bit 1-0 **FCB<1:0>:** Factory-controlled bits. This is not for the user. Do not change default settings.

REGISTER 5-27: ADDRESS 0X6B – PLL CALIBRATION

R/W-0	R/W-0	R/W-0	R/W-0	R/W-1	R/W-0	R/W-0	R/W-0
		FCB<6:2>		PLL_CAL_TRIG	FCB	<1:0>	
bit 7							bit 0
Logond							

Legena:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-3 FCB<6:2>: Factory-Controlled Bits. This is not for the user. Do not change default settings.

bit 2 **PLL_CAL_TRIG**: Manually force recalibration of the PLL at the state of bit transition⁽¹⁾ Toggle from "1" to "0", or "0" to "1" = Start PLL calibration

bit 1-0 **FCB<1:0>:** Factory-Controlled Bits. This is not for the user. Do not program.

Note 1: See PLL_CAL_STAT in Address 0xD1 (Register 5-81) for calibration status indication.

REGISTER 5-28: ADDRESS 0X6D – PLL OUTPUT AND OUTPUT CLOCK PHASE⁽¹⁾

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
— E		EN_PLL_CLK	FCB<1>	DCL	_K_DLY_PLL<2	::0>	FCB<0>
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 Unimplemented: Not used

bit 5 EN PLL CLK: Enable PLL output clock

- 1 = PLL output clock is enabled to the ADC core
 - 0 = PLL clock output is disabled (Default)
- bit 4 **FCB<1>:** Factory-Controlled Bit. This is not for the user. Do not change default settings.

bit 3-1 DCLK_DLY_PLL<2:0>: Output clock is delayed by the number of VCO clock cycles from the nominal PLL output⁽²⁾ 111 = Delay of 15 cycles

- 110 = Delay of 14 cycles
- •••
- 001 = Delay of one cycle
- 000 = No delay (Default)
- bit 0 FCB<0>: Factory-Controlled Bit. This is not for the user. Do not change default setting.
- **Note 1:** This register has effect only when the PLL clock is selected by the CLK_SOURCE bit in Address 0x53 (Register 5-8) and PLL circuit is enabled by EN_PLL bit in Address 0x59 (Register 5-14).
 - 2: This bit setting enables the output clock phase delay. This phase delay control option is applicable when PLL is used as the clock source and the decimation is not used.

REGISTER 5-29: ADDRESS 0X74 – USER-DEFINED OUTPUT PATTERN A (LOWER NIBBLE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	PATTERN	_A<3:0>		Do ne	ot use (Leave t	hese bits as '0	000')
bit 7							bit 0
Legend:							
R = Readable bit		W = Writable bit		II = Unimpleme	ented hit read as	' Ω'	

R = Readable bit		O = Onimplemented bit, read as	0
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-4 **PATTERN_A<3:0>:** Lower nibble of PATTERN_A<11:0>⁽¹⁾

bit 3-0 **Do not use:** Leave these bits to default settings ('0000')⁽²⁾

Note 1: See PATTERN_A<11:4> in Address 0x75 (Register 5-30) and TEST_PATTERNS<2:0> in Address 0x62 (Register 5-20).

2: The output from these bit settings is on "Unused Output Pattern Test Pins", which are recommended to be not connected to the host device. Therefore, the effect of these bit settings is not monitored. Leave these bits as default settings ('0000') all the time.

REGISTER 5-30: ADDRESS 0X75 – USER-DEFINED OUTPUT PATTERN A (UPPER BYTE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			PATTERN	_A<11:4>			
bit 7							bit 0
Legend:							
R = Readable bit		W = Writable bit		U = Unimpleme	ented bit, read as	'0'	

-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 7-0 **PATTERN_A<11:4>:** Upper byte of PATTERN_A<11:0>⁽¹⁾

Note 1: See PATTERN_A<3:0> in Address 0x74 (Register 5-29) and TEST_PATTERNS<2:0> in Address 0x62 (Register 5-20).

REGISTER 5-31: ADDRESS 0X76 – USER-DEFINED OUTPUT PATTERN B (LOWER NIBBLE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	PATTERN	_B<3:0>		Do no	ot use (Leave	hese bits as '00	000 ')
bit 7							bit 0
Legend:							
R = Readable bit		W = Writable bit		U = Unimpleme	nted bit, read as	s 'O'	
-n = Value at POR		'1' = Bit is set		'0' = Bit is cleare	ed	x = Bit is unknow	wn

bit 7-4 **PATTERN_B<3:0>:** Lower nibble of PATTERN_B<11:0>⁽¹⁾

bit 3-0 **Do not use:** Leave these bits to default settings ('0000')⁽²⁾

Note 1: See PATTERN_B<11:4> in Address 0x77 (Register 5-32) and TEST_PATTERNS<2:0> in Address 0x62 (Register 5-20).

2: The output from these bit settings is on "Unused Output Pattern Test Pins", which are recommended to be not connected to the host device. Therefore, the effect of these bit settings is not monitored. Leave these bits as default settings ('0000') all the time.

REGISTER 5-32: ADDRESS 0X77 – USER-DEFINED OUTPUT PATTERN B (UPPER BYTE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			PATTERN_	_B<11:4>			
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as	; 'O'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 **PATTERN_B<11:4>:** Upper byte of PATTERN_B<11:0>⁽¹⁾

Note 1: See PATTERN_B<3:0> in Address 0x76 (Register 5-31) and TEST_PATTERNS<2:0> in Address 0x62 (Register 5-20).

REGISTER 5-33: ADDRESS 0X78 – NOISE-SHAPING REQUANTIZER RESET CONTROL AND CHANNEL A FILTER (NSRA)⁽¹⁾

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
NSR_RESET				NSRA<6:0>			
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7	NSR_RESET: Toggle of this bit causes a reset of the NSRA and NSRB state. - Toggle from '1' to '0' or from '0' to '1' = Reset of NSRA and NSRB ⁽²⁾
	- Otherwise = No effect (Default)
bit 6-0	NSRA<6:0>: NSRA filter settings. See Tables 4-13 to 4-14 for the NSR filter settings ⁽³⁾
	000-0000 = (Default)

Note 1: This register is used for single- and dual-channel modes only.

- 2: The NSR filter will be also automatically reset if the filter setting is changed.
- 3: In dual-channel mode, NSRA<6:0> is used for channel A.

REGISTER 5-34: ADDRESS 0X79 – DUAL-CHANNEL DIGITAL SIGNAL POST-PROCESSING CONTROL AND NOISE-SHAPING REQUANTIZER CHANNEL B FILTER (NSRB)⁽¹⁾

						,	
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
EN_DSPP_2				NSRB<6:0>	>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, re	ead as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

EN_DSPP_2: Enable digital post-processing functions for dual-channel operations 1 = Enabled

- 0 = Disabled (Default)
- bit 6-0 NSRB<6:0>: NSRB filter settings. See Tables 4-13 to 4-14 for the NSR filter settings⁽²⁾ 000-0000 = (Default)

Note 1: This register is used for single- and dual-channel modes only.

2: In dual-channel mode, NSRB<6:0> is used for channel B.

REGISTER	R 5-35: A	DDRESS 0X	7A – FIR_A	0 FILTER, FDR A	ND NSR CONTR	80L ⁽¹⁾		
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
FCB<1>	FIR_A<0>	EN_FDR	FCB<0>	EN_NSRB_11	EN_NSRB_12	EN_NSRA_11	EN_NSRA_12	
bit 7						•	bit 0	
Legend:								
R = Readab	ole bit	W = Writable	bit	U = Unimplemente	d bit, read as '0'			
-n = Value a	at POR	'1' = Bit is se		'0' = Bit is cleared		x = Bit is unknow	'n	
bit 7 bit 6	FIR_A<0>: E 1 = Enable	nable the first		not for the user. Do n n (Stage 1A in FIR A)	Ũ			
bit 5	 EN_FDR: Enable fractional delay recovery (FDR) option 1 = Enabled (with delay of 59 clock cycles). 0 = Disabled (Default) 							
bit 4	FCB<0>: Fac	ctory-Controlle	d Bit. This is	not for the user. Do n	ot change default s	setting.		
bit 3	1 = Enable		it noise-shap	ing requantizer for C	hannel B			
bit 2	1 = Enable		bit noise-shap	ing requantizer for C	hannel B			
bit 1	1 = Enable		it noise-shap	ing requantizer for C	hannel A			
bit 0	1 = Enable		bit noise-shap	oing requantizer for C	hannel A			
Note 1:	This register is	used only for si	ngle- and dua	l-channel modes.				

2: This is the LSb of the FIR A filter settings. For the first 2x decimation, set FIR_A<0> = 1 for single-channel operation, and FIR_A<0> = 0 for dual-channel operation. See Address 0x7B (Register 5-36) for FIR_A<8:1> settings.

REGISTER 5-36: ADDRESS 0X7B – FIR A FILTER^(1,5)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
				FIR_A<8:1>			
bit 7							bit (
Legend:							
R = Reada	able bit	W = Writable I	oit	U = Unimplemen	ted bit, read as	'0'	
-n = Value	at POR	'1' = Bit is set		'0' = Bit is cleared	d	x = Bit is unknown	
bit 7-0	FIR A<8.1>	Decimation Filte	er FIR A setti	ngs for Channel A (c	or ()(2)		
	Single-Cha	nnel Mode: ⁽³⁾			,,,,,		
	FIR_A<8:0>						
	_	11 = Stage 1 - 9 f	ilters (decima	ation rate: 512)			
	0-1111-11	11 = Stage 1 - 8 f	ilters				
	0-0111-11	11 = Stage 1 - 7 f	ilters				
		11 = Stage 1 - 6 f					
		11 = Stage 1 - 5 f					
		11 = Stage 1 - 4 f					
		11 = Stage 1 - 3 f					
		11 = Stage 1 - 21		,			
		01 = Stage 1 filte					
	0-0000-00 Dual-Chanr	00 = Disabled all	FIR A flitters.	(Default)			
	FIR A<8:0>						
	_	10 = Stage 2 - 91	ilters (decim	ation rate: 256)			
		10 = Stage 2 - 8 1		200)			
		10 = Stage 2 - 7 f					
		10 = Stage 2 - 6 f					
	0-0001-11	10 = Stage 2 - 5 f	ilters				
	0-0000-11	10 = Stage 2 - 4 f	ilters				
	0-0000-01	10 = Stage 2 - 3 f	ilters				
	0-0000-00	10 = Stage 2 filte	r (decimation	rate = 2)			
	0 - 0 0 0 0 - 0 0	00 = Disabled all	FIR A filters.	(Default)			
Note 1:	This register is	used only for single	e and dual-ch	annel modes. The reg	ister values are	thermometer encoded.	
2:	FIR_A<0> is pla	aced in Address 0x	7A (Register	5-35).			
-			CH 1.		A line A al al an a A		

- 3: In single-channel mode, the 1st stage filter is selected by FIR_A<0> = 1 in Address 0x7A (Register 5-35).
- 4: In dual-channel mode, the 1st stage filter is disabled by setting FIR_A<0> = 0 in Address 0x7A.
- 5: SNR is improved by approximately 2.5 dB per each filter stage, and output data rate is reduced by a factor of two per stage. The data and clock rates in Address 0X02 (Register 5-3) need to be updated accordingly. Address 0x64 (Register 5-22) setting is also affected. The maximum decimation rate for the single-channel mode is 512, and 256 for the dual-channel mode.

REGISTER 5-37: ADDRESS 0X7C – FIR B FILTER^(1,2)

					DAA/ O		
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
				FIR_B<7:0>			
bit 7							bit (
Legend:							
R = Readabl	e bit	W = Writable bit U = Unimplemented bit, read as '0'					
-n = Value at	POR	'1' = Bit is set		'0' = Bit is cleared x = Bit is unknow			
bit 7-0	FIR_B<7:0>:	Decimation Filte	r FIR B settings	for Channel B (or	r Q) ⁽³⁾		
	1111-1111:	= Stage 2 - 9 filte	ers (decimation	rate = 256)			
	0111-1111:	= Stage 2 - 8 filte	ers				
	0011-1111 =	= Stage 2 - 7 filte	ers				

0001-1111 = Stage 2 - 6 filters 0000-1111 = Stage 2 - 5 filters 0000-0111 = Stage 2 - 4 filters 0000-0011 = Stage 2 - 3 filters 0000-0001 = Stage 2 filter (decimation rate = 2) 0000-0000 = Disabled all FIR B Filters. (Default)

Note 1: This register is used for the dual-channel mode only. The register values are thermometer encoded.

2: EN_DSPP_2 bit in Address 0x79 (Register 5-34) must be set when using decimation in dual-channel mode.

3: SNR is improved by approximately 2.5 dB per each filter stage, and output data rate is reduced by a factor of two per stage. The data and clock rates in Address 0X02 (Register 5-3) need to be updated accordingly. Address 0x64 (Register 5-22) setting is also affected. The maximum decimation factor for the dual-channel mode is 256.

REGISTER 5-38: ADDRESS 0X7D – AUTO-SCAN CHANNEL ORDER (LOWER BYTE)

R/W-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-0	R/W-0	R/W-0
			CH	I_ORDER<7:0>			
bit 7							bit 0
Legend:							
R = Readable bi	it	W = Writable bit		U = Unimplement	ed bit, read as ')'	
-n = Value at PC	R	'1' = Bit is set		'0' = Bit is cleared	i	x = Bit is unknown	

bit 7-0 CH_ORDER<7:0>: Lower byte of CH_ORDER<31:0>⁽¹⁾

0111-1000 **= Default**

Note 1: See Table 5-3 for the channel order selection. See SEL_NCH<2:0> in Address 0x01 (Register 5-2) for the number of channels to be selected.

REGISTER 5-39: ADDRESS 0X7E – AUTO-SCAN CHANNEL ORDER (MIDDLE BYTE)

R/W-1	R/W-0	R/W-1	R/W-0	R/W-1	R/W-1	R/W-0	R/W-0
			CH_	_ORDER<15:8>			
bit 7							bit
Legend:							
R = Readable I	oit	W = Writable bit		U = Unimplemente	ed bit_read as '	0'	
R - Reauable i	510					•	

bit 7-0 CH_ORDER<15:8>: Middle byte of CH_ORDER<31:0>⁽¹⁾

1010-1100 **= Default**

Note 1: See Table 5-3 for the channel order selection. See SEL_NCH<2:0> in Address 0x01 (Register 5-2) for the number of channels to be selected.

REGISTER 5-40: ADDRESS 0X7F – AUTO-SCAN CHANNEL ORDER (UPPER BYTE)

R/W-1	R/W-0	R/W-0	R/W-0	R/W-1	R/W-1	R/W-1	R/W-0
			CH_	ORDER<23:16>			
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0)'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 CH_ORDER<23:16>: Upper byte of CH_ORDER<31:0>⁽¹⁾

1000-1110 **= Default**

Note 1: See Table 5-3 for the channel order selection. See SEL_NCH<2:0> in Address 0x01 (Register 5-2) for the number of channels to be selected.

REGISTER 5-41: ADDRESS 0X80 – DIGITAL DOWN-CONVETER CONTROL 1⁽¹⁾

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
HBFILTER_B	HBFILTER_A	EN_NCO	EN_AMPDITH	EN_PHSDITH	EN_LFSR	EN_DDC_FS/8	EN_DDC1
bit 7							bit 0

Legend:				
R = Reada	able bit	W = Writable bit	U = Unimplemented bit, r	read as '0'
-n = Value	at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown
bit 7	1 = Se	ER_B: Select half-bandwidth filte elect High-Pass filter at DDC outp elect Low-Pass filter at DDC outp	but	lual-channel mode ⁽²⁾
bit 6	1 = Se	ER_A: Select half-bandwidth filte elect High-Pass filter at DDC outp elect Low-Pass filter at DDC outp	but	
bit 5	1 = Er	D: Enable NCO of DDC1 nabled sabled (Default)		
bit 4	1 = Er	PDITH: Enable amplitude ditherir nabled sabled (Default)	ng for NCO ^(3, 4)	
bit 3	1 = Er	SDITH: Enable phase dithering fo nabled sabled (Default)	or NCO ^(3, 4)	
bit 2	1 = Er	SR: Enable linear feedback shift re nabled sabled (Default)	egister (LFSR) for amplitude and	phase dithering for NCO
bit 1	1 = Er	C_FS/8: Enable NCO for the DDC nabled sabled (Default)	C2 to center the DDC output signa	al to be around f _S /8/DER ⁽⁵⁾
bit 0	1 = Er	C1: Enable digital down conver nabled ⁽⁶⁾ sabled (Default)	ter 1 (DDC1)	
Note 1: 2: 3: 4: 5: 6:	This filter inclu -Single-cha -Dual-char This requires EN_AMPDITH DER is the de	s used for single-, dual- and octal-cl udes a decimation of 2. annel mode: HBFILTER_A is used. anel mode: Both HBFILTER_A and I the LFSR to be enabled: EN_LFSR I = 1 and EN_PHSDITH = 1 are red cimation rate defined by FIR A or F	HBFILTER_B are used. =1 commended for the best performance	ce. abled (disabled), output is I/Q data.

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
FDR_BAN	ID EN_DDC2	GAIN_HBF_DDC	SEL_FDR	EN_DSPP_8	8CH_CW	GAIN_8CH	l<1:0>
bit 7							bit
Legend:							
R = Readab	le hit	W = Writable bit		U = Unimpleme	ented bit read	as '0'	
-n = Value a		'1' = Bit is set		'0' = Bit is clear	-	x = Bit is unknown	
bit 7	—	Select 1st or 2nd Nyq	uist band				
	,	quist band juist band (Default)					
bit 6	5	nable DDC2 after the	digital half-har	nd filter (HBE) in I	DDC		
bit 0	1 = Enable		aigitai nan-bai		000.		
	0 = Disable	d (Default)					
bit 5	GAIN_HBF_[DDC: Gain selection for	or the output of	f the digital half-b	and filter (HBF) in DDC ⁽¹⁾	
	1 = x2 0 = x1 (Def	out)					
bit 4	•	elect fractional delay re		,			
DIL 4	1 = FDR fo)			
		r dual-channel (Defau	lt)				
bit 3	EN_DSPP_8	: Enable digital signal	post-processin	ig (DSPP) feature	es for 8-channe	el operation ⁽²⁾	
	1 = Enable	-					
		d (Default)		. (2 3)			
bit 2	1 = Enable	able CW mode in octa	al-channel moo	le ^(2, 3)			
		d (Default)					
bit 1-0	GAIN 8CH<1	I:0>: Select gain facto	r for CW signa	I in octal-channe	l modes.		
	—	= x4, 01 = x2, 00 = x1	-				
	· · · · · · · · · · · · · · · · · · ·	'Decimation Filters"					
2:	, ,	the phase offset correct obal setting bit to enable			· ·	,	abled.
3:		enabled, the ADC output					fter each
		ase offset, digital gain, a			ing the Address	ses 0x86 - 0xA7 (<mark>Reg</mark>	isters 5-47 f

REGISTER 5-42: ADDRESS 0X81 – DIGITAL DOWN-CONVERTER CONTROL 2

5-79). The result is similar to the beamforming in the phased-array sensors.

REGISTER 5-43: ADDRESS 0X82 – NUMERICALLY CONTROLLED OSCILLATOR TUNING (LOWER BYTE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			NC	C_TUNE<7:0>			
bit 7							bit
Legend:							
Legend: R = Readable	bit	W = Writable bit		U = Unimplemente	ed bit, read as '	D,	

bit 7-0 NCO_TUNE <7:0>: Lower byte of NCO_TUNE<31:0>⁽¹⁾

0000-0000 = DC (0 Hz) when NCO_TUNE<31:0> = 0x00000000 (Default)

Note 1: See Note 1 and Note 2 in Address 0x85 (Register 5-46).

REGISTER 5-44: ADDRESS 0X83 – NUMERICALLY CONTROLLED OSCILLATOR TUNING (MIDDLE-LOWER BYTE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			NCO	O_TUNE<15:8>			
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0)'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 NCO_TUNE<15:8>: Middle lower byte of NCO_TUNE<31:0>⁽¹⁾

0000-0000 **= Default**

Note 1: See Note 1 and Note 2 in Address 0x85 (Register 5-46).

REGISTER 5-45: ADDRESS 0X84 – NUMERICALLY CONTROLLED OSCILLATOR TUNING (MIDDLE-UPPER BYTE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			NCC	D_TUNE<23:16>			
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0	,
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 NCO_TUNE<23:16>: Middle upper byte of NCO_TUNE<31:0>⁽¹⁾ 0000-0000 = Default

Note 1: See Note 1 and Note 2 in Address 0x85 (Register 5-46).

REGISTER 5-46: ADDRESS 0X85 – NUMERICALLY CONTROLLED OSCILLATOR TUNING (UPPER BYTE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			NCC	D_TUNE<31:24>			
bit 7							bit 0
Legend:							
R = Readable	bit	W = Writable bit		U = Unimplemen	ted bit, read as '0	,	
-n = Value at F	POR	'1' = Bit is set		'0' = Bit is cleared	d	x = Bit is unknown	

^{1111-1111 =} f_S if NCO_TUNE<31:0> = 0xFFFF FFFF • • •

0000-0000 = **Default**

Note 1: This Register is used only when DDC is enabled: EN_DDC1 = 1 in Address 0x80 (Register 5-41). See Section 4.8.4.3, "Numerically Controlled Oscillator (NCO)" for the details of NCO.

2: NCO frequency = (NCO_TUNE<31:0>/ 2^{32}) x f_S, where f_S is the sampling clock frequency.

REGISTER 5-47: ADDRESS 0X86 - CH0 NCO PHASE OFFSET IN CW OR DDC MODE (LOWER BYTE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			CH0_N	NCO_PHASE<7:()>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0	3
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

CH0_NCO_PHASE<7:0>: Lower byte of CH0_NCO_PHASE<15:0>(1,2,3) bit 7-0

1111-1111 = 1.4° when CH0 NCO PHASE<15:0> = 0x00FF

. . .

0000-0000 = 0° when CH0_NCO_PHASE<15:0> = 0x0000 (Default)

- Note 1: This register is not used in the MCP37211. In the MCP37D11, this register has an effect when the following modes are used: - CW with DDC mode in octal-channel mode
 - Single and dual-channel mode with DDC.
 - 2:
 - CH0 is the 1st channel selected by CH_ORDER<23:0>. CH(n)_NCO_PHASE<15:0> = 2^{16} x Phase Offset Value/360. 3:

REGISTER 5-48: ADDRESS 0X87: CH0 NCO PHASE OFFSET IN CW OR DDC MODE (UPPER BYTE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			CH0_N	CO_PHASE<15	:8>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0	,
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 CH0_NCO_PHASE<15:8>: Upper byte of CH0_NCO_PHASE<15:0>⁽¹⁾ 1111-1111 = 359.995° when CH0_NCO_PHASE<15:0> = 0xFFFF ••• 0000-0000 = 0° when CH0_NCO_PHASE<15:0> = 0x0000 (Default)

Note 1: See Note 1 - Note 3 in Register 5-47.

REGISTER 5-49: ADDRESS 0X88 – CH1 NCO PHASE OFFSET IN CW OR DDC MODE (LOWER BYTE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			CH1_N	NCO_PHASE<7:()>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0	,
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 CH1_NCO_PHASE<7:0>: Lower byte of CH1_NCO_PHASE<15:0>⁽¹⁾ 1111-1111 = 1.4° when CH1_NCO_PHASE<15:0> = 0x00FF

0000-0000 = 0° when CH1_NCO_PHASE<15:0> = 0x0000 (Default)

Note 1: See Note 1 - Note 3 in Register 5-47. CH1 is the 2nd channel selected by CH_ORDER<23:0> bits.

REGISTER 5-50: ADDRESS 0X89 - CH1 NCO PHASE OFFSET IN CW OR DDC MODE (UPPER BYTE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			CH1_N	ICO_PHASE<15:	8>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0)'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 CH1_NCO_PHASE <15:8>: Upper byte of CH1_NCO_PHASE<15:0>⁽¹⁾ 1111-1111 = 359.995° when CH1_NCO_PHASE<15:0> = 0xFFFF ... 0000-0000 = 0° when CH1_NCO_PHASE<15:0> = 0x0000 (Default)

Note 1: See Note 1 - Note 3 in Register 5-47. CH1 is the 2nd channel selected by CH_ORDER<23:0> bits.

REGISTER 5-51: ADDRESS 0X8A – CH2 NCO PHASE OFFSET IN CW OR DDC MODE (LOWER BYTE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			CH2_I	NCO_PHASE<7:0	>		
bit 7							bit 0
Legend:							
R = Readable	bit	W = Writable bit		U = Unimplemen	ted bit, read as '0	,	
-n = Value at F	POR	'1' = Bit is set		'0' = Bit is cleare	d	x = Bit is unknown	

bit 7-0	CH2_NCO_PHASE<7:0>: Lower byte of CH2_NCO_PHASE<15:0>(1)
	1111-1111 = 1.4° when CH2_NCO_PHASE<15:0> = 0x00FF
	• • •
	0000-0000 = 0° when CH2_NCO_PHASE<15:0> = 0x0000 (Default)

Note 1: See Note 1 - Note 3 in Register 5-47. CH2 is the 3rd channel selected by CH_ORDER<23:0> bits.

REGISTER 5-52: ADDRESS 0X8B – CH2 NCO PHASE OFFSET IN CW OR DDC MODE (UPPER BYTE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			CH2_N	CO_PHASE<15:	8>		
bit 7							bit 0

Legend:				
R = Readable bit	W = Writable bit	U = Unimplemented bit, rea	ad as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown	

bit 7-0 CH2_NCO_PHASE <15:8>: Upper byte of CH2_NCO_PHASE<15:0>⁽¹⁾

1111-1111 = 359.995° when CH2_NCO_PHASE<15:0> = 0xFFFF

0000-0000 = 0° when CH2 NCO PHASE<15:0> = 0x0000 (Default)

Note 1: See Note 1 - Note 3 in Register 5-47. CH2 is the 3rd channel selected by CH_ORDER<23:0> bits.

REGISTER 5-53: ADDRESS 0X8C - CH3 NCO PHASE OFFSET IN CW OR DDC MODE (LOWER BYTE)

CH3_NCO_PHASE<7:0> bit 7	
bit 7	
	bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 CH3_NCO_PHASE<7:0>: Lower byte of CH3_NCO_PHASE<15:0>⁽¹⁾ 1111-1111 = 1.4° when CH3_NCO_PHASE<15:0> = 0x00FF ••• 0000-0000 = 0° when CH3_NCO_PHASE<15:0> = 0x0000 (Default)

Note 1: See Note 1 - Note 3 in Register 5-47. CH3 is the 4th channel selected by CH_ORDER<23:0> bits.

REGISTER 5-54: ADDRESS 0X8D – CH3 NCO PHASE OFFSET IN CW OR DDC MODE (UPPER BYTE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			CH3_N	CO_PHASE<15:	8>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0)'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 CH3_NCO_PHASE <15:8>: Upper byte of CH3_NCO_PHASE<15:0>⁽¹⁾ 1111-1111 = 359.995° when CH3_NCO_PHASE<15:0> = 0xFFFF

0000-0000 = 0° when CH3 NCO PHASE<15:0> = 0x0000 (Default)

Note 1: See Note 1 - Note 3 in Register 5-47. CH3 is the 4th channel selected by CH_ORDER<23:0> bits.

REGISTER 5-55: ADDRESS 0X8E – CH4 NCO PHASE OFFSET IN CW OR DDC MODE (LOWER BYTE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
CH4_NCO_PHASE<7:0>								
bit 7							bit 0	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0	,
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 CH4_NCO_PHASE<7:0>: Lower byte of CH4_NCO_PHASE<15:0>⁽¹⁾

1111-1111 = 1.4° when CH4_NCO_PHASE<15:0> = 0x00FF

0000-0000 = 0° when CH4_NCO_PHASE<15:0> = 0x0000 (Default)

Note 1: See Note 1 - Note 3 in Register 5-47. CH4 is the 5th channel selected by CH_ORDER<23:0> bits.

REGISTER 5-56: ADDRESS 0X8F – CH4 NCO PHASE OFFSET IN CW OR DDC MODE (UPPER BYTE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0		
	CH4_NCO_PHASE<15:8>								
bit 7							bit 0		

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0	,
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 CH4_NCO_PHASE <15:8>: Upper byte of CH4_NCO_PHASE<15:0>⁽¹⁾ 1111-1111 = 359.995° when CH4_NCO_PHASE<15:0> = 0xFFFF ... 0000-0000 = 0° when CH4_NCO_PHASE<15:0> = 0x0000 (Default)

Note 1: See Note 1 - Note 3 in Register 5-47. CH4 is the 5th channel selected by CH_ORDER<23:0> bits.

...

REGISTER 5-57: ADDRESS 0X90 – CH5 NCO PHASE OFFSET IN CW OR DDC MODE (LOWER BYTE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			CH5_	NCO_PHASE<7:0	>		
bit 7							bit (
Legend:							
R = Readable bi	it	W = Writable bit		U = Unimplement	ted bit, read as	ʻ0'	
-n = Value at PC	R	'1' = Bit is set		'0' = Bit is cleared	ł	x = Bit is unknown	

bit 7-0 CH5_NCO_PHASE<7:0>: Lower byte of CH5_NCO_PHASE<15:0>⁽¹⁾ 1111-1111 = 1.4° when CH5_NCO_PHASE<15:0> = 0x00FF

0000-0000 = 0° when CH5_NCO_PHASE<15:0> = 0x0000 (Default)

Note 1: See Note 1 - Note 3 in Register 5-47. CH5 is the 6th channel selected by CH_ORDER<23:0> bits.

REGISTER 5-58: ADDRESS 0X91 – CH5 NCO PHASE OFFSET IN CW OR DDC MODE (UPPER BYTE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			CH5_N	ICO_PHASE<15:	:8>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0	,
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 CH5_NCO_PHASE <15:8>: Upper byte of CH5_NCO_PHASE<15:0>⁽¹⁾

1111-1111 = 359.995° when CH5_NCO_PHASE<15:0> = 0xFFFF

0000-0000 = 0° when CH5_NCO_PHASE<15:0> = 0x0000 (Default)

Note 1: See Note 1 - Note 3 in Register 5-47. CH5 is the 6th channel selected by CH_ORDER<23:0> bits.

REGISTER 5-59: ADDRESS 0X92 – CH6 NCO PHASE OFFSET IN CW OR DDC MODE (LOWER BYTE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
CH6_NCO_PHASE<7:0>								
bit 7							bit 0	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0	,
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 CH6_NCO_PHASE<7:0>: Lower byte of CH6_NCO_PHASE<15:0>⁽¹⁾ 1111-1111 = 1.4° when CH6_NCO_PHASE<15:0> = 0x00FF ••• 0000-0000 = 0° when CH6_NCO_PHASE<15:0> = 0x0000 (Default)

Note 1: See Note 1 - Note 3 in Register 5-47. CH6 is the 7th channel selected by CH_ORDER<23:0> bits.

...

REGISTER 5-60: ADDRESS 0X93 – CH6 NCO PHASE OFFSET IN CW OR DDC MODE (UPPER BYTE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0		
	CH6_NCO_PHASE<15:8>								
bit 7							bit 0		

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0)'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 CH6_NCO_PHASE <15:8>: Upper byte of CH6_NCO_PHASE<15:0>⁽¹⁾ 1111-1111 = 359.995° when CH6_NCO_PHASE<15:0> = 0xFFFF

0000-0000 = 0° when CH6 NCO PHASE<15:0> = 0x0000 (Default)

Note 1: See Note 1 - Note 3 in Register 5-47. CH6 is the 7th channel selected by CH_ORDER<23:0> bits.

REGISTER 5-61: ADDRESS 0X94 – CH7 NCO PHASE OFFSET IN CW OR DDC MODE (LOWER BYTE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0			
	CH7_NCO_PHASE<7:0>									
bit 7							bit 0			

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0	3
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 CH7_NCO_PHASE<7:0>: Lower byte of CH7_NCO_PHASE<15:0>⁽¹⁾

1111-1111 = 1.4° when CH7_NCO_PHASE<15:0> = 0x00FF

0000-0000 = 0° when CH7_NCO_PHASE<15:0> = 0x0000 (Default)

Note 1: See Note 1 - Note 3 in Register 5-47. CH7 is the 8th channel selected by CH_ORDER<23:0> bits.

REGISTER 5-62: ADDRESS 0X95 – CH7 NCO PHASE OFFSET IN CW OR DDC MODE (UPPER BYTE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0			
	CH7_NCO_PHASE<15:8>									
bit 7							bit 0			

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0	,
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 CH7_NCO_PHASE <15:8>: Upper byte of CH7_NCO_PHASE<15:0>⁽¹⁾ 1111-1111 = 359.995° when CH7_NCO_PHASE<15:0> = 0xFFFF ••• 0000-0000 = 0° when CH7_NCO_PHASE<15:0> = 0x0000 (Default)

Note 1: See Note 1 - Note 3 in Register 5-47. CH7 is the 8th channel selected by CH_ORDER<23:0> bits.

...

REGISTER 5-63: ADDRESS 0X96 – CH0 DIGITAL GAIN

R/W-0	R/W-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-0	R/W-0
			СН	0_DIG_GAIN<7:0>			
bit 7							bit
Legend:							
R = Readat	ole bit	W = Writable bit		U = Unimplement	ted bit, read as	'0'	
-n = Value a	at POR	'1' = Bit is set		'0' = Bit is cleared	t	x = Bit is unknown	
bit 7-0	CH0 DIG G	AIN<7:0>: Digital g	nain setting	for channel 0 ^(1,2)			
	1111-1111		Jan				
	1111-1110	= -0.0625					
	1111-1101	= -0.09375					
	1111-1100	= -0.125					
	•••						
	1000-0011	= -3.90625					
	1000-0010						
	1000-0001	= -3.96875					
	1000-0000						
		= 3.96875 (MAX)					
	0111-1110						
	0111-1101						
	0111-1100	= 3.875					
	•••	4 075 (D - f					
	•••	= 1.875 (Default)					
	0000-0011	= 0.09375					
	0000-0011						
	0000-0010						
	0000-0001						
Nata di							

- **Note 1:** CH0 is the 1st channel selected by CH_ORDER<23:0>.
 - 2: Max = 0x7F(3.96875), Min = 0x80 (-4), Step size = 0x01 (0.03125). Bits from 0x81-0xFF are two's complementary of 0x00-0x80. Negative gain setting inverts output. See Addresses 0x7D - 0x7F (Registers 5-38 - 5-40) for channel selection.

REGISTER 5-64: ADDRESS 0X97 – CH1 DIGITAL GAIN

R/W-0	R/W-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-0	R/W-0
			СН	1_DIG_GAIN<7:0>			
bit 7							bit
Legend:							
R = Readable	bit	W = Writable bit		U = Unimplemente	d bit, read as	'0'	
-n = Value at I	POR	'1' = Bit is set		'0' = Bit is cleared		x = Bit is unknown	
bit 7-0	CH1 DIG G	AIN<7:0>: Digital g	ain setting	for channel 1 ^(1,2)			
	1111-1111		0				
	1111-1110	= -0.0625					
	1111-1101	= -0.09375					
	1111-1100	= -0.125					
	•••						
	1000-0011	= -3.90625					
	1000-0010	= -3.9375					
	1000-0001	= -3.96875					
	1000-0000	= -4					
	0111-1111	= 3.96875 (MAX)					
	0111-1110						
	0111-1101	= 3.90625					
	0111-1100	= 3.875					
	•••						
	0011-1100	= 1.875 (Default)					
	•••						
	0000-0011	= 0.09375					
	0000-0010	= 0.0625					
	0000-0001	= 0.03125					
	0000-0000	= 0.0					

- **Note 1:** CH1 is the 2nd channel selected by CH_ORDER<23:0>.
 - 2: See Note 2 in Register 5-63.

REGISTER 5-65: ADDRESS 0X98 – CH2 DIGITAL GAIN

R/W-0	R/W-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-0	R/W-0
			СН	2_DIG_GAIN<7:0>			
bit 7							bit
Legend:							
R = Readat	ole bit	W = Writable bit		U = Unimplemented	d bit, read as	'0'	
-n = Value a	at POR	'1' = Bit is set '0' = Bit is cleared				x = Bit is unknown	
bit 7-0	CH2_DIG_G	AIN<7:0>: Digital g	ain setting	for channel 2 ^(1,2)			
	1111-1111	= -0.03125					
	1111-1110						
	1111-1101						
	1111-1100	= -0.125					
	•••	0.00005					
	1000-0011						
	1000-0010						
	1000-0001						
		= 3.96875 (MAX)					
	0111-1110	· · ·					
	0111-1101						
	0111-1100						
	•••						
	0011-1100	= 1.875 (Default)					
	•••	· · ·					
	0000-0011	= 0.09375					
	0000-0010	= 0.0625					
	0000-0001	= 0.03125					
	0000-0000	= 0.0					
Note 1:	CH2 is the 3 rd c	hannel selected by C	H_ORDER	<23:0> bits.			
-							

2: See Note 2 in Register 5-63.

REGISTER 5-66: ADDRESS 0X99 – CH3 DIGITAL GAIN

R/W-0	R/W-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-0	R/W-0
			CH	3_DIG_GAIN<7:0>			
bit 7							bit
Legend:							
R = Readable	e bit	W = Writable bit		U = Unimplement	ed bit, read as '	0'	
-n = Value at I	POR	'1' = Bit is set		'0' = Bit is cleared	l	x = Bit is unknown	
bit 7-0	CH3 DIG G	AIN<7:0>: Digital g	ain setting	for channel 3 ^(1,2)			
	1111-1111		annootting				
	1111-1110						
	1111-1101						
	1111-1100						
	•••	0.1.20					
	1000-0011	= -3.90625					
	1000-0010						
	1000-0001						
	1000-0000						
		= 3.96875 (MAX)					
	0111-1110	· /					
	0111-1101						
	0111-1100	= 3.875					
	•••						
	0011-1100	= 1.875 (Default)					
	•••	· · · ·					
	0000-0011	= 0.09375					
	0000-0010						
	0000-0001						
	0000-0000	= 0 0					

- **Note 1:** CH3 is the 4th channel selected by CH_ORDER<23:0> bits.
 - 2: See Note 2 in Register 5-63.

REGISTER 5-67: ADDRESS 0X9A – CH4 DIGITAL GAIN

R/W-0	R/W-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-0	R/W-0
			CH	4_DIG_GAIN<7:0>			
bit 7							bit
Legend:							
R = Readal	ole bit	W = Writable bit		U = Unimplemente	d bit, read as	'0'	
-n = Value at POR		'1' = Bit is set '0' = Bit is cleared				x = Bit is unknown	
bit 7-0	CH4_DIG_G	GAIN<7:0>: Digital ga	ain setting	for channel 4 ^(1,2)			
	1111-1111						
	1111-1110						
	1111-1101						
	1111-1100	= -0.125					
	••• 1000-0011	- 2.00625					
	1000-0011						
	1000-0001						
	1000-0000						
		= 3.96875 (MAX)					
	0111-1110	· · ·					
	0111-1101	= 3.90625					
	0111-1100	= 3.875					
	•••						
	0011-1100	= 1.875 (Default)					
	•••						
	0000-0011	= 0.09375					
	0000-0010						
	0000-0001						
	0000-0000	= 0.0					
		hannel selected by Cl	H_ORDER«	<23:0>.			
0 .							

2: See Note 2 in Register 5-63.

REGISTER 5-68: ADDRESS 0X9B – CH5 DIGITAL GAIN

R/W-0	R/W-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-0	R/W-0		
			CH	5_DIG_GAIN<7:0>					
bit 7							bit		
Legend:									
R = Readable	bit	W = Writable bit		U = Unimplement	ed bit, read as '	'0'			
-n = Value at I	POR	'1' = Bit is set		'0' = Bit is cleared	I	x = Bit is unknown			
bit 7-0	CH5 DIG G	AIN<7:0>: Digital g	ain setting f	or channel 5(1,2)					
	1111-1111		an setting i	or charmer of					
	1111-1110								
	1111-1101								
	1111-1100 = -0.125								
	•••	0.120							
	1000-0011	= -3 90625							
	1000-0010								
	1000-0001								
	1000-0000								
		= 3.96875 (MAX)							
	0111-1110								
	0111-1101	= 3.90625							
	0111-1100	= 3.875							
	•••								
	0011-1100	= 1.875 (Default)							
	•••	· · · ·							
	0000-0011	= 0.09375							
	0000-0010	= 0.0625							
	0000-0001	= 0.03125							
	0000-0000	= 0 0							

- **Note 1:** CH5 is the 6th channel selected by CH_ORDER<23:0>.
 - 2: See Note 2 in Register 5-63.

REGISTER 5-69: ADDRESS 0X9C - CH6 DIGITAL GAIN

R/W-0	R/W-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-0	R/W-0
			CH	6_DIG_GAIN<7:0>			
bit 7							bit
Legend:							
R = Readal	ble bit	W = Writable bit		U = Unimplemente	ed bit, read as	'0'	
-n = Value at POR		'1' = Bit is set		'0' = Bit is cleared		x = Bit is unknown	
bit 7-0	CH6_DIG_G	GAIN<7:0>: Digital g	ain setting	for channel 6 ^(1,2)			
	1111-1111	= -0.03125					
	1111-1110	= -0.0625					
	1111-1101	= -0.09375					
	1111-1100	= -0.125					
	•••						
	1000-0011						
	1000-0010						
	1000-0001						
	1000-0000						
		= 3.96875 (MAX)					
	0111-1110						
	0111-1101						
	0111-1100	= 3.875					
	•••						
		= 1.875 (Default)					
	•••						
	0000-0011						
	0000-0010						
	0000-0001						
	0000-0000						
Note 1:		hannel selected by C	H_ORDER	<23:0>.			
.	See Note 2 in D	a minton E. CO					

- - **2:** See Note 2 in Register 5-63.

REGISTER 5-70: ADDRESS 0X9D – CH7 DIGITAL GAIN

R/W-0	R/W-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-0	R/W-0
			CH	H7_DIG_GAIN<7:0>			
bit 7							bit
Legend:							
R = Readable	e bit	W = Writable bit	t	U = Unimplemen	ted bit, read as	ʻ0'	
-n = Value at	POR	'1' = Bit is set		'0' = Bit is cleare	d	x = Bit is unknown	
bit 7-0		AIN<7:0>: Digital	nain setting	for channel 7(1,2)			
bit 7-0	1111-1111		Jain Setting				
	1111-1110						
	1111-1101						
	1111-1100						
	•••	0.125					
	1000-0011	= -3 90625					
	1000-0010						
	1000-0001						
	1000-0000						
		= 3.96875 (MAX)					
	0111-1110						
	0111-1101						
	0111-1100						
	•••						
	0011-1100	= 1.875 (Default)					
	•••	· · · ·					
	0000-0011	= 0.09375					
	0000-0010						
	0000-0001						
	0000-0000	= 0 0					

- **Note 1:** CH7 is the 8th channel selected by CH_ORDER<23:0>.
 - 2: See Note 2 in Register 5-63.

REGISTER 5-71: ADDRESS 0X9E – CH0 DIGITAL OFFSET

Legend:							
bit 7							bit 0
			CH0_D	IG_OFFSET<7:0)>		
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0

- 3			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '	D'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 CH0_DIG_OFFSET <7:0>: Digital offset setting bits for channel 0⁽¹⁾ 1111-1111 = 0xFF x DIG_OFFSET_WEIGHT<1:0> ... 0000-0001 = 0x01 x DIG_OFFSET_WEIGHT<1:0> 0000-0000 = 0 (Default)

Note 1: See Table 4-21 for the corresponding channel. Offset value is two's complement. This value is multiplied by DIG_OFFSET_-WEIGHT<1:0> in Address 0xA7 (Register 5-79).

REGISTER 5-72: ADDRESS 0X9F – CH1 DIGITAL OFFSET

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
CH1_DIG_OFFSET<7:0>								
bit 7							bit 0	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0	,
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 CH1_DIG_OFFSET <7:0>: Digital offset setting bits for channel 1⁽¹⁾ 1111-1111 = 0xFF x DIG_OFFSET_WEIGHT<1:0> ... 0000-0001 = 0x01 x DIG_OFFSET_WEIGHT<1:0> 0000-0000 = 0 (Default)

Note 1: See Note 1 in Register 5-71.

REGISTER 5-73: ADDRESS 0XA0 – CH2 DIGITAL OFFSET

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CH2_DIG_OFFSET<7:0>							
bit 7							bit 0

Legend:				
R = Readable bit		W = Writable bit	U = Unimplemented bit, re	ad as '0'
-n = Value a	at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown
bit 7-0	1111-111 ••• 0000-000	_OFFSET <7:0>: Digital offs 11 = 0xFF x DIG_OFFSET_V 11 = 0x01 x DIG_OFFSET_V 10 = 0 (Default)		

Note 1: See Note 1 in Register 5-71.

REGISTER 5-74: ADDRESS 0XA1 – CH3 DIGITAL OFFSET

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0		
			CH3_E	DIG_OFFSET<7:	0>				
bit 7									
L									

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0)'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 CH3_DIG_OFFSET <7:0>: Digital offset setting bits for channel 3⁽¹⁾ 1111-1111 = 0xFF x DIG_OFFSET_WEIGHT<1:0> ... 0000-0001 = 0x01 x DIG_OFFSET_WEIGHT<1:0> 0000-0000 = 0 (Default)

Note 1: See Note 1 in Register 5-71.

REGISTER 5-75: ADDRESS 0XA2 – CH4 DIGITAL OFFSET

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			CH4_E	DIG_OFFSET<7:	0>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0)'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 CH4_DIG_OFFSET <7:0>: Digital offset setting bits for channel 4⁽¹⁾
1111-1111 = 0xFF x DIG_OFFSET_WEIGHT<1:0>
...
0000-0001 = 0x01 x DIG_OFFSET_WEIGHT<1:0>
0000-0000 = 0 (Default)

Note 1: See Note 1 in Register 5-71.

REGISTER 5-76: ADDRESS 0XA3 – CH5 DIGITAL OFFSET

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CH5_DIG_OFFSET<7:0>							
bit 7							bit 0

Legend:				
R = Readable bit	ad as '0'			
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown	
	5_OFFSET <7:0>: Digital offs	et setting bits for channel 5 ⁽¹⁾		

1111-1111 = 0x01 x DIG_OFFSET_WEIGHT<1:0> •••• 0000-0001 = 0xFF x DIG_OFFSET_WEIGHT<1:0> 0000-0000 = 0 (Default)

Note 1: See Note 1 in Register 5-71.

REGISTER 5-77: ADDRESS 0XA4 – CH6 DIGITAL OFFSET

	1. 14			11 11.2			
Legend:							
bit 7							bit 0
			CH6_E	DIG_OFFSET<7:	0>		
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0)'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 CH6_DIG_OFFSET <7:0>: Digital offset setting bits for channel 6⁽¹⁾ 1111-1111 = 0xFF x DIG_OFFSET_WEIGHT<1:0> ... 0000-0001 = 0x01 x DIG_OFFSET_WEIGHT<1:0> 0000-0000 = 0 (Default)

Note 1: See Note 1 in Register 5-71.

REGISTER 5-78: ADDRESS 0XA5 – CH7 DIGITAL OFFSET

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0				
CH7_DIG_OFFSET<7:0>											
bit 7							bit 0				

Legend:				
R = Readable bit	W = Writable bit	U = Unimplemented bit, re-	ad as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown	

bit 7-0 CH7_DIG_OFFSET <7:0>: Digital offset setting bits for channel 7⁽¹⁾ 1111-1111 = 0xFF x DIG_OFFSET_WEIGHT<1:0> ... 0000-0001 = 0x01 x DIG_OFFSET_WEIGHT<1:0> 0000-0000 = 0 (Default)

Note 1: See Note 1 in Register 5-71.

REGISTER 5-79: ADDRESS 0XA7 – DIGITAL OFFSET WEIGHT CONTROL

R/W-0	R/W-1	R/W-0	R/W-0	R/W-0	R/W-1	R/W-1	R/W-1
	FCB<5:3> DIG_OFFSET_WEIGHT<1:0>			FCB<2:0>			
bit 7							bit 0

R = Readable bit W = Writable bit U = Unimpl	
	emented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is c	cleared x = Bit is unknown

bit 7-5 **FCB<5:3>:** Factory-Controlled Bits. This is not for the user. Do not change default settings.

bit 4-3 DIG_OFFSET_WEIGHT<1:0>: Control the weight of the digital offset settings⁽¹⁾

- 11 = 2 LSb x Digital Gain
- 10 = LSb x Digital Gain
- 01 = LSb/2 x Digital Gain
- 00 = LSb/4 x Digital Gain, (Default)

bit 2-0 FCB<2:0>: Factory-Controlled Bits. This is not for the user. Do not change default settings.

Note 1: This bit setting is used for the digital offset setting registers in Addresses 0x9E - 0xA7 (Registers 5-71 - 5-79).

REGISTER 5-80: ADDRESS 0XC0 – CALIBRATION STATUS INDICATION

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
ADC_CAL_STAT				FCB<6:0>			
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read a	is '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7

ADC_CAL_STAT: Power-up auto-calibration status indication flag bit

1 = Device power-up calibration is completed

0 = Device power-up calibration is not completed

bit 6-0

REGISTER 5-81: ADDRESS 0XD1 – PLL CALIBRATION STATUS AND PLL DRIFT STATUS INDICATION

FCB<6:0>: Factory-Controlled Bits. These bits are read only, and have no meaning for the user.

R-x	R-x	R-x	R-x	R-x	R-x	R-x	R-x
FCB•	<4:3>	PLL_CAL_STAT	FCB<2:1>		PLL_VCOL_STAT	PLL_VCOH_STAT	FCB<0>
bit 7							bit 0

Legend:				
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	d as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown	

bit 7-6 **FCB<4:3>:** Factory-Controlled Bits. These bits are read only, and have no meaning for the user.

- bit 5 PLL_CAL_STAT: PLL auto-calibration status indication flag bit⁽¹⁾
 - 1 = Complete: PLL auto-calibration is completed
 - 0 = Incomplete: PLL auto-calibration is not completed
- bit 4-3 **FCB<2:1>:** Factory-Controlled Bits. These bits are read only, and have no meaning for the user.

bit 2 PLL VCOL STAT: PLL drift status indication bit

- 1 = PLL drifts out of lock with low VCO frequency
- 0 = PLL operates as normal

bit 1 PLL_VCOH_STAT: PLL drift status indication bit

- 1 = PLL drifts out of lock with high VCO frequency
- 0 = PLL operates as normal
- bit 0 FCB<0>: Factory-Controlled Bit. This bit is readable, but has no meaning for the user.
- Note 1: See PLL_CAL_TRIG bit setting in Address 0x6B (Register 5-27).

REGISTER 5-82: ADDRESS 0X15C – CHIP ID (LOWER BYTE)

R-x	R-x	R-x	R-x	R-x	R-x	R-x	R-x
			C	CHIP_ID<7:0>			
bit 7							bit 0
Legend:							
R = Readable bit		W = Writable bit		U = Unimplemen	ited bit, read as '0'		

K – Keauable bit		0 - Onimplemented bit, read as 0	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 CHIP_ID<7:0>: Device identification number. Lower byte of the CHIP ID<15:0>⁽¹⁾

Note 1: Read-only register. Preprogrammed at the factory for internal use. Example: MCP37211-200: '0000 1000 0011 0000'

MCP37D11-200: '0000 1010 0011 0000'

REGISTER 5-83: ADDRESS 0X15D – CHIP ID (UPPER BYTE)

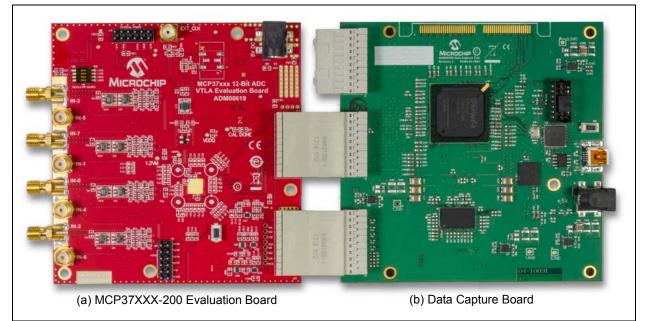
R-x	R-x	R-x	R-x	R-x	R-x	R-x	R-x
				CHIP_ID<15:8>			
bit 7							bit 0
Legend:							
R = Readable	bit	W = Writable bit	t	U = Unimplement	ed bit, read as '0		
-n = Value at F	POR	'1' = Bit is set		'0' = Bit is cleared		x = Bit is unknown	

bit 7-0 CHIP_ID<15:8>: Device identification number. Lower byte of the CHIP ID<15:0>⁽¹⁾

Note 1: See Note 1 in Register 5-82.

6.0 DEVELOPMENT SUPPORT

Microchip offers a high-speed ADC evaluation platform which can be used to evaluate Microchip's high-speed ADC products. The platform consists of an MCP37XXX evaluation board, an FPGA-based data capture card board, and PC-based Graphical User Interface (GUI) software for ADC configuration and evaluation. Figure 6-1 and Figure 6-2 show this evaluation tool. This evaluation platform allows users to quickly evaluate the ADC's performance for their specific application requirements. More information is available at http://www.microchip.com.







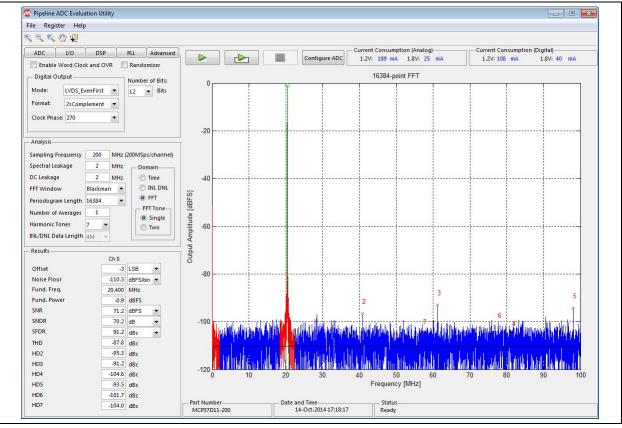


FIGURE 6-2: PC-Based Graphical User Interface Software.

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NOTES:

7.0 TERMINOLOGY

Analog Input Bandwidth (Full-Power Bandwidth)

The analog input frequency at which the spectral power of the fundamental frequency (as determined by FFT analysis) is reduced by 3 dB.

Aperture Delay or Sampling Delay

This is the time delay between the rising edge of the input sampling clock and the actual time at which the sampling occurs.

Aperture Uncertainty

The sample-to-sample variation in aperture delay.

Aperture Delay Jitter

The variation in the aperture delay time from conversion to conversion. This random variation will result in noise when sampling an AC input. The signal-to-noise ratio due to the jitter alone will be:

EQUATION 7-1:

 $SNR_{JITTER} = -20log(2\pi \times f_{IN} \times t_{JITTER})$

Calibration Algorithms

This device utilizes two patented analog and digital calibration algorithms, Harmonic Distortion Correction (HDC) and DAC Noise Cancellation (DNC), to improve the ADC performance. The algorithms compensate various sources of linear impairments such as capacitance mismatch, charge injection error and finite gain of operational amplifiers. These algorithms execute in both power-up sequence (foreground) and background mode:

- Power-Up Calibration: The calibration is conducted within the first 2²⁷ clock cycles after power-up. The user needs to wait this Power-Up Calibration period after the device is powered-up for an accurate ADC performance.
- Background Calibration: This calibration is conducted in the background while the ADC performs conversions. The update rate is about every 2³⁰ clock cycles.

Channel Crosstalk

This is a measure of the internal coupling of a signal from an adjacent channel into the channel of interest in the multi-channel mode. It is measured by applying a full-scale input signal in the adjacent channel. Crosstalk is the ratio of the power of the coupling signal (as measured at the output of the channel of interest) to the power of the signal applied at the adjacent channel input. It is typically expressed in dBc.

Pipeline Delay (LATENCY)

LATENCY is the number of clock cycles between the initiation of conversion and when that data is presented to the output driver stage. Data for any given sample is available after the pipeline delay plus the output delay after that sample is taken. New data is available at every clock cycle, but the data lags the conversion by the pipeline delay plus the output delay. Latency is increased if digital signal post-processing is used.

Clock Pulse Width and Duty Cycle

The clock duty cycle is the ratio of the time the clock signal remains at a logic high (clock pulse width) to one clock period. Duty cycle is typically expressed as a percentage. A perfect differential sine-wave clock results in a 50% duty cycle.

Differential Nonlinearity (DNL, No Missing Codes)

An ideal ADC exhibits code transitions that are exactly 1 LSb apart. DNL is the deviation from this ideal value. No missing codes to 12-bit resolution indicates that all 4096 codes must be present over all the operating conditions.

Integral Nonlinearity (INL)

INL is the maximum deviation of each individual code from an ideal straight line drawn from negative full scale through positive full scale.

Signal-to-Noise Ratio (SNR)

SNR is the ratio of the power of the fundamental (P_S) to the noise floor power (P_N), below the Nyquist frequency and excluding the power at DC and the first nine harmonics.

EQUATION 7-2:

$$SNR = 10 log \left(\frac{P_S}{P_N} \right)$$

SNR is either given in units of dBc (dB to carrier) when the absolute power of the fundamental is used as the reference, or dBFS (dB to full-scale) when the power of the fundamental is extrapolated to the converter full-scale range.

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Signal-to-Noise and Distortion (SINAD)

SINAD is the ratio of the power of the fundamental (P_S) to the power of all the other spectral components including noise (P_N) and distortion (P_D) below the Nyquist frequency, but excluding DC:

EQUATION 7-3:

$$SINAD = 10log\left(\frac{P_S}{P_D + P_N}\right)$$
$$= -10log\left[10^{\frac{SNR}{10}} - 10^{\frac{THD}{10}}\right]$$

SINAD is either given in units of dBc (dB to carrier) when the absolute power of the fundamental is used as the reference, or dBFS (dB to full-scale) when the power of the fundamental is extrapolated to the converter full-scale range.

Effective Number of Bits (ENOB)

The effective number of bits for a sine wave input at a given input frequency can be calculated directly from its measured SINAD using the following formula:

EQUATION 7-4:

$$ENOB = \frac{SINAD - 1.76}{6.02}$$

Gain Error

Gain error is the deviation of the ADC's actual input full-scale range from its ideal value. The gain error is given as a percentage of the ideal input full-scale range.

Gain error is usually expressed in LSb or as a percentage of full-scale range (%FSR).

Gain-Error Drift

Gain-error drift is the variation in gain-error due to a change in ambient temperature, typically expressed in ppm/°C.

Offset Error

The major carry transition should occur for an analog value of 50% LSb below A_{IN} + = A_{IN} -. Offset error is defined as the deviation of the actual transition from that point.

Temperature Drift

The temperature drift for offset error and gain error specifies the maximum change from the initial (+25°C) value to the value across the T_{MIN} to T_{MAX} range.

Maximum Conversion Rate

The maximum clock rate at which parametric testing is performed.

Minimum Conversion Rate

The minimum clock rate at which parametric testing is performed.

Spurious-Free Dynamic Range (SFDR)

SFDR is the ratio of the power of the fundamental to the highest other spectral component (either spur or harmonic). SFDR is typically given in units of dBc (dB to carrier) or dBFS.

Total Harmonic Distortion (THD)

THD is the ratio of the power of the fundamental (P_S) to the summed power of the first 13 harmonics (P_D) .

EQUATION 7-5:

$$THD = 10 \log\left(\frac{P_S}{P_D}\right)$$

THD is typically given in units of dBc (dB to carrier). THD is also shown by:

EQUATION 7-6:

$$THD = -20\log \frac{\sqrt{V_2^2 + V_3^2 + V_4^2 + \dots + V_n^2}}{V_1^2}$$

Where:

$$V_1$$
 = RMS amplitude of the
fundamental frequency
 V_1 through V_n = Amplitudes of the second
through nth harmonics

Two-Tone Intermodulation Distortion (Two-Tone IMD, IMD3)

Two-tone IMD is the ratio of the power of the fundamental (at frequencies f_{IN1} and f_{IN2}) to the power of the worst spectral component at either frequency $2f_{IN1} - f_{IN2}$ or $2f_{IN2} - f_{IN1}$. Two-tone IMD is a function of the input amplitudes and frequencies (f_{IN1} and f_{IN2}). It is either given in units of dBc (dB to carrier) when the absolute power of the fundamental is used as the reference, or dBFS (dB to full-scale) when the power of the fundamental is extrapolated to the ADC full-scale range.

Common-Mode Rejection Ratio (CMRR)

Common-mode rejection is the ability of a device to reject a signal that is common to both sides of a differential input pair. The common-mode signal can be an AC or DC signal or a combination of the two. CMRR is measured using the ratio of the differential signal gain to the common-mode signal gain and expressed in dB with the following equation:

EQUATION 7-7:

$$CMRR = 20log\left(\frac{A_{DIFF}}{A_{CM}}\right)$$

Where:

 $A_{DIFF} = \Delta Output Code/\Delta Differential Voltage$

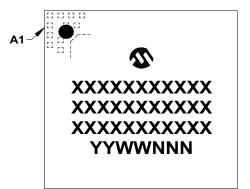
 A_{DIFF} = $\Delta Output Code/\Delta Common Mode Voltage$

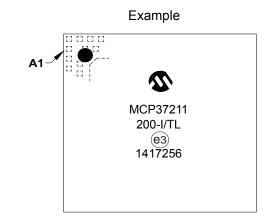
NOTES:

8.0 PACKAGING INFORMATION

8.1 Package Marking Information

124-Lead VTLA (9x9x0.9 mm)

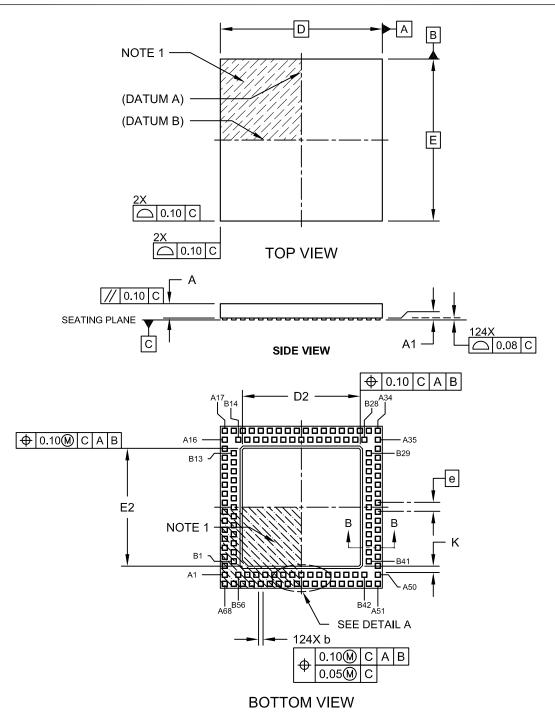




Legend:	XXX Y YY WW NNN @3 *	Customer-specific information Year code (last digit of calendar year) Year code (last 2 digits of calendar year) Week code (week of January 1 is week '01') Alphanumeric traceability code Pb-free JEDEC [®] designator for Matte Tin (Sn) This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.
I	be carried	nt the full Microchip part number cannot be marked on one line, it will d over to the next line, thus limiting the number of available s for customer-specific information.

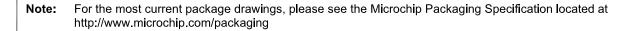
124-Terminal Very Thin Leadless Array Package (TL) – 9x9x0.9 mm Body [VTLA]

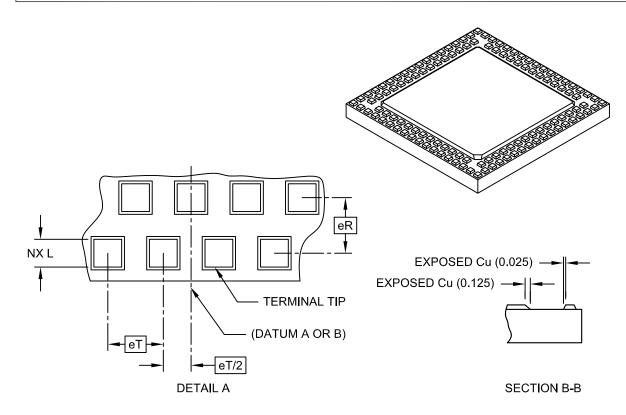
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-193A Sheet 1 of 2

124-Terminal Very Thin Leadless Array Package (TL) – 9x9x0.9 mm Body [VTLA]





Units		MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX
Number of Pins	Ν	124		
Pitch	еT	0.50 BSC		
Pitch (Inner to outer terminal ring)	eR	0.50 BSC		
Overall Height	Α	0.80	0.85	0.90
Standoff	A1	0.00	-	0.05
Overall Width E		9.00 BSC		
Exposed Pad Width	E2	6.40	6.55	6.70
Overall Length	D	9.00 BSC		
Exposed Pad Length	D2	6.40	6.55	6.70
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.20	0.25	0.30
Contact-to-Exposed Pad		0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

2. Package is saw singulated.

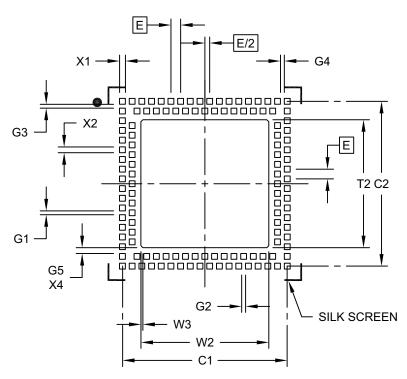
- 3. Dimensioning and tolerancing per ASME Y14.5M.
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-193A Sheet 2 of 2

124-Very Thin Leadless Array Package (TL) – 9x9x0.9 mm Body [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	Units		MILLIMETER	S
Dimension	Limits	MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Pad Clearance	G1	0.20		
Pad Clearance	G2	0.20		
Pad Clearance	G3	0.20		
Pad Clearance	G4	0.20		
Contact to Center Pad Clearance (X4)	G5	0.30		
Optional Center Pad Width	T2			6.60
Optional Center Pad Length	W2			6.60
Optional Center Pad Chamfer (X4)	W3		0.10	
Contact Pad Spacing	C1		8.50	
Contact Pad Spacing	C2		8.50	
Contact Pad Width (X124)	X1			0.30
Contact Pad Length (X124)	X2			0.30

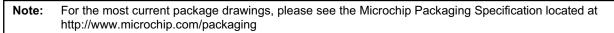
Notes:

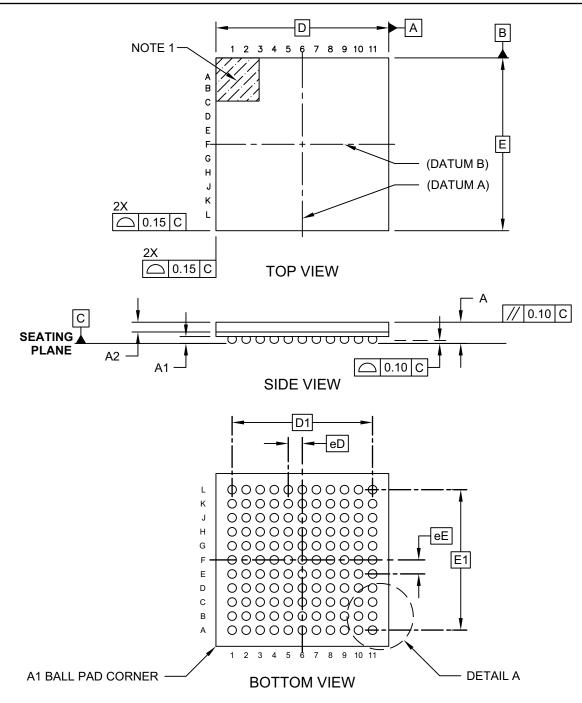
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2193A

121-Ball Thin Fine Pitch Ball Grid Array (TE) - 8x8 mm Body [TFBGA] System In Package

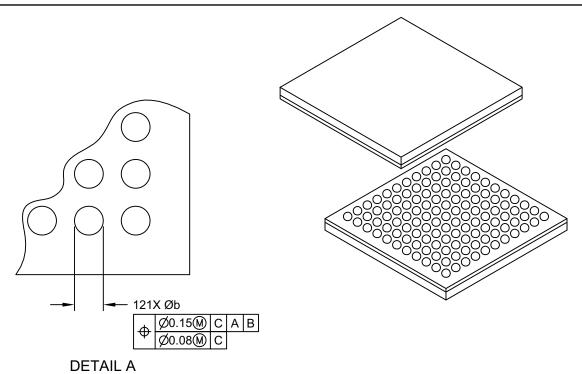




Microchip Technology Drawing C04-212A Sheet 1 of 2

121-Ball Thin Fine Pitch Ball Grid Array (TE) - 8x8 mm Body [TFBGA] System In Package

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	Ν	ILLIMETER:	S
Dimens	sion Limits	MIN	NOM	MAX
Number of Terminals	N	121		
Pitch	eE	0.65 BSC		
Pitch eD 0.65 BS		0.65 BSC		
Overall Height	Α	-	-	1.08
Standoff	A1	0.21	0.32	-
Cap Thickness	A2	0.40	0.45	0.50
Overall Width	E	8.00 BSC		
Overall Pitch	E1	6.50 BSC		
Overall Length	D	8.00 BSC		
Overall Pitch	D1	6.50 BSC		
Terminal Diameter	b	.035	0.40	0.45

Notes:

1. Terminal A1 visual index feature may vary, but must be located within the hatched area.

2. Dimensioning and tolerancing per ASME Y14.5M

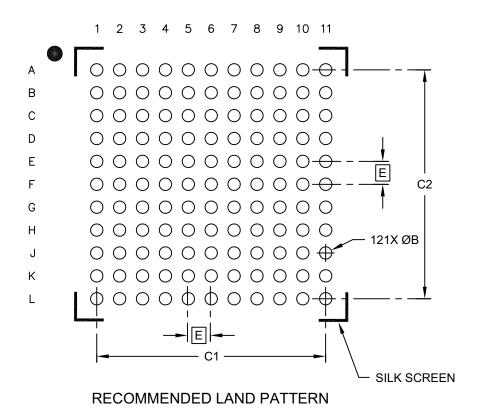
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-212A Sheet 2 of 2

121-Ball Thin Fine Pitch Ball Grid Array (TE) - 8x8 mm Body [TFBGA] System In Package

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	MILLIMETERS			
Dimension Limits		MIN	NOM	MAX
Contact Pitch			0.65 BSC	
Contact Pad Spacing	C1		6.50	
Contact Pad Spacing	C2		6.50	
Contact Pad Diameter (X121)	В		0.35	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2212B-TE

NOTES:

APPENDIX A: REVISION HISTORY

Revision C (August 2016)

The following is the list of modifications:

- Updated availability of TFBGA package.
- Added Figure 2-7, Figure 2-8 and Figure 2-9.
- Added Section 4.15, AutoSync Mode: Synchronizing Multiple ADCs at the Same Clock using Master and Slave Configuration.

Revision B (July 2015)

- Updated the Features list.
- Updated the Functional Block Diagram.
- Updated the Description section.
- Updated and added notes in Tables 1-1 and 1-2.
- Updated values and notes in Tables 2-1 and 2-2.
- Updated value in Figure 2-1.
- Updated note in Section 3.0 "Typical Performance Curves".
- Updated text title in Figures 3-26 and 3-29.
- Updated text in Section 4.0 "Theory of Operation".
- Updated text in Section 4.5.1 "Analog Input Driving Circuit".
- Added new column to Table 4-2.
- Added Section 4.5.2.1 "SENSE Selection Vs. SNR/SFDR Performance" and Section 4.5.3.1 "Decoupling Circuits for REF1 and REF0 Pins".
- Replaced text in Section 4.5.3.1 "Decoupling Circuits for REF1 and REF0 Pins".
- Updated values in Figure 4-7.
- Added note after Figure 4-7.
- Replaced the entire Section 4.7 "ADC Clock Selection".
- Updated text in Section 4.8.1 "Fractional Delay Recovery for Dual- and Octal-Channel Modes".
- Updated Figure 4-11.
- Changed parameters and updated/added notes in Tables 4-5, 4-6, 4-9, 4-10, 4-12, 4-13 and 4-14.
- Changed value in Equation 4-6.
- Deleted Note in Section 4.8.3 "Decimation Filters".
- Added Section 4.8.3.1 "Output Data Rate and Clock Phase Control When Decimation is Used".
- Changed parameter in Table 4-15 and bit names in Tables 4-17, 4-19, 4-20.
- Replaced and added text and reorganized structure in Section 4.8.4 "Digital Down-Conversion (MCP37D11-200 only)".

- Replaced text in Section 4.8.4.3 "Numerically Controlled Oscillator (NCO)".
- Updated values in Section 4.8.4.5 "NCO for fS/8 and fS/(8xDER)".
- Updated parameters and notes in Tables 4-16, 4-17, 4-18 and 4-19.
- Reorganized and added text to Section 4.11 "Output Data format" and Section 4.12 "Digital Output".
- Updated Figure 4-25.
- · Updated Section 5.2 "Configuration Registers".
- Updated Table 5-3.
- Updated Registers 5-1 to 5-3, 5-7, 5-8, 5-10, 5-11, 5-13, 5-22, 5-24, 5-25, 5-27, 5-28, 5-34, 5-35, 5-36, 5-37, 5-42, 5-43 to 5-46, 5-47, 5-63, 5-79 and 5-80.
- Deleted "Power Supply Rejection Ration" section from Section 7.0 "Terminology".
- Updated Product Identification System.
- · Minor typographical corrections.

Revision A (October 2014)

• Original release of this document.

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>	<u>іхі(1) -ххх х /хх</u>	Examples:
	e and Reel Sample Temperature Package Dption Rate Range	a) MCP37211-200I/TL: 200 Msps, Industrial temperature, 124LD VTLA Package
Device:	MCP37211-200: 12-Bit Low-Power ADC with 8-Channel MUX	b) MCP37211T-200I/TL 200 Msps, Tape and Reel Industrial temperature 124LD VTLA Package
	MCP37D11-200: 12-Bit Low-Power ADC with 8-Channel MUX, Digital Down-Converter and CW Beamforming	c) MCP37211-200I/TE 200 Msps, Industrial temperature, 121LD TFBGA Package
Tape and Reel Option:	Blank = Standard packaging (tube or tray) T = Tape and Reel ⁽¹⁾	a) MCP37D11-200I/TL: 200 Msps, Industrial temperature, 124LD VTLA Package
Sample Rate:	200 = 200 Msps	b) MCP37D11T-200I/TL 200 Msps, Tape and Reel Industrial temperature 124LD VTLA Package
Temperature Range:	I = -40° C to $+85^{\circ}$ C (Industrial)	c) MCP37D11-200I/TE: 200 Msps, Industrial temperature, 121LD TFBGA Package
Package:	TL = Terminal Very Thin Leadless Array Package - 9x9x0.9 mm Body (VTLA), 124-Lead	Note 1: Tape and Reel identifier appears only in the
	TE = Ball Plastic Thin Profile Fine Pitch Ball Grid Array - 8x8x1.08 mm Body (TFBGA), 121-Lead	catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.

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- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
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